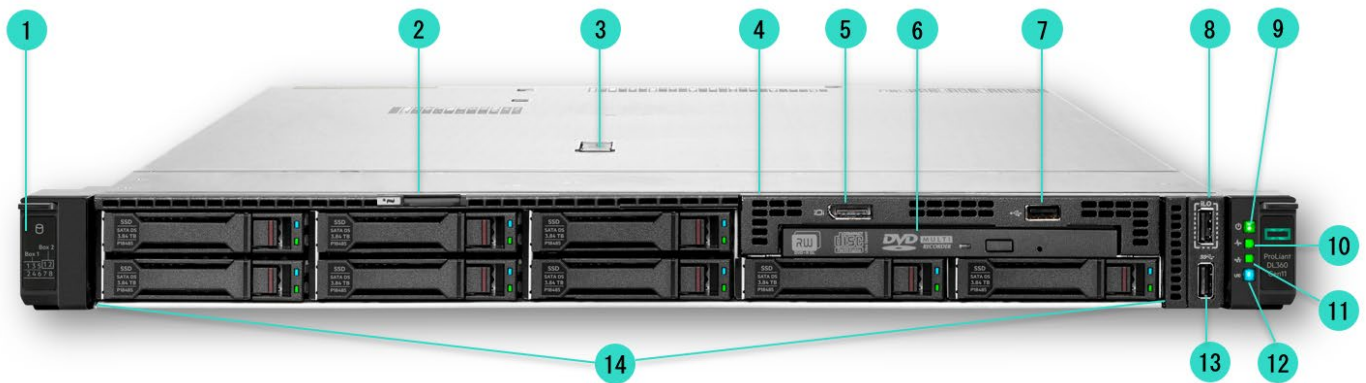


Overview

HPE ProLiant DL360 Gen11

Do you need to efficiently expand or refresh your IT infrastructure to propel the business? Adaptable for diverse workloads and environments, the compact 1U HPE ProLiant DL360 Gen11 delivers enhanced performance with the right balance of expandability and density. Designed for supreme versatility and resiliency while backed by a comprehensive warranty, the HPE ProLiant DL360 Gen11 is ideal for IT infrastructure, either physical, virtual, or containerized.

The HPE ProLiant DL360 Gen11 supports the 4th & 5th Generation Intel® Xeon® Scalable Processors with up to 64 cores, plus 5600 MT/s HPE DDR5 Smart Memory up to 4.0 TB per socket. Introducing PCIe Gen5 and Intel® Software Guard Extensions (SGX) support on the dual-socket segment, the HPE ProLiant DL360 Gen11 complements Gen10 Plus reach by delivering premium compute, memory, networking communication, discrete graphic, I/O, and security capabilities for customers focused on performance at any cost. DL360 Gen11 server is an excellent choice of daily business and workloads in General Compute, Database Management, Virtual Desktop Infrastructure, Content Delivery Network, EDA, CAD, Edge Acceleration and Intelligent Video Analytics.



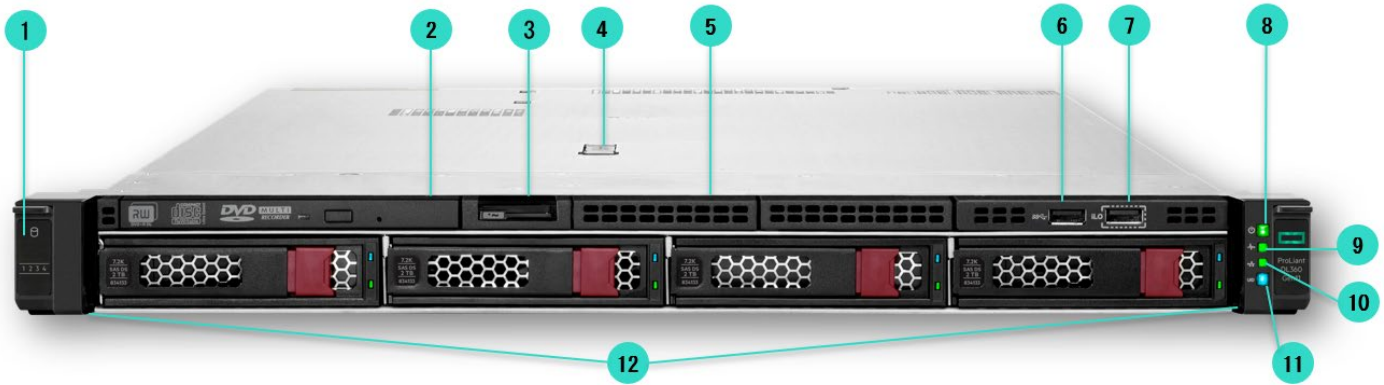
8 SFF Front View – 8 SFF + optional Universal Media Bay, optical drive, Display Port, USB2.0 and SAS drives shown

- | | |
|--|---|
| <ol style="list-style-type: none"> 1. Drive support label 2. Serial number/iLO information pull tab 3. Quick removal access panel 4. Universal Media Bay (optional): <ul style="list-style-type: none"> • Option: Optical drive bay + Display port & USB 2.0 port kit (shown) • Option : 2SFF 24G x4 NVMe/SAS (TriMode) U.3 BC Cage 5. Display Port (optional – shown) 6. Optical drive (optional – shown) 7. USB2.0 port (optional) | <ol style="list-style-type: none"> 8. iLO Service port 9. Power On/Standby button and system power LED 10. Health LED 11. NIC status LED 12. Unit ID button/LED 13. USB 3.2 Gen1 port 14. Drive bays; optional backplanes: <ul style="list-style-type: none"> • Option: 8 SFF 24G x1 NVMe/SAS (TriMode) U.3 BC • Option: 8 SFF 24G x4 NVMe/SAS (TriMode) U.3 BC |
|--|---|

Notes: Optional- Systems Insight Display (SID) module is available for 8SFF CTO Server, and will be installed at the left-hand side of iLO Service port and USB 3.2 Gen1 port.



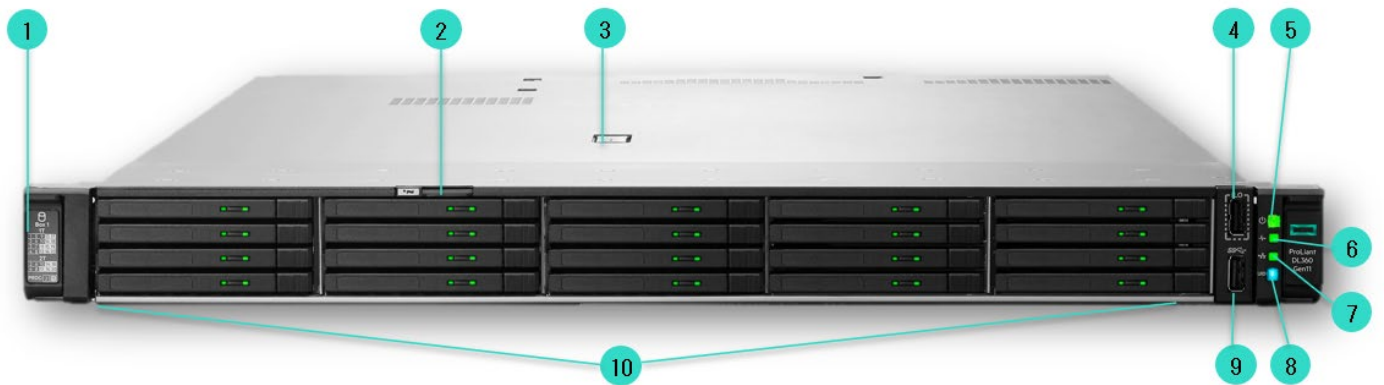
Overview



4 LFF Front View – 4 LFF + optional Optical drive, Display Port, USB2.0 and SAS drives shown

- | | |
|---|---|
| 1. Drive support label | 7. iLO Service Port |
| 2. Optical drive (optional – shown) | 8. Power On/Standby button and system power LED |
| 3. Serial number/iLO information pull tab | 9. Health LED |
| 4. Quick removal access panel | 10. NIC status LED |
| 5. Option: Display port & USB 2.0 port bundle Kit (blank shown) | 11. Unit ID button/LED |
| 6. USB 3.2 Gen1 port | 12. SAS/SATA drive bays (12G x1 SAS LP BP embedded) |

Notes: The optional Systems Insight Display (SID) module is not available in 4LFF CTO Server.



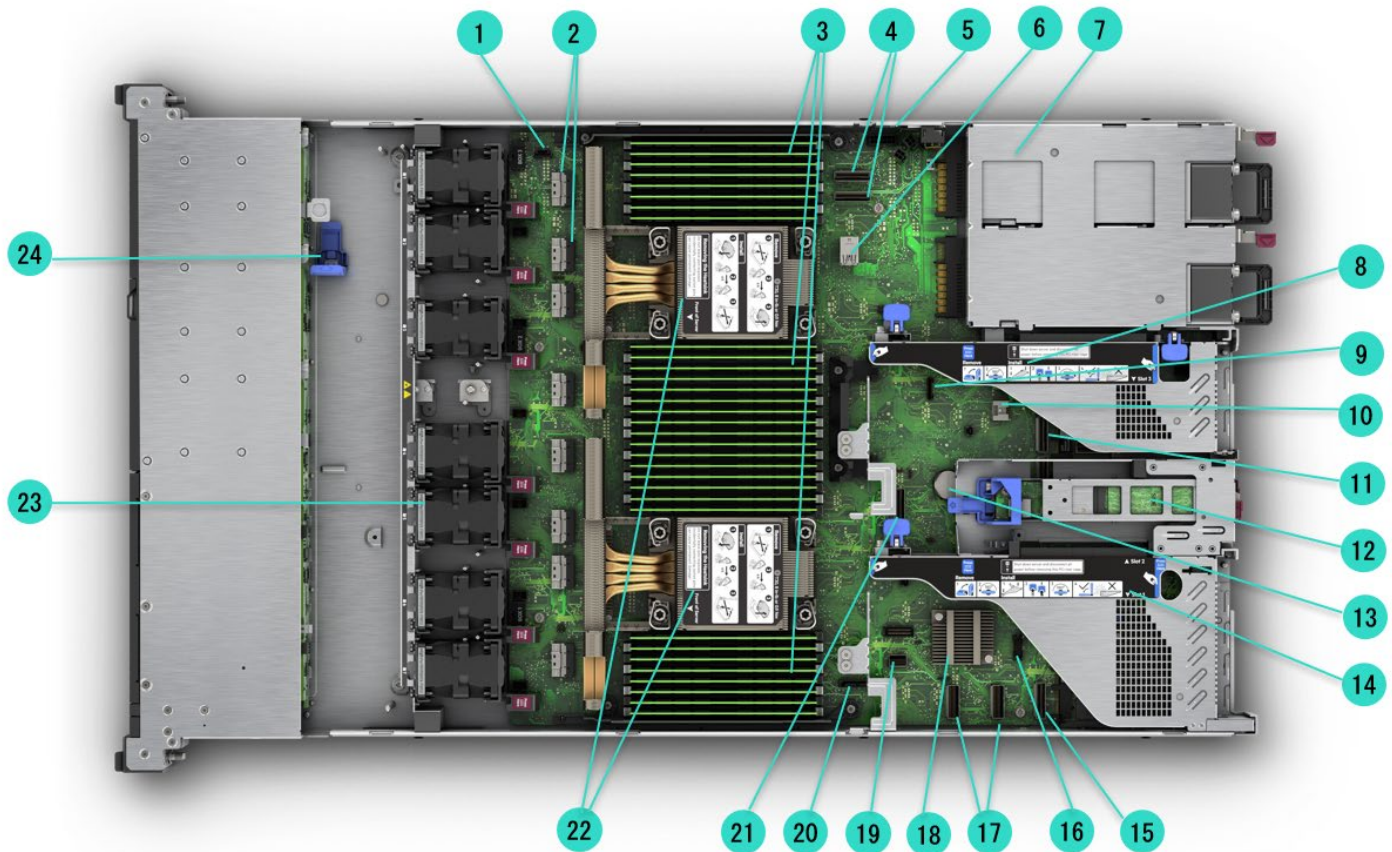
20 EDSFF Front View – 20 E3.s 1T NVMe drives shown

- | | |
|---|--|
| 1. Drive support label | 6. Health LED |
| 2. Serial number/iLO information pull tab | 7. NIC status LED |
| 3. Quick removal access panel | 8. Unit ID button/LED |
| 4. iLO Service Port | 9. USB 3.2 Gen1 port |
| 5. Power On/Standby button and system power LED | 10. EDSFF drive bays (32G x4 NVMe BP embedded) |

Notes: The optional Systems Insight Display (SID) module is not available in 20EDSFF CTO Server.



Overview

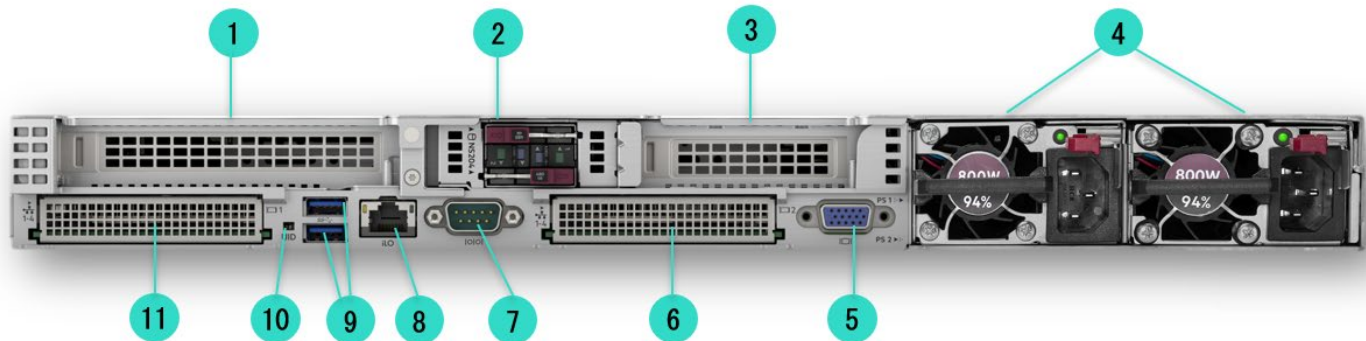


Internal View - Standard for all DL360 Gen11

- | | |
|---|---|
| 1. Liquid Cooling Module connector | 13. System Battery |
| 2. x8 SlimSAS ports (1A to 4A, 1B to 4B) | 14. Primary (CPU1) Riser PCIe 5.0 <ul style="list-style-type: none"> • 1x 16 FH and 1x16 LP slots |
| 3. DDR5 DIMM Slots (fully populated 32 DIMMs shown) | 15. OCP Slot port |
| 4. Socket 2 MCIO ports (1 & 2) | 16. Front Display Port and USB 2.0 connector (optional feature) |
| 5. Backplane Power connector | 17. LP SlimSAS ports (1 & 2) |
| 6. Internal USB port (top USB 3.2 Gen1 and bottom USB 2.0) | 18. Chipset |
| 7. Redundant Power Supply (1 & 2 as shown) | 19. Front I/O and USB 3.2 Gen1 connector |
| 8. Secondary (CPU 2) Riser PCIe 5.0 <ul style="list-style-type: none"> • Option: Low Profile x16 • Option: Full height x16 (lose Slot 2 on Primary Riser) | 20. SATA Optical port |
| 9. SID connector (optional feature, 8SFF only) | 21. Socket 1 MCIO connector |
| 10. Energy Pack connector | 22. CPU 1 (bottom) and CPU 2 (top) (shown with High Performance Heatsink) |
| 11. OCP Slot port | 23. Hot plug (dual rotor) High Performance Fan Kit (7 fans) <ul style="list-style-type: none"> • Option: Closed-loop Liquid Cooling Heat Sink Fan FIO Bundle Kit |
| 12. HPE NS204i-u NVMe Hot Plug Boot Optimized Storage Device (optional – shown) | 24. HPE Hybrid Capacitor or HPE Storage Battery holder |



Overview



Rear View - Standard for all DL360 Gen11

- | | |
|---|---|
| 1. Slot 1 x16 PCIe 5.0 – Full Height | 6. OCP 3.0 Slot 2: x16* PCIe 5.0 ^{1,2} (Requires 2 nd Processor) Notes: *x8 for 20EDSFF CTO Server (requires 2 nd Processor) |
| 2. Slot 2 x16 PCIe 5.0 – Low Profile* Notes: *Shown with optional hot-plug NS204i-u Boot Device (cabled, PCIe connection is not required) | 7. Serial port (optional - shown) |
| 3. Option: Slot 3 x16 PCIe 5.0 (Requires 2 nd processor) | 8. iLO Management Port |
| • Low Profile and Full Height options | 9. USB 3.2 Gen1 Ports |
| 4. Redundant Power Supply (1 & 2 as shown) | 10. Uint ID Indicator LED |
| 5. Video (VGA) port | 11. OCP 3.0 Slot 1: x16* PCIe 5.0 ² Notes: *x8 for 20EDSFF CTO Server |

Notes:

- ¹ Supports various NICs, up to 200GbE
- ² Or supports each slot with x8 PCIe 5.0 under one processor, with the selection of “P51911-B21, CPU1 to the “OCP2 x8 Enablement Kit”.

What's New

- All new DL360 Gen11 server
- New 4th Generation Intel® Xeon® Scalable Processors (Extreme Core Count die/ XCC die; Medium Core Count/ MCC; High Bandwidth Memory/ HBM)
- New PCIe 5.0 support
- New HPE DDR5 SmartMemory – Registered (RDIMM), 4800MT/s
- New HPE Gen11 Storage Controllers
- New HPE NS204i-u Gen11 NVMe Hot Plug Boot Optimized Storage Device
- New HPE Storage SSD and HDD support
- New HPE iLO6 support
- Nvidia A2 and L4 GPU support
- New Intel® Virtual RAID on CPU (Intel® VROC) Premium & Standard FIO Software for HPE
- New 4th Generation Intel® Xeon® Scalable Processors (Medium Core Count die/ MCC die)
- New DL360 Gen11 Standard Heatsink & Standard Fan Kit
- New DL360 Gen11 20EDSFF NC CTO Server
- New DL360 Gen11 Pre-Configured Models
- New HPE NVMe EDSFF E3.s 1T SSD
- New HPE Self-encrypting Drives
- HPE 500W Flex Slot Platinum Hot Plug Low Halogen Power Supply Kit



Overview

- HPE 800W Flex Slot Titanium Hot Plug Low Halogen Power Supply Kit
- HPE 1600W Flex Slot -48VDC Hot Plug Power Supply Kit
- HPE ProLiant DL360 Gen11 Direct Liquid Cooling solution
- HPE ProLiant for vSAN
- HPE Azure Stack HCI
- OpenBMC Capable through iLO6 Transfer of Ownership Process
- HPE 96GB Dual Rank x4 DDR5-4800 Registered Smart Memory Kit
- HPE 1800W-2200W Flex Slot Titanium Hot Plug Power Supply Kit
- HPE ProLiant DL3xx Gen11 Cache Mode for HBM Memory Mode setting from factory installation
- New 5th Generation Intel® Xeon® Scalable Processors (Extreme Core Count die/ XCC die; Medium Core Count/ MCC; Edge Enhanced Low Core Count die /EE LCC)
- New HPE DDR5 SmartMemory – Registered (RDIMM), 5600MT/s
- Energy Star 4.0 Compliance
- European Union Erp Lot 9 Regulation
- **Intel Virtual RAID on CPU RAID 1 FIO Software for HPE**
- HPE 256GB (1x256GB) Octal Rank x4 DDR5-5600 CAS-52-45-45 EC8 Registered 3DS Smart Memory Kit

Platform Information

Form Factor

- 1U rack

Chassis Types

- 20 EDSFF Carrier 1T (EC1) drive bays: 32G x4 NVMe (PCIe5.0 E3.s 1T)
- 8 SFF Basic Carrier (BC) drive bays:
 - 24G x1 NVMe/SAS (TriMode) U.3 (PCIe4.0) or
 - 24G x4 NVMe/SAS (TriMode) U.3 (PCIe4.0)
- With options for additional 2 SFF BC drive bays: 24G x4 NVMe/SAS (TriMode) U.3 (PCIe4.0)
- With options for additional optical drive, 1x USB3.2 Gen1 and 1x Display Port
- 4 LFF Low Profile (LP) drive bays: 12G x1 SAS/SATA
- With additional options for optical drive, 1x USB3.2 Gen1, and 1x Display Port

System Fans

- **For 4 LFF and 8+2 SFF chassis**
 - Choice of 1P (one processor) Standard Fan Kit, 2P (two processors) Standard Fan Kit, Performance Fan Kits and Closed-loop Liquid Cooling Heatsink Fan FIO Bundle Kit
- **For 20 EDSFF chassis**
 - Choice of Performance Fan Kits and Closed-loop Liquid Cooling Heatsink Fan FIO Bundle Kit

Notes:

- Standard Fan Kit: Dual rotor hot plug Standard Fan kit (includes 5 fans) for processors below 185W TDP.
- Optional 2P standard Fan Kit: Dual rotor hot plug 2P Standard Fan Kit (includes 2 fans) for second processor.
- Performance Fan Kit: Dual rotor hot plug High Performance Fan Kit available (includes 7 fans), for one or two processors from 186W to 270W TDP. Or one processor with 300W TDP.
- The DL360 Gen11 will support up to 7 fans with fan redundancy built in. One fan rotor failure will place server in degraded mode but fully functional. Two fan rotor failures could provide warning and imminent server shutdown.
- Closed-loop Liquid Cooling Heat Sink Fan FIO Bundle Kit supports one or two processors that go beyond 271W TDP, as factory installation kit only. Customer self-repair or self-field upgrade is not allowed.
- Direct Liquid Cooling Heatsink Fan FIO Bundle Kit supports two processors go beyond 271W TDP, with enhanced thermal condition



Optional Features

Processors – Up to 2 of the following, depending on model.

- The 2nd digit of the processor model number “x4xx” is used to denote the processor generation (i.e. 4 = New 4th Generation Intel® Xeon® Scalable Processors)
- The required firmware for the 5th Generation Intel Xeon Processors is not compatible with the DL360 Gen11 system board shipped with the 4th Generation Intel Xeon Processors. A new server order (latest firmware system board) is required for the activation of the 5th Generation Intel Xeon Processors. Field upgrade from the 4th Generation Intel Xeon Processors to the 5th Generation is not supported.

Notes:

- All information provided here is subject to change without notice. Intel may make changes to specifications and product descriptions at any time, without notice. Please contact your Intel representative to obtain the latest Intel product specifications and roadmaps.
- For more information regarding Intel® Xeon® Scalable Processors, please see the following <http://www.intel.com/xeon>.

New 4th Generation Intel® Xeon® Scalable Processors numbering convention

Workload

| New 4 th Generation Intel® Xeon® Scalable Processors | | |
|---|--|---|
| Processor Suffix | Description | Offering |
| H | DB and Analytics | Highest core counts. Database and Analytics usages benefit from DSA and IAA accelerators. |
| M | Media Transcode | Optimized around AVX frequencies to deliver better performance/watt around Media, AI, and HPC workloads. |
| N | Network/5G/Edge (High TPT/Low latency) | Designed for NFV and networking workloads, such as: L3 forwarding, 5G UPF, OVS DPDK, VPP FIB router, VPP IPsec, web server/NGINX, vEPC, vBNG, and vCMTS. |
| S | Storage and HCI | Optimized for Storage UMA use cases with increased UPI Bandwidth for vs Mainline SKUs. |
| P | Cloud - IaaS | Designed for cloud IaaS environments to deliver higher frequencies at constrained TDPs. |
| Q | Liquid Cooling | Liquid cooled processors with higher frequency and performance at same TDP. |
| U | One Socket Optimized | Optimized for targeted platforms adequately served by the cores, memory bandwidth and IO capacity. Available from a single processor configuration. |
| V | Cloud- SaaS | Optimized for orchestration efficiency that delivers higher core counts and VMs per rack. |
| Y | Speed Select ¹ | Intel® SST-Performance Profile (PP) increases base frequency when fewer cores are enabled. Allows greater flexibility, deployment options and platform longevity. |

Notes:

- Covers the Intel public offering only.
- New Built-in Accelerators.
 - o 1 to 8 socket support
 - o Intel® Data Streaming Accelerator (DSA)
 - o Intel® Dynamic Load Balancer (DLB)
 - o Intel® Quick Assist Technology (QAT)
 - o Intel® In-Memory Analytics Accelerator (IAA)
- Increased memory bandwidth with 8 channels DDR5, up to 4800 MT/s, 4.0TB maximum RAM per socket.
- Increased I/O bandwidth up to 80 PCIe 5.0 lanes per socket, and new Compute Express Link (CXL).
- Built-in AI Acceleration: Intel® Advanced Matrix Extension (AMX)
- Hardware-enhanced Security: Enhanced Intel® Software Guard Extensions (SGX) – with new cryptographic memory integrity
- Increased Multi-Socket Bandwidth with new UPI2.0 (up to 16GT/s) with maximum 4 UPI Links



Optional Features

- New FlexBus I/O Interface PCIe5.0 + CXL
- ¹The 4th Generation Intel® Xeon® Scalable Processors are featured with Intel Speed Select Technology (SST) for Infrastructure as a Service, Networking and Virtualized environments workloads. The SST includes,
 - o SST- Performance Profile
 - o SST- Base Frequency
 - o SST- Core Power
 - o SST- Turbo Frequency
- Default setting in ROM-Based Setup Utility (RBSU) as shown.

| Intel® SST Features | RBSU Options | Granular Control over CPU Performance | Default Setting |
|---------------------------|--|--|--|
| SST- Performance Profile | Dynamic Intel® Speed Select Technology – Performance Profile | Allows the CPU to run in one of three performance profiles | CPU hardware-based. Enabled by default |
| SST-Base Frequency | Intel® Speed Select Technology – Base Frequency | Enables some CPU cores to run at a higher base frequency in return for other cores running at a lower base frequency | Disabled by default |
| SST-Core Power | Intel® Speed Select Technology – Core Power | Allows software to prioritize with cores will receive excess power after satisfying minimum requirements | Disabled by default |
| Intel SST Turbo Frequency | Intel® Turbo Boost Technology | Allows software-selected cores to achieve a higher max turbo frequency by reducing other cores' max turbo frequency | Enabled by default |

| 5 th Generation Intel® Xeon® Scalable Processor Family (Platinum) | | | | | | | | |
|--|-----------|-------|----------|-------|-----|-----------|------------------|-----|
| Intel® Xeon® Models | Frequency | Cores | L3 Cache | Power | UPI | DDR5 | SGX Enclave size | Die |
| Platinum 8593Q Processor | 2.2 GHz | 64 | 320 MB | 385W | 4 | 5600 MT/s | 512 GB | XCC |
| Platinum 8592+ Processor | 1.9 GHz | 64 | 320 MB | 350W | 4 | 5600 MT/s | 512 GB | XCC |
| Platinum 8592V Processor | 2.0 GHz | 64 | 320 MB | 330W | 3 | 4800 MT/s | 512 MB | XCC |
| Platinum 8581V ¹ Processor | 2.0 GHz | 60 | 300 MB | 270W | 0 | 4800 MT/s | 512 GB | XCC |
| Platinum 8580 Processor | 2.0 GHz | 60 | 300 MB | 350W | 4 | 5600 MT/s | 512 GB | XCC |
| Platinum 8570 Processor | 2.1 GHz | 56 | 300 MB | 350W | 4 | 5600 MT/s | 512 GB | XCC |
| Platinum 8568Y Processor | 2.3 GHz | 48 | 300 MB | 350W | 4 | 5600 MT/s | 512 GB | XCC |
| Platinum 8562Y+ Processor | 2.8 GHz | 32 | 300 MB | 300W | 3 | 5600 MT/s | 512 GB | MCC |
| Platinum 8558P Processor | 2.7 GHz | 48 | 260 MB | 350W | 3 | 5600 MT/s | 512 GB | XCC |
| Platinum 8558 Processor | 2.1 GHz | 48 | 260 MB | 330W | 4 | 5200 MT/s | 512 GB | XCC |
| Platinum 8558U ¹ Processor | 2.0 GHz | 48 | 260 MB | 300W | 0 | 4800 MT/s | 512 GB | XCC |

Notes:

- One or two processor(s) with TDP equal to or greater than 186W through 270W require High Performance Heatsink Kit (P48905-B21) and High-Performance Fan Kit (P48908-B21)
- Two processors with TDP equal to or greater than 271W require Closed-loop Liquid Cooling Heat Sink Fan FIO Bundle Kit (P48906-B21) or Direct Liquid Cooling solution.
- In 300Watt processor one socket configuration, the air cooling with Performance Heatsinks & Performance Fan Kits can be supported. Field upgrade to two socket is not supported with air cooling solution.
- ¹Single socket only, no dual socket support
- Intel® Speed Select enabled processors: Platinum 8593Q, 8592V, 8581V, 8568Y+, 8562Y+, 8558P, 8558 and 8558U.



Optional Features

5th Generation Intel® Xeon® Scalable Processor Family (Gold 6)

| Intel® Xeon® Models | Frequency | Cores | L3 Cache | Power | UPI | DDR5 | SGX Enclave size | Die |
|-----------------------|-----------|-------|----------|-------|-----|-----------|------------------|-----|
| Gold 6558Q Processor | 3.2 GHz | 32 | 60.0 MB | 350W | 3 | 5200 MT/s | 128 GB | MCC |
| Gold 6554S Processor | 2.2 GHz | 36 | 180 MB | 270W | 4 | 5200 MT/s | 128 GB | XCC |
| Gold 6548N Processor | 2.8 GHz | 32 | 60.0 MB | 250W | 3 | 5200 MT/s | 128 GB | MCC |
| Gold 6548Y+ Processor | 2.5 GHz | 32 | 60.0 MB | 250W | 3 | 5200 MT/s | 128 GB | MCC |
| Gold 6544Y Processor | 3.6 GHz | 16 | 45.0 MB | 270W | 3 | 5200 MT/s | 128 GB | MCC |
| Gold 6542Y Processor | 2.9 GHz | 24 | 60.0 MB | 250W | 3 | 5200 MT/s | 128 GB | MCC |
| Gold 6538N Processor | 2.1 GHz | 32 | 60.0 MB | 205W | 3 | 5200 MT/s | 128 GB | MCC |
| Gold 6538Y+ Processor | 2.2 GHz | 32 | 60.0 MB | 225W | 3 | 5200 MT/s | 128 GB | MCC |
| Gold 6534 Processor | 3.9 GHz | 8 | 22.5 MB | 195W | 3 | 4800 MT/s | 128 GB | MCC |
| Gold 6530 Processor | 2.1 GHz | 32 | 160 MB | 270W | 3 | 4800 MT/s | 128 GB | XCC |
| Gold 6526Y Processor | 2.8 GHz | 16 | 37.5 MB | 195W | 3 | 5200 MT/s | 128 GB | MCC |

Notes:

- One or two processor(s)
- One or two processor(s) with TDP equal to or greater than 186W through 270W or one processor with TDP equals 300W, require High Performance Heatsink Kit (P48905-B21) and High-Performance Fan Kit (P48908-B21) together.
- Two processors with TDP equal or greater than 271W require Closed-loop Liquid Cooling Heat Sink Fan FIO Bundle Kit (P48906-B21) or Direct Liquid Cooling solution.
- In 300W processor one socket configuration, the air cooling with Performance Heatsinks & Performance Fan Kits can be supported together. Field upgrade to two socket is not supported with air cooling solution.
- Intel® Speed Select enabled processors: Gold 6558Q, 6554S, 6548N, 6548Y+, 6544Y, 6542Y, 6538N, 6538Y+ and 6526Y.

5th Generation Intel® Xeon® Scalable Processor Family (Gold 5)

| Intel® Xeon® Models | Frequency | Cores | L3 Cache | Power | UPI | DDR5 | SGX Enclave size | Die |
|----------------------|-----------|-------|----------|-------|-----|-----------|------------------|-----|
| Gold 5520+ Processor | 2.2 GHz | 28 | 52.5 MB | 205W | 3 | 4800 MT/s | 128 GB | MCC |
| Gold 5515+Processor | 3.2 GHz | 8 | 22.5 MB | 165W | 3 | 4800 MT/s | 128 GB | MCC |

Notes:

- One or two processor(s)
- Intel® Speed Select enabled processors: N.A.

5th Generation Intel® Xeon® Scalable Processor Family (Silver)

| Intel® Xeon® Models | Frequency | Cores | L3 Cache | Power | UPI | DDR5 | SGX Enclave size | Die |
|-------------------------|-----------|-------|----------|-------|-----|-----------|------------------|-----------|
| Silver 4516Y+ Processor | 2.2 GHz | 24 | 45.0 MB | 185W | 2 | 4400 MT/s | 64 GB | MCC |
| Silver 4514Y Processor | 2.0 GHz | 16 | 30.0 MB | 150W | 2 | 4400 MT/s | 64 GB | MCC |
| Silver 4510 Processor | 2.4 GHz | 12 | 30.0 MB | 150W | 2 | 4000 MT/s | 64 GB | EE LCC |
| Silver 4509Y Processor | 2.6 GHz | 8 | 22.5 MB | 125W | 2 | 4400 MT/s | 64 GB | EE LCC |

Notes:

- One or two processor(s)
- Intel® Speed Select enabled processors: 4516Y+, 4514Y and 4509Y.
- If 4510 or 4509Y is selected, then 96GB 5600 MT/s Memory cannot be selected.

5th Generation Intel® Xeon® Scalable Processor Family (Bronze)

| Intel® Xeon® Models | Frequency | Cores | L3 Cache | Power | UPI | DDR5 | SGX Enclave size | Die |
|-------------------------------------|-----------|-------|----------|-------|-----|-----------|------------------|-----------|
| Bronze 3508U Processor ¹ | 2.1 GHz | 8 | 22.5 MB | 125W | N/A | 4400 MT/s | 64 GB | EE LCC |



Optional Features

Notes:

- ¹Single socket capable, no dual socket support
- Intel® Speed Select enabled processors: N.A.
- If 3508U is selected, then 96GB 5600MT/s Memory cannot be selected
- PCIe4.0 only

4th Generation Intel® Xeon® Scalable Processor Family (Platinum)

| Intel® Xeon® Models | Frequency | Cores | L3 Cache | Power | UPI | DDR5 | SGX Enclave size | Die |
|---|-----------|-------|----------|-------|-----|-----------|------------------|-----|
| Platinum 9462 Processor | 2.7 GHz | 32 | 75.0 MB | 350W | 3 | 4800 MT/s | 128 GB | HBM |
| Platinum 8490H Processor | 1.9 GHz | 60 | 112.5 MB | 350W | 4 | 4800 MT/s | 512 GB | XCC |
| Platinum 8480+ Processor | 2.0 GHz | 56 | 105 MB | 350W | 4 | 4800 MT/s | 512 GB | XCC |
| Platinum 8470 Processor | 2.0 GHz | 52 | 105 MB | 350W | 4 | 4800 MT/s | 512 GB | XCC |
| Platinum 8470Q Processor | 2.1 GHz | 52 | 105 MB | 350W | 4 | 4800 MT/s | 512 GB | XCC |
| Platinum 8470N Processor | 1.7 GHz | 52 | 105 MB | 300W | 3 | 4800 MT/s | 128 GB | XCC |
| Platinum 8468 Processor | 2.1 GHz | 48 | 105 MB | 350W | 4 | 4800 MT/s | 512 GB | XCC |
| Platinum 8468V Processor | 2.4 GHz | 48 | 97.5 MB | 330W | 3 | 4800 MT/s | 128 GB | XCC |
| Platinum 8462Y+ Processor | 2.8 GHz | 32 | 60.0 MB | 300W | 3 | 4800 MT/s | 128 GB | MCC |
| Platinum 8460Y ¹⁺² Processor | 2.0 GHz | 40 | 105 MB | 300W | 4 | 4800 MT/s | 128 GB | XCC |
| Platinum 8458P Processor | 2.7 GHz | 44 | 82.5 MB | 350W | 3 | 4800 MT/s | 512 GB | XCC |
| Platinum 8452Y ¹ Processor | 2.0 GHz | 36 | 67.5 MB | 300W | 4 | 4800 MT/s | 128 GB | XCC |
| Platinum 8444H Processor | 2.9 GHz | 16 | 45.0 MB | 270W | 4 | 4800 MT/s | 512 GB | XCC |

Notes:

- One or two processor(s) with TDP equal to or greater than 186W through 270W require High Performance Heatsink Kit (P48905-B21) and High-Performance Fan Kit (P48908-B21)
- Two processors with TDP equal or greater than 271W require Closed-loop Liquid Cooling Heat Sink Fan FIO Bundle Kit (P48906-B21)
- In 300Watt processor one socket configuration, the air cooling with Performance Heatsinks & Performance Fan Kits can be supported. Field upgrade to two socket is not supported with air cooling solution.
- ¹Supports Intel® Speed Select Performance Profile (SST-PP), even though not being a “Y” processor.
- ²+: Feature Plus: Support AMX, DLB, DSA, IAA and QAT additionally
- Intel® Speed Select enabled processors: Platinum 8468V, 8460Y+, 8458P and 8452Y.

4th Generation Intel® Xeon® Scalable Processor Family (Gold 6)

| Intel® Xeon® Models | Frequency | Cores | L3 Cache | Power | UPI | DDR5 | SGX Enclave size | Die |
|-----------------------------------|-----------|-------|----------|-------|-----|-----------|------------------|-----|
| Gold 6458Q Processor | 3.1 GHz | 32 | 60.0 MB | 350W | 3 | 4800 MT/s | 128 GB | MCC |
| Gold 6454S Processor | 2.2 GHz | 32 | 60.0 MB | 270W | 4 | 4800 MT/s | 128 GB | XCC |
| Gold 6448Y Processor | 2.1 GHz | 32 | 60.0 MB | 225W | 3 | 4800 MT/s | 128 GB | MCC |
| Gold 6448H Processor | 2.4 GHz | 32 | 60.0 MB | 250W | 3 | 4800 MT/s | 512 GB | MCC |
| Gold 6444Y Processor | 3.6 GHz | 16 | 45.0 MB | 270W | 3 | 4800 MT/s | 128 GB | MCC |
| Gold 6442Y Processor | 2.6 GHz | 24 | 60.0 MB | 225W | 3 | 4800 MT/s | 128 GB | MCC |
| Gold 6438Y+ Processor | 2.0 GHz | 32 | 60.0 MB | 205W | 3 | 4800 MT/s | 128 GB | MCC |
| Gold 6438N Processor | 2.0 GHz | 32 | 60.0 MB | 205W | 3 | 4800 MT/s | 128 GB | MCC |
| Gold 6434 Processor | 3.7 GHz | 8 | 22.5 MB | 195W | 3 | 4800 MT/s | 128 GB | MCC |
| Gold 6430 Processor | 2.1 GHz | 32 | 60.0 MB | 270W | 3 | 4400 MT/s | 128 GB | XCC |
| Gold 6426Y Processor | 2.5 GHz | 16 | 37.5 MB | 185W | 3 | 4800 MT/s | 128 GB | MCC |
| Gold 6421N Processor ¹ | 1.8 GHz | 32 | 60.0 MB | 185W | N/A | 4400 MT/s | 128 GB | MCC |
| Gold 6418H Processor | 2.1 GHz | 24 | 60.0 MB | 185W | 3 | 4800 MT/s | 512 GB | MCC |
| Gold 6416H Processor | 2.2 GHz | 18 | 45.0 MB | 165W | 3 | 4800 MT/s | 512 GB | MCC |
| Gold 6414U Processor ¹ | 2.0 GHz | 32 | 60.0 MB | 250W | N/A | 4800 MT/s | 128 GB | XCC |



Optional Features

Notes:

- One or two processor(s)
- ¹Single socket capable, no dual socket support
- One or two processor(s) with TDP equal to or greater than 186W through 270W or one processor with TDP equals 300W, require High Performance Heatsink Kit (P48905-B21) and High-Performance Fan Kit (P48908-B21) together.
- In 300W processor one socket configuration, the air cooling with Performance Heatsinks & Performance Fan Kits can be supported together. Field upgrade to two socket is not supported with air cooling solution.
- One or two processors with TDP equal or greater than 271W require Closed-loop Liquid Cooling Heat Sink Fan FIO Bundle Kit (P48906-B21)
- 96GB 4800 MT/s Memory cannot be selected if HBM die

4th Generation Intel® Xeon® Scalable Processor Family (Gold 5)

| Intel® Xeon® Models | Frequency | Cores | L3 Cache | Power | UPI | DDR5 | SGX Enclave size | Die |
|-----------------------------------|-----------|-------|----------|-------|-----|-----------|------------------|-----|
| Gold 5420+ Processor | 2.0 GHz | 28 | 52.5MB | 205W | 3 | 4400 MT/s | 128 GB | MCC |
| Gold 5418Y Processor | 2.0 GHz | 24 | 45.0 MB | 185W | 3 | 4400 MT/s | 128 GB | MCC |
| Gold 5418N Processor | 1.8 GHz | 24 | 45.0 MB | 165W | 3 | 4000 MT/s | 128 GB | MCC |
| Gold 5416S Processor | 2.0 GHz | 16 | 30.0 MB | 150W | 3 | 4400 MT/s | 128 GB | MCC |
| Gold 5415+Processor | 2.9 GHz | 8 | 22.5 MB | 150W | 3 | 4400 MT/s | 128 GB | MCC |
| Gold 5411N ¹ Processor | 1.9 GHz | 24 | 45.0 MB | 165W | N/A | 4400 MT/s | 128 GB | MCC |

Notes:

- One or two processor(s)
- ¹Single socket capable, no dual socket support
- 96GB 4800 MT/s Memory cannot be selected if HBM die

4th Generation Intel® Xeon® Scalable Processor Family (Silver)

| Intel® Xeon® Models | Frequency | Cores | L3 Cache | Power | UPI | DDR5 | SGX Enclave size | Die |
|------------------------|-----------|-------|----------|-------|-----|-----------|------------------|-----|
| Silver 4416+ Processor | 2.0 GHz | 20 | 37.5MB | 165W | 2 | 4000 MT/s | 64 GB | MCC |
| Silver 4410Y Processor | 2.0 GHz | 12 | 30.0 MB | 150W | 2 | 4000 MT/s | 64 GB | MCC |

Notes:

- One or two processor(s)
- 96GB 4800 MT/s Memory cannot be selected if HBM die.

4th Generation Intel® Xeon® Scalable Processor Family (Bronze)

| Intel® Xeon® Models | Frequency | Cores | L3 Cache | Power | UPI | DDR5 | SGX Enclave size | Die |
|-------------------------------------|-----------|-------|----------|-------|-----|-----------|------------------|-----|
| Bronze 3408U Processor ¹ | 1.8 GHz | 8 | 22.5 MB | 125W | N/A | 4000 MT/s | 64 GB | MCC |

Notes:

- ¹Single socket capable, no dual socket support
- PCIe4.0 only
- 96GB 4800 MT/s Memory cannot be selected if HBM die

Chipset

Intel® C741 Chipset (Code Name: Product formerly Emmitsburg)

Notes: For more information regarding Intel® chipsets, please see the following URL:

<https://www.intel.com/content/www/us/en/products/chipsets/server-chipsets.html>

System Management Chipset

HPE iLO 6 ASIC

Notes: Read and learn more in the [iLO QuickSpecs](#).



Optional Features

Memory

| Type | HPE DDR5 Smart Memory | Registered (RDIMM) |
|--------------------------|-----------------------|--|
| DIMM Slots Available | 32 | 16 DIMM slots per processor, 8 channels per processor, 2 DIMMs per channel |
| Maximum capacity (RDIMM) | 8.0 TB | 32 x 256 GB RDIMM @ 5600 MT/s or 4800 MT/s |

Notes:

- All processors support up to 4TB memory per socket.
- The maximum memory speed is limited by the processor selection.
- To realize the performance memory capabilities listed in this document, HPE DDR5 Smart Memory is required.
- For additional information, please visit the [HPE Memory QuickSpecs and Technical White Papers or HPE DDR5 Smart Memory QuickSpecs](#).

Memory Protection

Advanced ECC

Advanced ECC uses single device data correction to detect and correct single and all multibit error that occurs within a single DRAM chip.

Online Spare

Memory online spare mode detects a rank that is degrading and switches operation to the spare rank.

Notes: For more information see our [Memory RAS feature technical whitepaper](#).

PCIe Expansion Slots

Primary Riser (default in chassis)

| Expansion Slots # | Technology | Bus Width | Connector Width | Processor | Slot Form Factor |
|-------------------|------------|-----------|-----------------|-----------|--|
| 1 | PCIe 5.0 | x16 | x16 | CPU 1 | Full-height, up to 9.5" length (or half-length card) |
| 2 | PCIe 5.0 | x16 | x16 | CPU 1 | Half-height (Low-profile), up to 9.5" length (or half length card) |

Notes: The specifications above correspond with the default primary butterfly riser, which comes with CTO chassis.

Secondary Riser*

| Expansion Slots # | Technology | Bus Width | Connector Width | Processor | Slot Form Factor (two options) |
|-------------------|------------|-----------|-----------------|-----------|---|
| 3 | PCIe 5.0 | x16 | x16 | CPU 2 | Full-height, up to 9.5" length (or half-length card). Slot 2 will be not available. |
| | | | | | Half-height (Low-profile), up to 9.5" length (or up half length card). Slot 2 is available. |

Notes:

- All PCIe Slots support Wake-on-Lane (WoL) feature.
- If Secondary riser is selected, then 2 Processor must be selected.
- If secondary riser is not selected and "NS204i-u Rear Cbl Kit" is not selected, then maximum 2 quantity of PCIe cards can be selected at Slot1 & Slot2. If secondary riser is not selected and "NS204i-u Rear Cbl Kit" is selected, then maximum 1 quantity of PCIe cards can be selected at Slot1.
- If secondary FH riser is installed, then primary PCIe Slot2 cannot be used, maximum 2 quantity of PCIe cards can be selected at Slot 1 & Slot3. If secondary FH riser is not selected, then maximum 1 quantity of FH PCIe cards can be selected at Slot1 & Slot3.
- If Secondary LP riser and "NS204i-u Rear Cbl Kit" are selected, then maximum 2 quantity of PCIe cards can be selected at Slot 1 & Slot3. If Secondary LP riser is selected and "NS204i-u Rear Cbl Kit" is not selected, then maximum 3 quantity of PCIe cards can be selected.



Optional Features

- Field upgrade riser cards setting after factory installation and shipment is currently not available

OCP Expansion Slots

| OCP3.0 Slot Priority Support Matrix | | | | | | |
|-------------------------------------|-----------------------------------|---|---------------|---------------|-------------------------|--------------------------------|
| Rear wall | | Selected OCP cards (Qty & type) | | | | |
| OCP Slots # | Share NIC Feature | 2 | 1 | 1 | 1 | 2 |
| | | 1xOROC ¹ + 1x NIC ² | 1xNIC | 2xNICs | 1xOROC | 2x OROCs |
| 1 | N/A | OROC | (Secondary) | NIC | OROC (Primary) | OROC ⁴ (Primary) |
| 2 | Available (Incl. Wake-on-Lane) | NIC | NIC (Primary) | NIC (Primary) | No support ³ | OROC ⁴ |

Notes:

- ¹ OCP form factor internal controller.
- ² OCP Networking card.
- ³ If only 1 OROC card is selected, by default connected from 8SFF backplane to OCP Slot1. And there is no controller cable that can connect from 8SFF Backplane to OCP Slot 2.
- ⁴ If 2 OROC cards are selected, by default the 8SFF controller cable is connected to OCP Slot1 (the comparably higher-end OROC card to be selected by default) and the 2SFF backplane is connected to OCP Slot2 with another OROC card selected (comparably less high-end one) with 2FF controller cable.
- In 4LFF & 8SFF CTO Server, each OCP slot is in design with up to x16 electrical PCIe5.0 lanes through OCP enablement kits.
- In 20EDSFF CTO Server. Each OCP slots are in design with up to x8 electrical PCIe5.0 lanes (OCP Slot2 through OCP enablement kit)

Internal Storage Devices

- Optical Drive**
Available on 8 SFF and 4 LFF CTO Servers as an option (DVD-ROM or DVD-RW)
- Hard Drives**
None ship standard

Storage Controllers

NVMe Boot Devices

- HPE NS204i-u NVMe Hot Plug Boot Optimized Storage Device (P48183-B21)¹
- HPE ProLiant DL360 Gen11 NS204i-u Rear Cable Kit (P54702-B21)
- HPE ProLiant DL360 Gen11 NS204i-u Internal Cable Kit (P48920-B21)

| DL360 Gen11 NS204i-u Enablement Kit Support Matrix | | | | |
|--|--|-------------|--------------------------|---------------------|
| Enablement Kit | Description | Field Inst. | NS204i-u Location | Hot-plug Capability |
| P54702-B21 | HPE ProLiant DL360 Gen11 NS204i-u Rear Cable Kit | Yes | PCIe Slot 2 ² | Yes |
| P48920-B21 | HPE ProLiant DL360 Gen11 NS204i-u Internal Cable Kit | Yes | Internal | No support |

Notes:

- ¹x4 PCIe Gen3.0 OS Boot device includes 2x 480GB M.2 NVMe SSDs, with preconfigured hardware RAID1.
- ²Removing the original PCIe Slot 2 cage and re-install the dedicated DL360 Gen11 NS204i-u cage, latch and cables in the P54702-B21. The NS204i-u will take up PCIe Slot 2 space only. The PCIe Slot 1 (FHHL) and PCIe Slot 3 (to be Low Profile) are available in the system with the selection of optional "HPE ProLiant DL360 Gen11 x16 LP Riser Kit (P48903-B21)".
- For additional information, please see the [HPE OS Boot Device QuickSpecs](#)



Optional Features

Software RAID Controllers

The available Gen11 controllers are depicted below.

Software RAID Controller

- **Intel® VROC SATA for HPE ProLiant Gen11**

Notes:

- Embedded Intel® VROC SATA for HPE ProLiant Gen11, with 14 SATA ports (10-ports accessible),
- Intel® VROC for HPE ProLiant Gen11 is an enterprise, hybrid Software RAID solution specifically designed for SSDs.
- Intel® VROC is a software-based solution utilizing Intel® CPU to RAID or HBA direct connected drives.
- RAID Support- 0/1/5/10.
- Windows and Linux OS support.
- Host Tools- Windows GUI/CLI, Linux CLI.
- UEFI Support- HII Utility, OBSE.
- iLO Support- IML, Alert, SNMP, AHS.
- iLO Redfish- Redfish Read .
- Intel® VROC SATA for HPE ProLiant Gen11 will operate in UEFI mode only. For legacy support an additional storage controller will be needed.
- Intel® VROC SATA is off by default and must be enabled.

- **Intel® VROC NVMe for HPE ProLiant Gen11**

- Intel® Virtual RAID on CPU (Intel® VROC) Premium FIO Software for HPE
- Intel® Virtual RAID on CPU (Intel® VROC) Standard Software FIO for HPE

Notes:

- All models feature 4 x8 PCIe 5.0 connectors per socket for NVMe connectivity, provides support for up to 8 direct attach x4 NVMe bays.
- Only supported on SFF models.
- Intel® VROC for HPE ProLiant Gen11 is an enterprise, hybrid Software RAID solution specifically designed for NVMe SSDs connected directly to the CPU. Intel® VROC is a software-based solution utilizing Intel® CPU to RAID or HBA direct connected drives.
- Intel® Virtual RAID on CPU Standard for RAID 0/1/10 (S0E37A/S0E38AAE) or Premium SKU for RAID 0/1/5/10 (R7J57A/R7J59AAE) must be ordered to enable RAID support Windows, Linux, VMware OS support.
- Host Tools- Windows GUI/CLI, Linux CLI.
- UEFI Support- HII Utility, OBSE.
- Active health monitoring of NVMe M.2 drives requires use of SMART tools.
- Intel® VROC NVMe for HPE ProLiant Gen11 will operate in UEFI mode only. For legacy support an additional Tri-Mode controller will be needed.
- For NVMe SSDs only, no PCIe card support.

In HPE ProLiant Gen11 servers, when secure boot is enabled, Intel® Virtual RAID on CPU (Intel® VROC) 8.0 Out-of-Band (OOB) management does not function with Linux kernel version 5.4 (or later). Intel® VROC OOB will not respond to any PLDM (over-MCTP-over-PCIe) requests from iLO (BMC). Intel® VROC Redfish resources will not function (e.g., Redfish actions); therefore, Intel® VROC over Redfish management is not available. This is due to a new security feature in Linux kernel version 5.4 (or later). For more information, pls visit **Customer Advisory Document ID: a00128934en_us** at HPE Support Center.

More product information is available at **[Intel VROC for HPE ProLiant QuickSpecs](#)**



Optional Features

Essential RAID Controllers

- HPE Smart Array E208e-p SR Gen10 Controller

Performance RAID Controllers

- HPE MR216i-p Gen11 x16 Lanes without Cache PCI SPDM Plug-in Storage Controller
- HPE MR216i-o Gen11 x16 Lanes without Cache OCP SPDM Storage Controller
- HPE MR408i-o Gen11 x8 Lanes 4GB Cache OCP SPDM Storage Controller
- HPE MR416i-o Gen11 x16 Lanes 8GB Cache OCP SPDM Storage Controller
- HPE MR416i-p Gen11 x16 Lanes 8GB Cache PCI SPDM Plug-in Storage Controller
- HPE SR932i-p Gen11 x32 Lanes 8GB Wide Cache PCI SPDM Plug-in Storage Controller^{1,2}

Notes:

- PE80xx NVMe drives are not supported.
- ¹Requires x16 physical and electrical riser slot.
- ²If a second controller is required, must select a secondary FH riser. For additional details, please see:

For more information, pls visit

[HPE Compute MR Gen11 Controllers QuickSpecs](#)

[HPE Compute SR Gen11 Controllers QuickSpecs](#)

Maximum Storage

| Storage | Capacity | Configuration |
|--------------------------------|----------|--|
| Hot Plug SFF SAS HDD | 24.0 TB | 8+2 x 2.4 TB (with optional 2 SFF cage on UMB) |
| Hot Plug SFF SATA HDD | 20.0 TB | 8+2 x 2.0 TB (with optional 2 SFF cage on UMB) |
| Hot Plug SFF SAS SSD | 153.6 TB | 8+2 x 15.36 TB (with optional 2 SFF cage on UMB) |
| Hot Plug SFF SATA SSD | 76.8 TB | 8+2 x 7.68 TB (with optional 2 SFF cage on UMB) |
| Hot Plug SFF U.3 NVMe PCIe SSD | 153.6 TB | 8+2 x 15.36 TB (with optional 2 SFF cage on UMB) |
| Hot Plug LFF SAS HDD | 80.0 TB | 4 x 20 TB |
| Hot Plug LFF SATA HDD | 80.0 TB | 4 x 20 TB |
| Hot Plug LFF SAS SSD | 30.72 TB | 4 x 7.68 TB |
| Hot Plug LFF SATA SSD | 3.84 TB | 4 x 960 GB |
| M.2 NVMe SSD | 960 GB | 2 x 480 GB (shipped with optional HPE NS204i-u Gen11 NVMe Hot Plug Boot Optimized Storage Device): Available with external or internal version |
| EDSFF M.2 NVMe SSD | 307.2TB | 20 x 15.36 TB |

Graphics

Integrated video standard

- Video modes up to 1920 x 1200 @ 60 Hz (32 bpp)
- 16 MB Video Memory

HPE iLO 6 on system management memory

- 32 MB Flash
- 8 Gbit DDR4 with ECC protection

Power Supply

- HPE 500W Flex Slot Platinum Hot Plug Low Halogen Power Supply Kit
Notes: Available in 94% efficiency.
- HPE 800W Flex Slot Platinum Hot Plug Low Halogen Power Supply Kit
Notes: Available in 94% efficiency.



Optional Features

- HPE 800W Flex Slot Titanium Hot Plug Low Halogen Power Supply Kit
Notes: Available in 96% efficiency.
- HPE 1000W Flex Slot Titanium Hot Plug Low Halogen Power Supply Kit
Notes: Available in 96% efficiency.
- HPE 1600W Flex Slot -48VDC Hot Plug Power Supply Kit
- HPE 1600W Flex Slot Platinum Hot Plug Low Halogen Power Supply Kit
Notes:
 - Available in 94% efficiency.
 - 1600W Platinum Power supplies only support high line voltage (200 VAC to 240 VAC).
- HPE 1800W-2200W Flex Slot Titanium Hot Plug Power Supply Kit
Notes:
 - Available in 96% efficiency.
 - 1800-2200W Titanium Power supply only supports high line voltage (200 VAC to 240 VAC).

HPE Flexible Slot (Flex Slot) Power Supplies share a common electrical and physical design that allows for hot plug, tool-less installation into HPE ProLiant Gen11 Performance Servers. Flex Slot power supplies are certified for high-efficiency operation and offer multiple power output options, allowing users to "right-size" a power supply for specific server configurations. This flexibility helps to reduce power waste, lower overall energy costs, and avoid "trapped" power capacity in the data center.

All pre-configured servers ship with a standard 6-foot IEC C-13/C-14 jumper cord (A0K02A). This jumper cord is also included with each standard AC power supply option kit. If a different power cord is required, please check the [ProLiant Power Cables](#) web page.

To review the power requirements for your selected system, please visit the HPE Power Advisor located at: [HPE Power Advisor](#)

For information on power specifications and technical content visit [HPE Flexible Slot Power Supplies](#).

For information regarding European Union Erp Lot 9 Regulation visit [Industry Standard Compliance](#) section.

Interfaces

| | |
|---|---|
| Serial | 1 port - Optional |
| Video | 1 Front - Display port (optional) 1 Rear - VGA port (standard on all models) Notes: Both ports are not active simultaneously. |
| Network Ports | None. Choice of OCP or stand up card, supporting a wide arrange of NIC adapters. BTO models will come pre-selected with a primary networking card. |
| HPE iLO Remote Mgmt Port at rear | 1 GbE Dedicated |
| Front iLO Service Port | 1 standard |
| MicroSD Slot | Optional via HPE 32GB microSD RAID1 USB Boot Device Notes: <ul style="list-style-type: none"> – MicroSD cards are not hot-pluggable, server must be powered down before removal. – There is limited supply on MicroSD cards and may not be available in Gen11 |
| USB | 5 standard on all models: 1 front, 2 rear, 2 internal +1 optional at the front <ul style="list-style-type: none"> • Front: 1 USB 3.2 Gen1 + iLO service port • Rear: 2 USB 3.2 Gen1 • Internal: 1 USB 3.2 Gen1 + 1 USB 2.0 • Optional: 1 Front USB 2.0 |
| Systems Insight Display (SID) | Optional for 8SFF CTO Server model |



Optional Features

Operating Systems and Virtualization Software

See [HPE Servers Support & Certification Matrices](#)

- [Microsoft Windows Server](#)
- [VMware ESXi](#)
- [Red Hat Enterprise Linux \(RHEL\)](#)
- [SUSE Linux Enterprise Server \(SLES\)](#)
- [Canonical Ubuntu](#)
- [Oracle Linux and Oracle VM](#)
- [SAP Linux](#)

Notes:

- For Windows Server and Microsoft Hyper-V Server, will be certified when shipment is available.
 - RHEL and Citrix will be certified at a later timeframe.
-

Industry Standard Compliance

- ACPI 6.4 Compliant
- PCIe 5.0 Compliant
- WOL Support
- Microsoft® Logo certifications
- PXE Support
- VGA
- Display Port
- **Notes:** This support is on the optional Universal Media Bay.
- USB 3.2 Gen1 Compliant
- USB 2.0 Compliant (only on optional Universal Media Bay and embedded internal USB)
- USB NIC Driver in UEFI for Factory
- UEFI (Unified Extensible Firmware Interface Forum) Class 3 Support
- UEFI (Unified Extensible Firmware Interface Forum) 2.7 support
- **Notes:** UEFI is the default for the DL360 Gen11.
- OCP 3.0 SFF NIC Support
- OCP 3.0 SFF Storage Support
- Embedded TPM Support
- Energy Star 4.0
- SMBIOS 3.4
- Redfish API
- IPMI 2.0
- Secure Digital 4.0
- Advanced Encryption Standard (AES)
- Triple Data Encryption Standard (3DES)
- SNMP v3
- TLS 1.2
- DMTF Systems Management Architecture for Server Hardware Command Line (SMASH CLP)
- Active Directory v1.0



Optional Features

- ASHRAE A3/A4

Notes:

For additional technical, thermal details regarding ambient temperature, humidity, and feature support, please visit <http://www.hpe.com/servers/ashrae>

Under Standard Operating Support conditions, there is no time limitation for operating the servers in ASHRAE Class A2 conditions, unless otherwise specified in the applicable product information.

Intel Xeon Platinum 8470Q and 8593Q are not in scope.

- European Union Erp Lot 9 Regulation

European Union (EU) eco-design regulations for server and storage products, known as Lot 9, establishes power thresholds for idle state, as well as efficiency and performance in active state which vary among configurations. HPE ProLiant Gen11 servers are compliant with Lot9 requirements.

Please visit: <https://www.hpe.com/us/en/about/environment/msds-specs-more.html> for more information regarding HPE Lot 9 conformance.

Beginning on January 1st, 2024, units sold into the European Union (EU), European Economic Area (EEA), the United Kingdom, or Switzerland must include more efficient AC power supplies: 94% for multi-output and 96% for single-output. HPE Flexible Slot power supplies are single-output, and part numbers 865438-B21, P03178-B21, and P44712-B21 are 96% efficient, thus meeting requirements.

HPE is on target to fulfil compliant systems ahead of time and will begin enforcing these requirements in advance to satisfy requests with the current power supplies by the set deadline.

HPE Server UEFI

Unified Extensible Firmware Interface (UEFI) is an industry standard that provides better manageability and more secured configuration than the legacy ROM while interacting with your server at boot time. HPE ProLiant Gen11 servers have a UEFI Class 2 implementation to support UEFI Mode.

Notes: The UEFI System Utilities tool is analogous to the HPE ROM-Based Setup Utility (RBSU) of legacy BIOS. For more information, please visit <http://www.hpe.com/servers/uefi>.

UEFI enables numerous new capabilities specific to HPE ProLiant servers such as

- Secure Boot and Secure Start enable enhanced security.
- Embedded UEFI Shell
- Operating system specific functionality
- Mass Configuration Deployment Tool using iLO RESTful API that is Redfish API Conformant
- Support for > 2.2 TB (using GPT) boot drives.
- PXE boot support for IPv6 networks
- USB 3.2 Gen1 Stack
- Workload Profiles for simple performance optimization

UEFI Boot Mode only

- TPM 2.0 Support
- iSCSI Software Initiator Support.
- NVMe Boot Support
- HTTP/HTTPs Boot support as a PXE alternative.
- Platform Trust Technology (PTT) can be enabled.
- Boot support for option cards that only support a UEFI option ROM.

Notes: For UEFI Boot Mode, boot environment and OS image installations should be configured properly to support UEFI. Enabling TPM 2.0 no longer requires TPM module option kit for Gen11. It is an embedded feature yet disabled for shipments to China.



Optional Features

HPE GreenLake for Compute Ops Management

HPE is intelligently transforming compute management with an intuitive cloud operating experience through HPE GreenLake cloud platform to streamline and secure operations from edge-to-cloud. Automated key lifecycle tasks, for onboarding, updating, managing, and monitoring HPE servers, brings agility and greater efficiencies to wherever compute devices reside via a unified single browser-based interface. Manage single locations or multiple, distributed sites. Keep tens to thousands of servers secure with batch policy controls and automated updates.

Compute Ops Management is cloud-native software that is continually updated with new services, features, patches, and fixes. The management application resides in the HPE GreenLake cloud platform (access via <https://console.greenlake.hpe.com>) and leverages the HPE GreenLake architecture, security, and unified operations.

A 3-year subscription to HPE GreenLake for Compute Ops Management is added by default when ordering an HPE ProLiant Gen11 rack, tower, or micro server.

For more information, visit the HPE GreenLake for Compute Ops Management QuickSpecs:

<https://www.hpe.com/psnow/doc/a50004263enw>

Embedded Management

HPE Integrated Lights-Out (HPE iLO)

Monitor your servers for ongoing management, service alerting, reporting and remote management with HPE iLO.

Learn more at <http://www.hpe.com/info/ilo>.

UEFI

Configure and boot your servers securely with industry standard Unified Extensible Firmware Interface (UEFI).

Learn more at <http://www.hpe.com/servers/uefi>.

OpenBMC Support

OpenBMC Capable through iLO6 Transfer of Ownership Process.

Learn more at [OpenBMC Support](#)

Intelligent Provisioning

Hassle free server and OS provisioning for one or more servers with Intelligent Provisioning.

Learn more at <http://www.hpe.com/servers/intelligentprovisioning>.

iLO RESTful API

iLO RESTful API is DMTF Redfish API information and offers simplified server management automation such as configuration and maintenance tasks based on modern industry standards. Learn more at <http://www.hpe.com/info/restfulapi>.

Server Utilities

Active Health System

The HPE Active Health System (AHS) is an essential component of the iLO management portfolio that provides continuous, proactive health monitoring of HPE servers. Learn more at <http://www.hpe.com/servers/ahs>.

Active Health System Viewer

Use the Active Health System Viewer, a web-based portal, to easily read AHS logs and speed problem resolution with HPE self-repair recommendations, to learn more visit: <http://www.hpe.com/servers/ahsv>.



Optional Features

Smart Update

Keep your servers up to date with the HPE Smart Update solution by using Smart Update Manager (SUM) to optimize the firmware and driver updates of the Service Pack for ProLiant (SPP).

Learn more at <https://www.hpe.com/us/en/servers/smart-update.html>.

iLO Amplifier Pack

Designed for large enterprise and service provider environments with hundreds of HPE servers, the iLO Amplifier Pack is a free, downloadable open virtual application (OVA) that delivers the power to discover, inventory and update Gen8, Gen9, Gen10 and Gen10 Plus HPE servers at unmatched speed and scale. Use with an iLO Advanced License to unlock full capabilities.

Learn more at <http://www.hpe.com/servers/iLOamplifierpack>.

HPE iLO Mobile Application

Enables the ability to access, deploy, and manage your server anytime from anywhere from select smartphones and mobile devices. For additional information please visit: <http://www.hpe.com/info/ilo/mobileapp>.

RESTful Interface Tool

RESTful Interface tool (iLOREST) is a single scripting tool to provision using iLO RESTful API to discover and deploy servers at scale. Learn more at <http://www.hpe.com/info/resttool>.

Scripting Tools

Provision one to many servers using your own scripts to discover and deploy with Scripting Tool (STK) for Windows and Linux or Scripting Tools for Windows PowerShell.

Learn more at <http://www.hpe.com/servers/powershell>.

HPE OneView Standard

HPE OneView Standard can be used for inventory, health monitoring, alerting, and reporting without additional fees. It can monitor multiple HPE server generations. The user interface is similar to the HPE OneView Advanced version, but the software-defined functionality is not available. Learn more at <http://www.hpe.com/info/oneview>.

HPE Systems Insight Manager (HPE SIM)

Ideal for environments already using HPE SIM, it allows you to monitor the health of your HPE ProLiant Servers and HPE Integrity Servers. Also provides you with basic support for non-HPE servers. HPE SIM also integrates with Smart Update Manager to provide quick and seamless firmware updates. Learn more at <http://www.hpe.com/info/hpesim>.

Security

- UEFI Secure Boot and Secure Start support
- Immutable Silicon Root of Trust
- FIPS 140-3 validation (iLO 6 certification in progress)
- Common Criteria certification (iLO 6 certification in progress)
- Configurable for PCI DSS compliance
- Advanced Encryption Standard (AES) and Triple Data Encryption Standard (3DES) on browser
- Support for Commercial National Security Algorithms (CNSA)
- iLO Security Modes
- Granular control over iLO interfaces
- Smart card (PIV/CAC) and Kerberos based 2-factor Authentication
- Tamper-free updates – components digitally signed and verified
- Secure Recovery – recover critical firmware to known good state on detection of compromised firmware
- Ability to rollback firmware
- Secure erase of NAND/User Data



Optional Features

- TPM 2.0 (Trusted Platform Module 2.0)
Notes: Enabling TPM 2.0 no longer requires TPM module option kit for Gen11. It is an embedded feature yet disabled for shipments to China.
- Bezel Locking Kit option
- Chassis Intrusion detection option

HPE Trusted Platform Module

Enabling HPE Trusted Platform Module (TPM) 2.0 no longer requires TPM module option kit for Gen11. It is an embedded feature yet disabled for shipments to China. TPM2.0 can also be disabled from the BIOS setting.

Notes: The TPM (Trusted Platform Module) is a microcontroller chip that can securely store artifacts used to authenticate the server platform. These artifacts can include passwords, certificates, and encryption keys.

Warranty

This product is covered by a global limited warranty and supported by HPE Services and a worldwide network of Hewlett Packard Enterprise Authorized Channel Partners resellers. Hardware diagnostic support and repair is available for three years from date of purchase. Support for software and initial setup is available for 90 days from date of purchase. Enhancements to warranty services are available through HPE Services operational services or customized service agreements. Hard drives have either a one year or three year warranty; refer to the specific hard drive QuickSpecs for details.

Notes: Server Warranty includes 3-Year Parts, 3-Year Labor, 3-Year Onsite support with next business day response. Warranty repairs may be accomplished through the use of Customer Self Repair (CSR) parts. These parts fall into two categories: 1) Mandatory CSR parts are designed for easy replacement. A travel and labor charge will result when customers decline to replace a Mandatory CSR part; 2) Optional CSR parts are also designed for easy replacement but may involve added complexity. Customers may choose to have Hewlett Packard Enterprise replace Optional CSR parts at no charge. Additional information regarding worldwide limited warranty and technical support is available at:

<https://www.hpe.com/support/ProLiantServers-Warranties>

Server Management

HPE iLO Advanced

HPE iLO Advanced licenses offer smart remote functionality without compromise, for all HPE ProLiant servers. The license includes the full integrated remote console, virtual keyboard, video, and mouse (KVM), multi-user collaboration, console record and replay, and GUI-based and scripted virtual media and virtual folders. You can also activate the enhanced security and power management functionality.

HPE OneView Advanced

HPE OneView Advanced offers a sophisticated level of automation to infrastructure management by taking a template driven approach to provisioning, updating, and integrating compute, storage, and networking infrastructure. It provides full-featured licenses which can be purchased for managing multiple HPE server generations.

To learn more visit <http://www.hpe.com/info/oneview>.

HPE InfoSight for Servers

HPE InfoSight for Servers combines the cloud-based machine learning of InfoSight with the health and performance monitoring of Active Health System (AHS) and iLO to optimize performance and predict and prevent problems. The end result is an intelligent environment that modernizes IT operations and enhances the support experience by predicting and preventing the infrastructure issues that lead to application disruptions, wasted IT staff time and missed business opportunities.

Learn more at <https://www.hpe.com/servers/infosight>

HPE Insight Cluster Management Utility (CMU)

HPE Insight Cluster Management Utility is a HyperScale management framework that includes software for the centralized provisioning, management and monitoring of nodes and infrastructure. Learn more at <http://www.hpe.com/info/cmu>.



Optional Features

Accelerator and GPGPU Information

Hewlett Packard Enterprise supports various accelerators on select HPE ProLiant servers to support different workloads. The accelerators enable seamless integration of GPU computing with HPE ProLiant servers for high-performance computing, large data center graphics, deep learning and virtual desktop deployments. These accelerators deliver all of the standard benefits of GPU computing while enabling maximum reliability and tight integration with system monitoring and management tools such as HPE Insight Cluster Management Utility.

Rack and Power Infrastructure

The story may end with servers, but it starts with the foundation that makes compute go – and business grow. We've reinvented our entire portfolio of rack and power products to make IT infrastructure more secure, more practical, and more efficient. In other words, we've created a stronger, smarter, and simpler infrastructure to help you get the most out of your IT equipment. As an industry leader, Hewlett Packard Enterprise is uniquely positioned to address the key concerns of power, cooling, cable management and system access.

HPE G2 Advanced and Enterprise Racks are perfect for the server room or today's modern data center with enhanced airflow and thermal management, flexible cable management, and a 10 year Warranty to support higher density computing.

HPE G2 PDUs offer reliable power in flexible form factors that operate at temperatures up to 60°, include color-coded outlets and load segments and a low-profile design for optimal access to the rack and support for dense rack environments.

HPE Uninterruptible Power Systems are cost-effective power protection for any type workload. Some UPSs include options for remote management and extended runtime modules so your critical dense data center is covered in power outages.

HPE KVM Solutions include a console and switches designed to work with your server and IT equipment reliably. We've got a cost-effective KVM switch for your first rack and multiple connection IP switches with remote management and security capabilities to keep your data center rack up and running.

Learn more about HPE Racks, KVM, PDUs and UPSs at [HPE Rack and Power Infrastructure](#).

One Config Simple (SCE)

SCE is a guided self-service tool to help sales and non-technical people provide customers with initial configurations in 3 to 5 minutes. You may then send the configuration on for configuration help, or use in your existing ordering processes. If you require "custom" rack configuration or configuration for products not available in SCE, please contact Hewlett Packard Enterprise Customer Business Center or an Authorized Partner for assistance <https://h22174.www2.hpe.com/SimplifiedConfig/Welcome#>



Service and Support

HPE Services

No matter where you are in your digital transformation journey, you can count on HPE Services to deliver the expertise you need when, where and how you need it. From planning to deployment, ongoing operations and beyond, our experts can help you realize your digital ambitions.

<https://www.hpe.com/services>

Consulting Services

No matter where you are in your journey to hybrid cloud, experts can help you map out your next steps. From determining what workloads should live where, to handling governance and compliance, to managing costs, our experts can help you optimize your operations.

<https://www.hpe.com/services/consulting>

HPE Managed Services

HPE runs your IT operations, providing services that monitor, operate, and optimize your infrastructure and applications, delivered consistently and globally to give you unified control and let you focus on innovation.

[HPE Managed Services | HPE](#)

Operational services

Optimize your entire IT environment and drive innovation. Manage day-to-day IT operational tasks while freeing up valuable time and resources. Meet service-level targets and business objectives with features designed to drive better business outcomes.

<https://www.hpe.com/services/operational>

HPE Complete Care Service

HPE Complete Care Service is a modular, edge-to-cloud IT environment service designed to help optimize your entire IT environment and achieve agreed upon IT outcomes and business goals through a personalized experience. All delivered by an assigned team of HPE Services experts. HPE Complete Care Service provides:

- A complete coverage approach -- edge to cloud
- An assigned HPE team
- Modular and fully personalized engagement
- Enhanced Incident Management experience with priority access
- Digitally enabled and AI driven customer experience

<https://www.hpe.com/services/complecare>

HPE Tech Care Service

HPE Tech Care Service is the operational support service experience for HPE products. The service goes beyond traditional support by providing access to product specific experts, an AI driven digital experience, and general technical guidance to not only reduce risk but constantly search for ways to do things better. HPE Tech Care Service delivers a customer-centric, AI driven, and digitally enabled customer experience to move your business forward. HPE Tech Care Service is available in three response levels. Basic, which provides 9x5 business hour availability and a 2-hour response time. Essential which provides a 15-minute response time 24x7 for most enterprise level customers, and Critical which includes a 6-hour repair commitment where available and outage management response for severity 1 incidents.

<https://www.hpe.com/services/techcare>



Service and Support

HPE Lifecycle Services

HPE Lifecycle Services provide a variety of options to help maintain your HPE systems and solutions at all stages of the product lifecycle. A few popular examples include:

- Lifecycle Install and Startup Services: Various levels for physical installation and power on, remote access setup, installation and startup, and enhanced installation services with the operating system.
- HPE Firmware Update Analysis Service: Recommendations for firmware revision levels for selected HPE products, taking into account the relevant revision dependencies within your IT environment.
- HPE Firmware Update Implementation Service: Implementation of firmware updates for selected HPE server, storage, and solution products, taking into account the relevant revision dependencies within your IT environment.
- Implementation assistance services: Highly trained technical service specialists to assist you with a variety of activities, ranging from design, implementation, and platform deployment to consolidation, migration, project management, and onsite technical forums.
- HPE Service Credits: Access to prepaid services for flexibility to choose from a variety of specialized service activities, including assessments, performance maintenance reviews, firmware management, professional services, and operational best practices.

Notes: To review the list of Lifecycle Services available for your product go to:

<https://www.hpe.com/services/lifecycle>

For a list of the most frequently purchased services using service credits, see the [HPE Service Credits Menu](#)

Other Related Services from HPE Services:

HPE Education Services

Training and certification designed for IT and business professionals across all industries. Broad catalogue of course offerings to expand skills and proficiencies in topics ranging from cloud and cybersecurity to AI and DevOps. Create learning paths to expand proficiency in a specific subject. Schedule training in a way that works best for your business with flexible continuous learning options.

<https://www.hpe.com/services/training>

Defective Media Retention

An option available with HPE Complete Care Service and HPE Tech Care Service and applies only to Disk or eligible SSD/Flash Drives replaced by HPE due to malfunction.

Consult your HPE Sales Representative or Authorized Channel Partner of choice for any additional questions and services options.

Parts and Materials

HPE will provide HPE-supported replacement parts and materials necessary to maintain the covered hardware product in operating condition, including parts and materials for available and recommended engineering improvements.

Parts and components that have reached their maximum supported lifetime and/or the maximum usage limitations as set forth in the manufacturer's operating manual, product QuickSpecs, or the technical product data sheet will not be provided, repaired, or replaced as part of these services.

How to Purchase Services

Services are sold by Hewlett Packard Enterprise and Hewlett Packard Enterprise Authorized Service Partners:

- Services for customers purchasing from HPE or an enterprise reseller are quoted using HPE order configuration tools.
- Customers purchasing from a commercial reseller can find services at <https://ssc.hpe.com/portal/site/ssc/>



Service and Support

AI Powered and Digitally Enabled Support Experience

Achieve faster time to resolution with access to product-specific resources and expertise through a digital and data driven customer experience.

Sign into the HPE Support Center experience, featuring streamlined self-serve case creation and management capabilities with inline knowledge recommendations. You will also find personalized task alerts and powerful troubleshooting support through an intelligent virtual agent with seamless transition when needed to a live support agent.

<https://support.hpe.com/hpesc/public/home/signin>

Consume IT On Your Terms

HPE GreenLake edge-to-cloud platform brings the cloud experience directly to your apps and data wherever they are—the edge, colocations, or your data center. It delivers cloud services for on-premises IT infrastructure specifically tailored to your most demanding workloads. With a pay-per-use, scalable, point-and-click self-service experience that is managed for you, HPE GreenLake edge-to-cloud platform accelerates digital transformation in a distributed, edge-to-cloud world.

- Get faster time to market.
- Save on TCO, align costs to business.
- Scale quickly, meet unpredictable demand.
- Simplify IT operations across your data centers and clouds.

To learn more about HPE Services, please contact your Hewlett Packard Enterprise sales representative or Hewlett Packard Enterprise Authorized Channel Partner. Contact information for a representative in your area can be found at "Contact HPE"

<https://www.hpe.com/us/en/contact-hpe.html>

For more information

<http://www.hpe.com/services>



Pre-Configured Models

Pre-Configured models ship with the configurations below.

- Pre-Configured models ship with the configurations below. Options can be selected from the Core or Additional options section of this QuickSpecs.
- Hewlett Packard Enterprise does not allow factory integration of options into pre-configured models. Any additional options purchased will not be shipped inside the server.
- Network Choice models do not include embedded LOM.

| | | | |
|-----------------------------|--|---|---|
| SKU Number | P51930-B21 P51930-291 P51930-421 | P51931-B21 P51931-291 P51931-421 P51931-AA1 | P51932-B21 P51932-291 P51932-421 |
| Model Name | HPE ProLiant DL360 Gen11 4410Y 2.0GHz 12-core 1P 32GB-R MR408i-o NC 8SFF 800W PS Server | P51931-B21, P51931-291 & P51931-421: HPE ProLiant DL360 Gen11 5416S 2.0GHz 16-core 1P 32GB-R NC 8SFF 800W PS Server P51931-AA1: HPE ProLiant DL360 Gen11 5416S 2.0GHz 16-core 1P 32GB-R MR408i-o NC 8SFF 800W PS Server | HPE ProLiant DL360 Gen11 5415+ 2.9GHz 8-core 1P 32GB-R NC 8SFF 800W PS Server |
| Chassis | HPE ProLiant DL360 Gen11 8SFF NC Configure-to-order Server | | |
| Processor | 4410Y (12 core, 2.0 GHz, 150W) | 5416S (16 core, 2.0 GHz, 150W) | 5415+ (8 core, 2.9 GHz, 150W) |
| Number of Processors | One with standard heatsink | | |
| Memory | 32 GB (1x32 GB , 4800 MT/s) Notes: Runs at 4000 MT/s due to processor limitation. | 32 GB (1x32 GB , 4800 MT/s) Notes: Runs at 4400 MT/s due to processor limitation. | 32 GB (1x32 GB , 4800 MT/s) Notes: Runs at 4400 MT/s due to processor limitation. |
| Network Controller | Broadcom BCM5719 Ethernet 1Gb 4-port BASE-T OCP3 Adapter for HPE Notes: No embedded networking | Broadcom BCM57416 Ethernet 10Gb 2-port BASE-T Adapter for HPE Notes: No embedded networking | Broadcom BCM57416 Ethernet 10Gb 2-port BASE-T Adapter for HPE Notes: No embedded networking |
| Storage Controller | HPE MR408i-o Gen11 x8 Lanes 4GB Cache OCP SPDM Storage Controller | P51931-B21, P51931-291 & P51931-421: Embedded Intel® VROC SATA for HPE ProLiant Gen11, with 14 SATA ports (10-ports accessible); Choice of HPE modular Smart Array and PCIe plug-in controller P51931-AA1: HPE MR408i-o Gen11 x8 Lanes 4GB Cache OCP SPDM Storage Controller | Embedded Intel® VROC SATA for HPE ProLiant Gen11, with 14 SATA ports (10-ports accessible); Choice of HPE modular Smart Array and PCIe plug-in controller |
| Included Hard Drives | None ship standard, 8 SFF supported | | |
| Internal Storage | 8 SFF NC CTO Server (upgradeable to 8+2 SFF front) | | |



Pre-Configured Models

| | | | |
|----------------------|---|---|---|
| Optical Drive | Optional - HPE 9.5mm SATA DVD-RW Optical Drive, HPE Mobile USB DVD-RW Drive. | | |
| Power Supply | P51930-B21 & P51930-291: 1x HPE 800W Flex Slot Platinum Hot Plug Low Halogen Power Supply Kit | P51931-B21, P51931-291 & P51931-AA1: 1x HPE 800W Flex Slot Platinum Hot Plug Low Halogen Power Supply Kit | P51932-B21 & P51932-291: 1x HPE 800W Flex Slot Platinum Hot Plug Low Halogen Power Supply Kit |
| | P51930-421: 1x HPE 800W Flex Slot Titanium Hot Plug Low Halogen Power Supply Kit | P51931-421: 1x HPE 800W Flex Slot Titanium Hot Plug Low Halogen Power Supply Kit | P51932-421: 1x HPE 800W Flex Slot Titanium Hot Plug Low Halogen Power Supply Kit |
| Fans | 5x Standard Fans | | |
| Management | HPE iLO 6 | | |
| Rail Kit | HPE ProLiant DL3XX Gen11 Easy Install Rail 3 Kit Notes: Server does not support shelf mounted rail kits ("L" brackets). | | |
| Security | TPM (Trusted Platform Module) | P51931-B21, P51931-291 & P51931-421: TPM (Trusted Platform Module) | TPM (Trusted Platform Module) |
| | | P51931-AA1: TPM disabled for shipments to China | |
| Form Factor | 1U Rack | | |
| Warranty | Server warranty includes 3-year parts, 3-year labor, 3-year onsite support with next business day response. | | |



Pre-Configured Models

| | | | |
|-----------------------------|---|---|---|
| SKU Number | P60734-B21 P60734-291 P60734-421 | P60735-B21 P60735-291 P60735-421 | P54866-AA1 |
| Model Name | HPE ProLiant DL360 Gen11 4416+ 2.0GHz 20-core 1P 32GB-R MR408i-o NC 8SFF 800W PS Server | HPE ProLiant DL360 Gen11 4410Y 2.0GHz 12-core 1P 32GB-R NC 4LFF 800W PS Server | HPE ProLiant DL360 Gen11 4410Y 2.0GHz 12-core 1P 32GB-R MR408i-o NC 8SFF 800W PS Server |
| Chassis | HPE ProLiant DL360 Gen11 8SFF NC Configure-to-order Server | HPE ProLiant DL360 Gen11 4LFF NC Configure-to-order Server | HPE ProLiant DL360 Gen11 8SFF NC Configure-to-order Server |
| Processor | 4416+ (20 core, 2.0 GHz, 165W) | 4410Y (12 core, 2.0 GHz, 150W) | 4410Y (12 core, 2.0 GHz, 150W) |
| Number of Processors | One with standard heatsink | | |
| Memory | 32 GB (1x32 GB, 4800 MT/s) Notes: Runs at 4000 MT/s due to processor limitation. | | |
| Network Controller | Broadcom BCM57416 Ethernet 10Gb 2-port BASE-T Adapter for HPE Notes: No embedded networking | Broadcom BCM5719 Ethernet 1Gb 4-port BASE-T OCP3 Adapter for HPE Notes: No embedded networking | Broadcom BCM5719 Ethernet 1Gb 4-port BASE-T OCP3 Adapter for HPE Notes: No embedded networking |
| Storage Controller | HPE MR408i-o Gen11 x8 Lanes 4GB Cache OCP SPDM Storage Controller | Embedded Intel® VROC SATA for HPE ProLiant Gen11, with 14 SATA ports (10-ports accessible); Choice of HPE modular Smart Array and PCIe plug-in controller | HPE MR408i-o Gen11 x8 Lanes 4GB Cache OCP SPDM Storage Controller |
| Included Hard Drives | None ship standard, 8 SFF supported | None ship standard, 4 LFF supported | None ship standard, 8 SFF supported |
| Internal Storage | 8 SFF NC CTO Server (upgradeable to 8+2 SFF front) | 4 LFF NC CTO Server (upgradeable to 4 LFF front) | 8 SFF NC CTO Server (upgradeable to 8+2 SFF front) |
| Optical Drive | Optional - HPE 9.5mm SATA DVD-RW Optical Drive, HPE Mobile USB DVD-RW Drive. | | |
| Power Supply | P60734-B21 & P60734-291: 1x HPE 800W Flex Slot Platinum Hot Plug Low Halogen Power Supply Kit P60734-421: 1x HPE 800W Flex Slot Titanium Hot Plug Low Halogen Power Supply Kit | P60735-B21 & P60735-291: 1x HPE 800W Flex Slot Platinum Hot Plug Low Halogen Power Supply Kit P60735-421: 1x HPE 800W Flex Slot Titanium Hot Plug Low Halogen Power Supply Kit | 1x HPE 800W Flex Slot Platinum Hot Plug Low Halogen Power Supply Kit |
| Fans | 5x Standard Fans | | |
| Management | HPE iLO 6 | | |
| Rail Kit | HPE ProLiant DL3XX Gen11 Easy Install Rail 3 Kit Notes: Server does not support shelf mounted rail kits ("L" brackets). | HPE Easy Install Rail 5 Kit Notes: Server does not support shelf mounted rail kits ("L" brackets). | HPE ProLiant DL3XX Gen11 Easy Install Rail 3 Kit Notes: Server does not support shelf mounted rail kits ("L" brackets). |
| Security | TPM (Trusted Platform Module) | TPM (Trusted Platform Module) | TPM disabled for shipments to China |

Pre-Configured Models

| | |
|--------------------|---|
| Form Factor | 1U Rack |
| Warranty | Server warranty includes 3-year parts, 3-year labor, 3-year onsite support with next business day response. |



Pre-Configured Models

| | | | |
|-----------------------------|---|---|---|
| SKU Number | P70540-291 P70540-421 | P70541-291 P70541-421 | P70542-291 P70542-421 |
| Model Name | HPE ProLiant DL360 Gen11 4509Y 2.6GHz 8-core 1P 32GB-R MR408i- o NC 8SFF 1000W PS Server | HPE ProLiant DL360 Gen11 5515+ 3.2GHz 8-core 1P 32GB-R MR408i- o NC 8SFF 1000W PS Server | HPE ProLiant DL360 Gen11 4514Y 2.0GHz 8-core 1P 32GB-R MR408i- o NC 8SFF 1000W PS Server |
| Chassis | HPE ProLiant DL360 Gen11 8SFF NC Configure-to-order Server | | |
| Processor | 4509Y (8 core, 2.6 GHz, 125W) | 5515+ (8 core, 3.2 GHz, 165W) | 4514Y (16 core, 2.0 GHz, 150W) |
| Number of Processors | One with standard heatsink | | |
| Memory | 32 GB (1x32 GB , 5600 MT/s) Notes: Runs at 4400 MT/s due to processor limitation. | 32 GB (1x32 GB , 5600 MT/s) Notes: Runs at 4800 MT/s due to processor limitation. | 32 GB (1x32 GB , 5600 MT/s) Notes: Runs at 4400 MT/s due to processor limitation. |
| Network Controller | Broadcom BCM5719 Ethernet 1Gb 4-port BASE-T OCP3 Adapter for HPE Notes: No embedded networking | Broadcom BCM57416 Ethernet 10Gb 2-port BASE-T Adapter for HPE Notes: No embedded networking | Broadcom BCM57416 Ethernet 10Gb 2-port BASE-T Adapter for HPE Notes: No embedded networking |
| Storage Controller | HPE MR408i-o Gen11 x8 Lanes 4GB Cache OCP SPDM Storage Controller | | |
| Included Hard Drives | None ship standard, 8 SFF supported | | |
| Internal Storage | 8 SFF NC CTO Server (upgradeable to 8+2 SFF front) | | |
| Optical Drive | Optional - HPE 9.5mm SATA DVD-RW Optical Drive, HPE Mobile USB DVD-RW Drive. | | |
| Power Supply | 1x HPE 1000W Flex Slot Titanium Hot Plug Power Supply Kit | | |
| Fans | 5x Standard Fans | | |
| Management | HPE iLO 6 | | |
| Rail Kit | HPE ProLiant DL3XX Gen11 Easy Install Rail 3 Kit Notes: Server does not support shelf mounted rail kits ("L" brackets). | | |
| Security | TPM (Trusted Platform Module) | | |
| Form Factor | 1U Rack | | |
| Warranty | Server warranty includes 3-year parts, 3-year labor, 3-year onsite support with next business day response. | | |



Pre-Configured Models

| | | |
|-----------------------------|---|--|
| SKU Number | P70577-D61 | P70578-D61 |
| Model Name | HPE ProLiant DL360 Gen11 6430 2.1GHz 32-core 1P 32GB-R NC 8SFF 800W PS Server | HPE ProLiant DL360 Gen11 6442Y 2.6GHz 24-core 1P 32GB-R NC 8SFF 800W PS Server |
| Chassis | HPE ProLiant DL360 Gen11 8SFF NC Configure-to-order Server | |
| Processor | 6430 (32 core, 2.1 GHz, 270W) | 6442Y (24 core, 2.6 GHz, 225W) |
| Number of Processors | One with high performance heatsink | |
| Memory | 32 GB (1x32 GB , 4800 MT/s) Notes: Runs at 4400 MT/s due to processor limitation. | 32 GB (1x32 GB , 4800 MT/s) |
| Network Controller | Broadcom BCM57412 Ethernet 10Gb 2-port SFP+ OCP3 Adapter for HPE Notes: No embedded networking | Broadcom BCM57414 Ethernet 10/25Gb 2-port SFP28 OCP3 Adapter for HPE Notes: No embedded networking |
| Storage Controller | Embedded Intel® VROC SATA for HPE ProLiant Gen11, with 14 SATA ports (10-ports accessible); Choice of HPE modular Smart Array and PCIe plug-in controller | |
| Included Hard Drives | None ship standard, 8 SFF supported | |
| Internal Storage | 8 SFF NC CTO Server (upgradeable to 8+2 SFF front) | |
| Optical Drive | Optional - HPE 9.5mm SATA DVD-RW Optical Drive, HPE Mobile USB DVD-RW Drive. | |
| Power Supply | 2x HPE 800W Flex Slot Platinum Hot Plug Low Halogen Power Supply Kit | |
| Fans | 7x High Performance Fans | |
| Management | HPE iLO 6 | |
| Rail Kit | HPE ProLiant DL3XX Gen11 Easy Install Rail 3 Kit Notes: Server does not support shelf mounted rail kits ("L" brackets). | |
| Security | TPM (Trusted Platform Module) | |
| Form Factor | 1U Rack | |
| Warranty | Server warranty includes 3-year parts, 3-year labor, 3-year onsite support with next business day response. | |



Pre-Configured Models

| Smart Choice Models | | |
|-----------------------------|---|--|
| SKU Number | P71673-425 | P71676-005 |
| Model Name | HPE ProLiant DL360 Gen11 4510 2.4GHz 12c 1P 64GB-R 8SFF MR408i-o 2x960GB SSD 2x1000W PS EMEA Server | HPE ProLiant DL360 Gen11 4509Y 2.6GHz 8-core 1P 64GB-R MR408i-o NC 8SFF 1000W RPS AMS Server |
| Chassis | HPE ProLiant DL360 Gen11 8SFF NC Configure-to-order Server | |
| Processor | 4510 (12 core, 2.4 GHz, 150W) | 4509Y (8 core, 2.6 GHz, 125W) |
| Number of Processors | One with standard heatsink | |
| Memory | 64 GB (2x32 GB, 5600 MT/s) Notes: Runs at 4400 MT/s due to processor limitation. | |
| Network Controller | Broadcom BCM5719 Ethernet 1Gb 4-port BASE-T OCP3 Adapter for HPE Notes: No embedded networking | |
| Storage Controller | HPE MR408i-o Gen11 x8 Lanes 4GB Cache OCP SPDM Storage Controller | |
| Included Hard Drives | 2x 960GB SATA SSD | 2x 480GB SATA SSD |
| Internal Storage | 8 SFF NC CTO Server (upgradeable to 8+2 SFF front) | |
| Optical Drive | Optional - HPE 9.5mm SATA DVD-RW Optical Drive, HPE Mobile USB DVD-RW Drive | |
| Power Supply | 2x HPE 1000W Flex Slot Titanium Hot Plug Power Supply Kit | |
| Fans | 5x Standard Fans | |
| Management | HPE iLO 6 | |
| Rail Kit | HPE ProLiant DL3XX Gen11 Easy Install Rail 3 Kit Notes: Server does not support shelf mounted rail kits ("L" brackets). | |
| Security | TPM (Trusted Platform Module) | |
| Form Factor | 1U Rack | |
| Warranty | Server warranty includes 3-year parts, 3-year labor, 3-year onsite support with next business day response. | |



Pre-Configured Models

| Smart Choice Models | | |
|-----------------------------|---|--|
| SKU Number | P71678-005 | P71686-005 |
| Model Name | HPE ProLiant DL360 Gen11 6526Y 2.8GHz 16-core 1P 128GB-R NS204i-u NC 8SFF 1000W RPS AMS Server | HPE ProLiant DL360 Gen11 4510 2.4GHz 12-core 1P 64GB-R MR408i-o NC 8SFF 1000W RPS AMS Server |
| Chassis | HPE ProLiant DL360 Gen11 8SFF NC Configure-to-order Server | |
| Processor | 6526Y (16 core, 2.8 GHz, 195W) | 4510 (12 core, 2.4 GHz, 150W) |
| Number of Processors | One with high performance heatsink | One with standard heatsink |
| Memory | 128 GB (4x32 GB , 5600 MT/s) Notes: Runs at 5200 MT/s due to processor limitation. | 64 GB (2x32 GB , 5600 MT/s) Notes: Runs at 4400 MT/s due to processor limitation. |
| Network Controller | Broadcom BCM5719 Ethernet 1Gb 4-port BASE-T OCP3 Adapter for HPE Notes: No embedded networking | |
| Storage Controller | HPE NS204i-u Gen11 NVMe Hot Plug Boot Optimized Storage Device | HPE MR408i-o Gen11 x8 Lanes 4GB Cache OCP SPDM Storage Controller |
| Included Hard Drives | None ship standard, 8 SFF supported | 2x 480GB SATA SSD |
| Internal Storage | 8 SFF NC CTO Server (upgradeable to 8+2 SFF front) | |
| Optical Drive | Optional - HPE 9.5mm SATA DVD-RW Optical Drive, HPE Mobile USB DVD-RW Drive | |
| Power Supply | 2x HPE 1000W Flex Slot Titanium Hot Plug Power Supply Kit | |
| Fans | 7x High Performance Fans | 5x Standard Fans |
| Management | HPE iLO 6 | |
| Rail Kit | HPE ProLiant DL3XX Gen11 Easy Install Rail 3 Kit Notes: Server does not support shelf mounted rail kits ("L" brackets). | |
| Security | TPM (Trusted Platform Module) | |
| Form Factor | 1U Rack | |
| Warranty | Server warranty includes 3-year parts, 3-year labor, 3-year onsite support with next business day response. | |

Country Code Key

- -B21 = Worldwide
- -005 = HPE Smart Choice for US and Canada
- -291 = Japan
- -421 = Europe, the Middle East and Africa
- -425 = HPE Smart Choice for DACH (Germany, Switzerland, Austria), France, UKI (Great Britain, Ireland, Scotland, Wales)
- -AA1 = China
- -D61 = India



Pre-Configured Models

HPE Smart Choice purchase program

- HPE Smart Choice purchase program is designed to make it easier to do business with HPE by offering fully configured solutions.
- Order popular configs in a single SKU.
- Get immediate purchase price in minutes.
- Get fast, predictable shipping.

Notes: - The -B21 SKU is to be ordered in countries in Americas and Asia-Pacific (other than Japan or PRC).
- The -421 SKU is to be ordered in European Union countries for Lot 9 compliance.



Configuration Information

Smart Templates from HPE

HPE is releasing new Smart Template technology in the One Config Advanced (OCA) configurator. These Templates represent the CTO equivalents of the top-selling BTO configurations. They are intended to provide simple starting points to assist you in easily creating and customizing your desired Server solutions. HPE Servers that have Platform Templates, developed by HPE Product Managers, will have a separate tab in the HPE OCA configurator.

Workload Solutions Templates from HPE

The Workload Solutions Templates build on the Smart Templates technology to easily develop working configurations of the most compelling Workload Solutions. The templates complement the Reference Builds developed by HPE. Workload Solutions templates preconfigure some of the key architecture decisions and make it easier for Sellers to get started and complete a differentiated server solution for your customer's specific workload.

Mainstream SKUs

HPE launched the Mainstream SKU initiative as a market-driven approach to Demand Steering. It is a simplified portfolio of our top selling options that meet the current and future market trends. HPE has committed to provide a more predictable and faster experience for these options. Mainstream SKUs enjoy higher safety stock levels and have higher fulfillment service levels than non-Mainstream SKUs. Mainstream orders are fulfilled +30% faster than non-Mainstream orders, have fewer shortages and better recovery dates. This platform has Mainstream SKUs in the options portfolio, and is eligible for the improved Mainstream experience. Mainstream SKUs are designated with a Mainstream symbol in our configurators.

Mainstream Configurations

HPE is using the new Smart Templates technology to present Mainstream configurations. All the options in a Mainstream configuration are pre-selected Mainstream SKUs to optimize the performance, predictability and fulfillment experience. Check the Template section in our configurators for eligible Mainstream configurations.

This section lists some of the steps required to configure a Factory Integrated Model.

To ensure valid configurations are ordered, Hewlett Packard Enterprise recommends the use of an HPE approved configurator. Contact your local sales representative for information on configurable product offerings and requirements.

- Factory Integrated Models must start with a CTO Server.
- FIO indicates that this option is only available as a factory installable option.
- Some options may not be integrated at the factory. Contact your local sales representative for additional information

Step 1: Base Configuration (choose one of the following configurable models)

CTO Server models do not include embedded LOM. To enable networking capability please select a validated alternative NIC - OCP or PCIe- from the Core Options section.

| CTO Server | HPE DL360 Gen11 4LFF NC CTO Server | HPE DL360 Gen11 8SFF NC CTO Server | HPE DL360 Gen11 20EDSFF NC CTO Server |
|---------------------------------|--|------------------------------------|---|
| SKU Number | P52498-B21 | P52499-B21 | P52500-B21 |
| TAA SKU* | P52498-B21#GTA | P52499-B21#GTA | P52500-B21#GTA |
| HPE Trusted Supply Chain | Optional: HPE Trusted Supply Chain for HPE ProLiant (P36394-B21) | | |
| Processor | Not included as standard. Optional: Qty 1 or 2 (2 processors must be selected in 20EDSFF NC CTO Server) | | |
| DIMM Slots | 32-DIMM slots | | |
| DIMM Blanks | DIMM Blanks are required, embedded and shipped as default in all CTO Servers | | |
| Storage Controller | Choice of Intel® VROC Software RAID capable; Choice of HPE ProLiant external hardware controller Choice of HPE ProLiant Gen11 MR and SR PCIe and OCP plug-in Controller, | | Choice of Intel® VROC Software RAID capable Choice of HPE ProLiant external hardware controller **Internal Hardware Controller support is not available |



Configuration Information

| | | | |
|------------------------------|---|--|---|
| PCIe Slots | Up to 3 Slots PCIe 5.0 (Slot 1, 2 & 3) One standard primary/butterfly riser: 2 slots as Slot 1 & Slot 2 (1 x16 FH / 1 x16 LP) and 4 x8 front NVMe connectors Optional: Slot 3 in 1 x16 FH or LP slot All PCIe Slots are in design with up to 9.5" length | | |
| OCP3.0 Slots | PCIe 5.0: 2 slots (1x16/ 1x16) ¹ | | PCIe 5.0: 2 slots (1x8/ 1x8) ² |
| Drive Cage – included | 4 LFF – default backplane. 12G x1 SAS with Low Profile (LP) carrier support. | 8SFF – Optional backplanes. in choice of: - 24G x1 NVMe/SAS U.3, or - 24G x4 NVMe/SAS U.3, TriMode supported, must be selected if internal drives needed. Basic carrier (BC) support. (PCIe4.0 storage) | 20EDSFF – default backplane. 32G x4 NVMe, with E3.s 1T carrier (EC1) support. (PCIe5.0 storage) |
| Network Controller | <p>"BCM 5719 1Gb 4p BASE-T OCP Adptr" to be defaulted in the configurator at OCP Slot 21. Customer is allowed to remove and select other cards (PCIe or OCP) from Networking, InfiniBand, Smart IO (HW) or Storage Offload category.</p> <p>Choice of OCP3.0 or stand-up cards for primary networking selection plus additional/optional stand-up networking adapters.</p> <p>Notes:</p> <ul style="list-style-type: none"> – No embedded networking from motherboard. – ¹In 1 Processor configuration, "CPU1 to OCP2 x8 Enablement Kit" will be selected as default as OCP NIC is pre-selected at OCP Slot 2, to be defaulted in the configurator if 1 Processor is selected. Customer is allowed to remove if OCP NIC is not selected but need to be replaced by a PCIe standup NIC. Meanwhile, the "CPU1 to OCP2 x8 Enablement Kit" will be removed. – ¹"CPU2 to OCP2 x8 Enablement Kit" or "CPU2 to OCP2 x16 Enablement Kit" must be selected if OCP NIC is selected in 2 Processors configuration. – "CPU2 to OCP2 x8 Enablement Kit" to be defaulted in the configurator if 2 Processors are selected. User should be allowed to remove "CPU2 to OCP2 x8 Enablement Kit" and should be forced select "CPU2 to OCP2 x16 Enablement Kit" if OCP NIC is selected. Customer is allowed to remove if OCP NIC is not selected but need to be replaced by a PCIe standup NIC. Meanwhile, the "CPU2 to OCP2 x8 Enablement Kit" will be removed. – ²In 20EDSFF CTO model, either no OCP enablement kit or "CPU2 to OCP2 x8 Enablement Kit" can be selected from the limited PCIe5.0 electrical lanes from OCP Slot 1 (x8) and OCP Slot2 (x8). | | |
| Fans | <p>Choice of</p> <ul style="list-style-type: none"> • 5 Standard Fans for one processor below 185W TDP • Additional 2 Standard Fans for 2nd Processor below 185W TDP • 7 High Performance Fan for processors 186W – 270W TDP • 7 High Performance Fan for processors 300W TDP in one socket configuration • Closed-loop Liquid Cooling (CL LC) Heat Sink Fan Bundle FIO Kit (7 fans included) for one or two processors above 271W TDP • Direct Liquid Cooling (DLC) Heatsink and High-Performance Fan FIO solution, for all processors in 2P Configuration <p>Notes: If Closed-loop Liquid Cooling HeatSink Fan FIO Bundle Kit is selected, there is default a FAN Kit bundled. Then any Fans (Standard Fan Kit or High Performane Fan Kit) cannot be selected. In the CL LC bundle Kit, with full speed the Fan Kit runs at 210W, which requires 42W additional power than DL360 Gen11 Performance Fan Kit.</p> | | |

Configuration Information

| | |
|---------------------|--|
| Management | HPE iLO with Intelligent Provisioning (standard) HPE GreenLake for Compute Ops Management (a 3-year subscription included) Optional: iLO Advanced and OneView |
| Video Output | Rear: 1 VGA Optional: <ul style="list-style-type: none"> 1 Front Display Port (standalone in 8SFF; USB2.0+ Display Port bundle kit in 4LFF), 1 Rear Serial Port |
| USB | Front: 1 USB 3.2 Gen1 + iLO service port Rear: 2 USB 3.2 Gen1 Internal: 1 USB 3.2 Gen1 + 1 USB2.0 Optional: 1 Front USB 2.0 |
| Security | Trusted Platform Module (TPM) 2.0. It is an embedded feature and can be disabled in the BIOS setting. Notes: Disabled for shipments to China |
| Rail Kit | Optional Easy Install rails and CMA <ul style="list-style-type: none"> HPE Easy Install Rail 3 Kit (P52341-B21) is available for 8SFF CTO Server if Rack is selected HPE Easy Install Rail 5 Kit (P52343-B21) is available for 4LFF & 20EDSFF CTO Server if Rail kit is selected DL300 Gen10 Plus 1U CMA (P26489-B21) as optional. (If CMA is selected, then Rail Kit must be selected) Notes: Server does not support shelf mounted rail kits (“L” brackets). |
| Form Factor | 1U Rack |
| Warranty | 3-year parts, 3-year labor, 3-year onsite support with next business day response. |

Notes:

- All DL360 Gen11 CTO Server models require the selection of Processor, Memory and Power Supply. Backplane to be further selected in 8SFF CTO Server.
- HPE Trusted Supply Chain (P36394-B21) is an optional security upgrade intended for agencies and regulated industries needing enhanced security and compliance needs. Applying this option to a DL360 Gen11 CTO server ensures it is built in the USA in a secured facility by vetted HPE personnel assigned to the manufacturing processes. A multitude of checkpoints/inspections for malicious microcode and counterfeit parts are performed throughout the server build, and additional safeguards are put in place against cyber-exploits throughout the server lifecycle. The HPE ProLiant DL360 Gen11 is re-branded as a HPE ProLiant DL360T Gen11 to denote the HPE Trusted Supply Chain security enhancements. The DL360T is Trade Agreement Act (TAA) compliant. See “HPE Security” section within this document for more detail and learn more at <http://www.hpe.com/security>
- *HPE offers multiple Trade Agreement Act (TAA) compliant configurations to meet the needs of US Federal Government customers. These products are either manufactured or substantially transformed in a designated country. TAA compliance is only provided when HPE options are included as part of factory integrated orders (CTO).
- All CTO servers are Energy Star 4.0 compliant, exclude configuration with GPU.
- Supported Rail kit to be defaulted for CTO Model in the configurator. But customer can deselect the Rail kit if the CTO Model is selected without Rack (Standalone server).
- If EDSFF CTO Model is selected, then Performance Heatsink or Closed Loop Liquid Cooling Heatsink Fan Bundle FIO Kit or Direct Liquid Cooling Module must be selected.



Configuration Information

Step 2: Choose Core Options

- Mixing of 2 different processor models is not supported.
 - CTO server will populate necessary heatsink and fan kits per system thermal requirements and processor models
 - DIMM Blanks are pre-selected as default, minimum Q'ty 1 of memory need to be selected in 1 Processor configuration, and minimum Q'ty 2 of memory need to be selected in 2 Processor configuration
 - Choice of hardware storage controllers (internal hardware controllers are not available for EDSFF CTO Server) and OS Boot Device
 - 4LFF backplane and cage are pre-selected, in 4LFF CTO Server; choice of backplanes in 8SFF CTO server; 20EDSFF backplane and cage are pre-selected, in 20EDSFF CTO server.
 - Choice of ODD drive (not available for 20EDSFF CTO server) and storage device
 - Factory Configuration Settings
 - Choice of riser card for PCIe5.0 slots enablement
 - Choice of OS Boot Device
 - Choice of Networking solution
 - Choice of Power and Cooling solution
 - Choice of Security Options
 - Software as a Service Management : Choice of HPE GreenLake for Compute Ops Management and Choice of HPE OneView
-

Step 3: Choose Additional Options

- Choice of Accessories
 - Choice of Intel® Virtual RAID on CPU Premium & Standard FIO Software for HPE
 - Choice of GPGPU
 - Choice of Embedded Management
 - Choice of Racks
 - Choice of PDUs
 - Choice of UPS
 - Choice of USB and SD Options (if available)
 - Choice of Enterprise Mainstream Flash Media Kits for Memory Cards
-



Core Options

Choose Core Options

- Mixing of 2 different processor models is not supported.
- CTO server will populate necessary fan kits per system thermal requirements and processor models, minimum as 5 standard fans. Dual processor configurations require 7 fans, either standard or high performance.
- If Processor Wattage is less than or equal to 185W, then "Standard Heatsink" and "Standard Fan" must be selected. Configurator to default "Standard Heatsink" and "Standard Fan". But Customer is allowed to remove and select "Performance Heatsink or DLC Module" and "Performance Fan" upon Processor selection.
- If Processor Wattage is more than 185W and less than or equal to 270W, then "Performance Heatsink (P48095-B21)" and "Performance Fan (P48908-B21)" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan Kit" upon Processor selection. But customer should be allowed to remove and select DLC Module and "Performance Fan" upon Processor selection.
- If Processor Wattage is more than 270W, then "Closed Loop Liquid Cooling" (P48906-B21) or "DLC Module" must be selected. Configurator to default "Closed Loop Liquid Cooling" upon Processor selection and allow the customer to remove and select "DLC Module" and "Performance Fan".
- In 300W processor one socket configuration, the air cooling with Performance Heatsinks & Performance Fan Kits can be supported together. Field upgrade to two socket is not supported with air cooling solution.
- If 350W Intel Open-loop Liquid Cooling CPU (6458Q/ 8470Q) Processor is selected with any backplanes or drives (excluding NS204i-u), then DLC Module must be selected.
- If 350W Processor (excluding Intel Open-loop Liquid Cooling CPU 6458Q/ 8470Q) is selected with Closed Loop Liquid cooling, then Maximum 10x SFF NVMe drive or 20x EDSFF can be selected. Or DLC module must be selected for SFF or EDSFF deives models.
- For Fan selection impact from memory capacity, pls refer to the support matrix in Fan Kit section
- See Networking section for constrained high speed networking adapter
- For GPU selection, pls refer to the support matrix in GPU section
 - In 8SFF CTO Model, if the Graphics Option is selected with the Processor that is more than 270W, then Maximum of 8 NVMe/ SAS/ SATAdrives can be selected.
 - In EDSFF CTO Model, if the Graphics Option is selected with Processor Wattage is more than 270W, then DLC Module & Performance Fan Kit must be selected

Processor

- Please select one or two matching processors.
For example: for a single **Xeon-Platinum 8570 processor configuration select 1x P49606-B21. If dual Xeon-Platinum 8570 processor configuration, select 2x P49606-B21.**
- The required firmware for the 5th Generation Intel Xeon Processors is not compatible with the DL360 Gen11 system board shipped with the 4th Generation Intel Xeon Processors. A new server order (latest firmware system board) is required for the activation of the 5th Generation Intel Xeon Processors. The field upgrade from the 4th Generation Intel Xeon Processor to the 5th Generation is not supported.

5th Generation Intel Xeon Processors

All SKUs below ship with processors only. Adequate fans and heatsinks must be selected.
Supports "HPE DDR5 SmartMemory – Registered (RDIMM), 5600MT/s".



Core Options

5th Generation Intel Xeon-Platinum

Intel Xeon-Platinum 8593Q 2.2GHz 64-core 385W Processor for HPE

P68449-B21

Notes:

- XCC die
- Max 2
- If two processors are selected, "DLC Module" must be selected, also as Configurator default.
- If one processor is selected with "Closed-loop Liquid Cooling" in max 4LFF & 8SFF CTO Servers, keeping datacenter at or below 25C ambient temperature is required.

Intel Xeon-Platinum 8592+ 1.9GHz 64-core 350W Processor for HPE

P67089-B21

Notes:

- XCC die
- Max 2
- "Closed Loop Liquid Cooling" or "DLC Module" must be selected. Configurator to default "Closed Loop Liquid Cooling" upon Processor selection and allow to remove and select "DLC Module" with "Performance Fan Kit".
- If selected with "Closed Loop Liquid cooling", then 10x SFF NVMe or 20xEDSFF drive can be selected.

Intel Xeon-Platinum 8592V 2.0GHz 64-core 330W Processor for HPE

P67107-B21

Notes:

- XCC die
- Max 2
- "Closed Loop Liquid Cooling" or "DLC Module" must be selected. Configurator to default "Closed Loop Liquid Cooling" upon Processor selection and allow to remove and select "DLC Module" with "Performance Fan Kit".
- If selected with "Closed Loop Liquid cooling", then 10x SFF NVMe or 20xEDSFF drive can be selected.

Intel Xeon-Platinum 8581V 2.0GHz 60-core 270W Processor for HPE

P67109-B21

Notes:

- XCC die
- Max 1
- "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But allowed to remove and select DLC Module and Performance Heatsink.

Intel Xeon-Platinum 8580 2.0GHz 60-core 350W Processor for HPE

P67088-B21

Notes:

- XCC die
- Max 2
- "Closed Loop Liquid Cooling" or "DLC Module" must be selected. Configurator to default "Closed Loop Liquid Cooling" upon Processor selection and allow to remove and select "DLC Module" with "Performance Fan Kit".
- If selected with "Closed Loop Liquid cooling", then Maximum 10x SFF NVMe or 20xEDSFF drive can be selected.



Core Options

Intel Xeon-Platinum 8570 2.1GHz 56-core 350W Processor for HPE

P67087-B21

Notes:

- XCC die
- Max 2
- "Closed Loop Liquid Cooling" or "DLC Module" must be selected. Configurator to default "Closed Loop Liquid Cooling" upon Processor selection and allow to remove and select "DLC Module".
- If selected with "Closed Loop Liquid cooling", then Maximum 10x SFF NVMe or 20xEDSFF drive can be selected.

Intel Xeon-Platinum 8568Y+ 2.3GHz 48-core 350W Processor for HPE

P67086-B21

Notes:

- XCC die
- Max 2
- "Closed Loop Liquid Cooling" or "DLC Module" must be selected. Configurator to default "Closed Loop Liquid Cooling" upon Processor selection and allow to remove and select "DLC Module".
- If selected with "Closed Loop Liquid cooling", then Maximum 10x SFF NVMe or 20xEDSFF drive can be selected.

Intel Xeon-Platinum 8562Y+ 2.8GHz 32-core 300W Processor for HPE

P67085-B21

Notes:

- MCC die
- Max 2
- For 2P configuration, "Closed Loop Liquid Cooling" or "DLC Module" must be selected. Configurator to default "Closed Loop Liquid Cooling" upon Processor selection and allow to remove and select "DLC Module".
- And if selected with "Closed Loop Liquid cooling", then Maximum 10x SFF NVMe or 20xEDSFF drive can be selected.
- For 1P configuration, "Closed Loop Liquid Cooling" or "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection and allow to remove and select "Closed Loop Liquid Cooling".

Intel Xeon-Platinum 8558P 2.7GHz 48-core 350W Processor for HPE

P67108-B21

Notes:

- XCC die
- Max 2
- "Closed Loop Liquid Cooling" or "DLC Module" must be selected. Configurator to default "Closed Loop Liquid Cooling" upon Processor selection and allow to remove and select "DLC Module".
- If selected with "Closed Loop Liquid cooling", then Maximum 10x SFF NVMe or 20xEDSFF drive can be selected.

Intel Xeon-Platinum 8558 2.1GHz 48-core 330W Processor for HPE

P67097-B21

Notes:

- XCC die
- Max 2
- "Closed Loop Liquid Cooling" or "DLC Module" must be selected. Configurator to default "Closed Loop Liquid Cooling" upon Processor selection and allow to remove and select "DLC Module".
- If selected with "Closed Loop Liquid cooling", then Maximum 10x SFF NVMe or 20xEDSFF drive can be selected.



Core Options

Intel Xeon-Platinum 8558U 2.0GHz 48-core 300W Processor for HPE

P67102-B21

Notes:

- XCC die
- Max 1
- "DLC Module" must be selected, also as Configurator default.
- Or "Closed-loop Liquid Cooling" in max 4xLFF, 8xSFF NVMe & 20xEDSFF CTO Servers, keeping datacenter at or below 25C ambient temperature is required.

5th Generation Intel Xeon-Gold 6

Intel Xeon-Gold 6558Q 3.2GHz 32-core 350W Processor for HPE

P67098-B21

Notes:

- MCC die
- Max 2
- If two processors are selected, "DLC Module" must be selected, also as Configurator default. Or "Closed-loop Liquid Cooling" can be selected only if no drive cage and backplane in SFF CTO Server.
- If one processor is selected with Closed-loop Liquid Cooling in max 4xLFF, 8xSFF NVMe & 20xEDSFF CTO Servers, keeping datacenter at or below 25C ambient temperature is required.

Intel Xeon-Gold 6554S 2.2GHz 36-core 270W Processor for HPE

P67110-B21

Notes:

- XCC die
- Max 2
- "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But customer should be allowed to remove and select DLC Module and Performance Heatsink.

Intel Xeon-Gold 6548N 2.8GHz 32-core 250W Processor for HPE

P67105-B21

Notes:

- MCC die
- Max 2
- "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But customer should be allowed to remove and select DLC Module and Performance Heatsink.

Intel Xeon-Gold 6548Y+ 2.5GHz 32-core 250W Processor for HPE

P67082-B21

Notes:

- MCC die
- Max 2
- "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But customer should be allowed to remove and select DLC Module and Performance Heatsink.

Intel Xeon-Gold 6544Y 3.6GHz 16-core 270W Processor for HPE

P67084-B21

Notes:

- MCC die
- Max 2
- "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But customer should be allowed to remove and select DLC Module and Performance Heatsink.



Core Options

Intel Xeon-Gold 6542Y 2.9GHz 24-core 250W Processor for HPE

P67081-B21

Notes:

- MCC die
- Max 2
- "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But customer should be allowed to remove and select DLC Module and Performance Heatsink.

Intel Xeon-Gold 6538N 2.1GHz 32-core 205W Processor for HPE

P67104-B21

Notes:

- MCC die
- Max 2
- "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But customer should be allowed to remove and select DLC Module and Performance Heatsink.

Intel Xeon-Gold 6538Y+ 2.2GHz 32-core 225W Processor for HPE

P67096-B21

Notes:

- MCC die
- Max 2
- "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But customer should be allowed to remove and select DLC Module and Performance Heatsink.

Intel Xeon-Gold 6534 3.9GHz 8-core 195W Processor for HPE

P67083-B21

Notes:

- MCC die
- Max 2
- "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But customer should be allowed to remove and select DLC Module and Performance Heatsink.

Intel Xeon-Gold 6530 2.1GHz 32-core 270W Processor for HPE

P67095-B21

Notes:

- XCC die
- Max 2
- "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But customer should be allowed to remove and select DLC Module and Performance Heatsink.

Intel Xeon-Gold 6526Y 2.8GHz 16-core 195W Processor for HPE

P67080-B21

Notes:

- MCC die
- Max 2
- "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But customer should be allowed to remove and select DLC Module and Performance Heatsink.



Core Options

5th Generation Intel Xeon-Gold 5

Intel Xeon-Gold 5520+ 2.2GHz 28-core 205W Processor for HPE

P67094-B21

Notes:

- MCC die
- Max 2
- "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But customer should be allowed to remove and select DLC Module and Performance Heatsink.

Intel Xeon-Gold 5515+ 3.2GHz 8-core 165W Processor for HPE

P67079-B21

Notes:

- MCC die
- Max 2
- "Standard Heatsink" and "Standard Fan" must be selected. Configurator to default "Standard Heatsink" and "Standard Fan ". But Customer is allowed to remove and select "Performance Heatsink or DLC Module" and "Performance Fan" upon Processor selection.

5th Generation Intel Xeon-Silver

Intel Xeon-Silver 4516Y+ 2.2GHz 24-core 185W Processor for HPE

P67093-B21

Notes:

- MCC die
- Max 2
- "Standard Heatsink" and "Standard Fan" must be selected. Configurator to default "Standard Heatsink" and "Standard Fan ". But Customer is allowed to remove and select "Performance Heatsink or DLC Module" and "Performance Fan" upon Processor selection.

Intel Xeon-Silver 4514Y 2.0GHz 16-core 150W Processor for HPE

P67092-B21

Notes:

- MCC die
- Max 2
- "Standard Heatsink" and "Standard Fan" must be selected. Configurator to default "Standard Heatsink" and "Standard Fan ". But Customer is allowed to remove and select "Performance Heatsink or DLC Module" and "Performance Fan" upon Processor selection.

Intel Xeon-Silver 4510 2.4GHz 12-core 150W Processor for HPE

P67091-B21

Notes:

- EE LCC die
- Max 2
- "Standard Heatsink" and "Standard Fan" must be selected. Configurator to default "Standard Heatsink" and "Standard Fan ". But Customer is allowed to remove and select "Performance Heatsink or DLC Module" and "Performance Fan" upon Processor selection.
- If this Processor is selected, then 96GB 5600 Memory cannot be selected.

Intel Xeon-Silver 4509Y 2.6GHz 8-core 125W Processor for HPE

P67090-B21

Notes:

- EE LCC die
- Max 2
- "Standard Heatsink" and "Standard Fan" must be selected. Configurator to default "Standard Heatsink" and "Standard Fan ". But Customer is allowed to remove and select "Performance Heatsink or DLC Module" and "Performance Fan" upon Processor selection.
- If this Processor is selected, then 96GB 5600 Memory cannot be selected.



Core Options

5th Generation Intel Xeon-Bronze

Intel Xeon-Bronze 3508U 2.1GHz 8-core 125W Processor for HPE

P67100-B21

Notes:

- EE LCC die
- Max 1
- "Standard Heatsink" and "Standard Fan" must be selected. Configurator to default "Standard Heatsink" and "Standard Fan ". But Customer is allowed to remove and select "Performance Heatsink or DLC Module" and "Performance Fan" upon Processor selection.
- If this Processor is selected, then 96GB DDR5-5600 Memory cannot be selected.
- Supports PCIe4.0 nly

4th Generation Intel Xeon Processors

All SKUs below ship with processor only. Adequate fans and heatsinks must be selected.

Supports "HPE DDR5 SmartMemeory – Registered (RDIMM), 4800MT/s".96GB 4800 MT/s Memory cannot be selected if HBM die.

4th Generation Intel Xeon-Platinum

Intel Xeon-Platinum 9462 2.7GHz 32-core 350W Processor for HPE

P49645-B21

Notes:

- HBM die
- Max 2
- "Closed Loop Liquid Cooling" or "DLC Module" must be selected. Configurator to default "Closed Loop Liquid Cooling" upon Processor selection and allow the customer to remove and select "DLC Module" with "Performance Fan Kit".
- Microsoft Windows Server is not supported. For the rest Operating System support for HBM processor, see **HPE Servers Support & Certification Matrices**

- HBM Memory Modes support (Three modes)
 - o HBM Only (memory size equals HBM memory capacity. It only provides best performance when workloads fit into 64GB of capacity):
Exists when system memory is removed as Qty 0. HBM caches DDR (symmetric DDR population required). No support for Intel® SGX and MKTME. The BIOS setting can be refreshed as "HBM Only" after system reboot. In RBSU, the HBM Memory Mode is shown as "1LM", meaning One Level Memory.
 - o Flat Mode (memory size equals System memory Plus HBM memory. DDR memory can be added for workloads needing capacity exceed 64GB):
Default setting from factory shipment if system memory to be minimum Qty 1. HBM and DDR exposed as separate regions. A higher performance can be achieved than Cache mode. Intel® SGX and MKTME are supported in DDR region. The HBM Memory Mode is shown as "1LM", meaning One Level Memory.
 - o Cache Mode (memory size equals System memory only, as HBM memory is hidden and is functioning as a cache. Cache mode provides improved performance when workloads need above 64GB of capacity) :
No support for Intel® SGX and MKTME. In RBSU, the HBM Memory Mode is shown as "2LM", meaning Two Level Memory. When the system memory are populated, Cache Mode can be selected when the configuration meets below two requiremnets, incl. System Memory population requirement and the specific ratio of System Memory. Otherwise, will be configuraed as Flat Mode instead.
 - To meet below system memory population requirement from Intel, one socket scenario.
Also with system DIMM Qty to be only a 4, 8 or 16.



Core Options

| | iMC3 | | | | iMC2 | | | | C P U | iMC0 | | | | iMC1 | | | | HBM Mode | | | | | | | | | | | | | | | | |
|-----------|-----------------|-------|-----------------|-------|-----------------|-------|-----------------|-------|-------------|-----------------|-------|-----------------|-------|-----------------|-------|-----------------|----------|----------|------|------|------|------|------|------|------|------|------|------|------|------|------|------|------|---------------|
| | Channel 1 (7/H) | | Channel 0 (6/G) | | Channel 1 (5/F) | | Channel 0 (4/E) | | | Channel 0 (0/A) | | Channel 1 (1/B) | | Channel 0 (2/C) | | Channel 1 (3/D) | | | | | | | | | | | | | | | | | | |
| DDR5+CPS | Slot0 | Slot1 | Slot0 | Slot1 | Slot0 | Slot1 | Slot0 | Slot1 | Slot1 | Slot0 | Slot1 | Slot0 | Slot1 | Slot0 | Slot1 | Slot0 | Slot1 | | | | | | | | | | | | | | | | | |
| 0+0 (HBM) | | | | | | | | | | | | | | | | | HBM Only | | | | | | | | | | | | | | | | | |
| 1+0 | | | | | | | | | | | | | | | | | DDR5 | | | | | | | | | | | | | | | | Flat | |
| 2+0 | | | | | | | | | | | | | | | | | | DDR5 | | | | | | | | | | | | | | | | Flat |
| 4+0 | | | | | | | | | | | | | | | | | | | DDR5 | | | | | | | | | | | | | | | Flat |
| 8+0 | | | | | | | | | | | | | | | | | DDR5 | | DDR5 | | | | | | | | | | | | | | | Flat or Cache |
| 16+0 | | | | | | | | | | | | | | | | | DDR5 | DDR5 | DDR5 | DDR5 | DDR5 | DDR5 | DDR5 | DDR5 | DDR5 | DDR5 | DDR5 | DDR5 | DDR5 | DDR5 | DDR5 | DDR5 | DDR5 | Flat or Cache |

- The Ratio of “System memory “ HBM memory” is in 2:1 or 64:1. Meaning the memory population in “one socket” needs to be:
 1. DDR5 16GB with min Qty 8 (System memory 16GB x8 : HBM memory 64GB = 2:1), or
 2. DDR5 32GB with min Qty 4 (System memory 32GB x4 : HBM memory 64GB = 2:1). or
 3. DDR5 256GB with Qty 16 (System memory 256GB x 16 : HBM memory 64GB = 64:1)
 4. Duplication of DDR5 system memory is required in two sockets configuration

– HPE ProLiant DL3XX Gen11 Cache Mode for High-Bandwidth Memory FIO Trigger System Setting (P65886-B21) is available for customer self-configuration which allows Cache Mode to be default setting, if the system memory population meets above requirement.

Intel Xeon-Platinum 8490H 1.9GHz 60-core 350W Processor for HPE

P49630-B21

Notes:

- XCC die
- Max 2
- "Closed Loop Liquid Cooling" or "DLC Module" must be selected. Configurator to default "Closed Loop Liquid Cooling" upon Processor selection and allow the customer to remove and select "DLC Module" with “Performance Fan Kit”.
- If selected with Closed Loop Liquid cooling , then Maximum 10x SFF NVMe or 20xEDSFF drive can be selected.

Intel Xeon-Platinum 8480+ 2.0GHz 56-core 350W Processor for HPE

P49607-B21

Notes:

- XCC die
- Max 2
- If Processor Wattage is more than 270W, then "Closed Loop Liquid Cooling" or "DLC Module" must be selected. Configurator to default "Closed Loop Liquid Cooling" upon Processor selection and allow the customer to remove and select "DLC Module".
- EDSFF CTO Model: If 350W CPU is selected with Closed Loop Liquid cooling, then 256GB DIMM cannot be selected.

Intel Xeon-Platinum 8470 2.0GHz 52-core 350W Processor for HPE

P49606-B21

Notes:

- XCC die
- Max 2
- "Closed Loop Liquid Cooling" or "DLC Module" must be selected. Configurator to default "Closed Loop Liquid Cooling" upon Processor selection and allow the customer to remove and select "DLC Module" with “Performance Fan Kit”.
- With Closed Loop Liquid cooling , then Maximum 8 quantity of SFF drive can be selected.
- EDSFF CTO Model: If 350W CPU is selected with Closed Loop Liquid cooling, then 256GB DIMM cannot be selected.



Core Options

Intel Xeon-Platinum 8470Q 2.1GHz 52-core 350W Processor for HPE

P49609-B21

Notes:

- XCC die
- Max 2
- "Closed Loop Liquid Cooling" or "DLC Module" must be selected. Configurator to default "Closed Loop Liquid Cooling" upon Processor selection and allow the customer to remove and select "DLC Module" with "Performance Fan Kit".
- If Open-loop Liquid Cooling processor 8470Q is selected with Closed-loop Liquid Cooling, then backplane and drive cannot be selected in the 8SFF CTO server. Only NS204i-u can be selected.
- If 8470Q Processor is selected with Closed-loop Liquid Cooling, then 4LFF and 20EDSFF CTO Server cannot be selected as backplane is embedded as default. Or DLC module with Performance Fan Kit must be selected.
- If selected with InfiniBand HDR/EN 200Gb 1p/2p QSFP56 OCP 3 Adapter, then NVMe drive cannot be selected.

Intel Xeon-Platinum 8470N 1.7GHz 52-core 300W Processor for HPE

P49649-B21

Notes:

- XCC die
- Max 2
- Requires Closed-loop LC Heat Sink Fan Bundle FIO Kit must be selected (P48906-B21) in two-socket configurations.
- In one socket configuration, Performance Heatsinks & Performance Fan Kits can be supported. Field upgrade to two socket is not supported with air cooling solution.
- With two socket configuration, then "Closed Loop Liquid Cooling" or "DLC Module" must be selected. Configurator to default "Closed Loop Liquid Cooling" upon Processor selection and allow the customer to remove and select "DLC Module" with "Performance Fan Kit".

Intel Xeon-Platinum 8468 2.1GHz 48-core 350W Processor for HPE

P49605-B21

Notes:

- XCC die
- Max 2
- "Closed Loop Liquid Cooling" or "DLC Module" must be selected. Configurator to default "Closed Loop Liquid Cooling" upon Processor selection and allow the customer to remove and select "DLC Module" with "Performance Fan Kit".
- With Closed Loop Liquid cooling , then Maximum 8 quantity of SFF drive can be selected.
- EDSFF CTO Model: If 350W CPU is selected with Closed Loop Liquid cooling, then 256GB DIMM cannot be selected.

Intel Xeon-Platinum 8468V 2.4GHz 48-core 330W Processor for HPE

P49631-B21

Notes:

- XCC die
- Max 2
- Requires Closed-loop LC Heat Sink Fan Bundle FIO Kit must be selected (P48906-B21).
- "Closed Loop Liquid Cooling" or "DLC Module" must be selected. Configurator to default "Closed Loop Liquid Cooling" upon Processor selection and allow the customer to remove and select "DLC Module" with "Performance Fan Kit".



Core Options

Intel Xeon-Platinum 8462Y+ 2.8GHz 32-core 300W Processor for HPE

P49603-B21

Notes:

- MCC die
- Max 2
- With two socket configuration, then “Closed Loop Liquid Cooling” or “DLC Module” must be selected in two-socket configuration. Configurator to default "Closed Loop Liquid Cooling" upon Processor selection and allow the customer to remove and select "DLC Module" with “Performance Fan Kit”.
- In one socket configuration, the air cooling with Performance Heatsinks & Performance Fan Kits can be supported. Field upgrade to two socket is not supported with air cooling solution.

Intel Xeon-Platinum 8460Y+ 2.0GHz 40-core 300W Processor for HPE

P49604-B21

Notes:

- XCC die
- Max 2
- With two socket configuration, then “Closed Loop Liquid Cooling” or “DLC Module” must be selected in two-socket configuration. Configurator to default “Closed Loop Liquid Cooling” upon Processor selection and allow the customer to remove and select “DLC Module” with “Performance Fan Kit”.
- In one socket configuration, the air cooling with Performance Heatsinks & Performance Fan Kits can be supported. Field upgrade to two socket is not supported with air cooling solution.

Intel Xeon-Platinum 8458P 2.7GHz 44-core 350W Processor for HPE

P49632-B21

Notes:

- XCC die
- Max 2
- Requires Closed-loop LC Heat Sink Fan Bundle FIO Kit must be selected (P48906-B21).
- With Closed Loop Liquid cooling , then Maximum 8 quantity of SFF drive can be selected.
- "Closed Loop Liquid Cooling" or "DLC Module" must be selected. Configurator to default "Closed Loop Liquid Cooling" upon Processor selection and allow the customer to remove and select "DLC Module" with “Performance Fan Kit”.
- EDSFF CTO Model: If 350W CPU is selected with Closed Loop Liquid cooling, then 256GB DIMM cannot be selected.

Intel Xeon-Platinum 8452Y 2.0GHz 36-core 300W Processor for HPE

P49616-B21

Notes:

- XCC die
- Max 2
- Requires Closed-loop LC Heat Sink Fan Bundle FIO Kit must be selected (P48906-B21) in two-socket configuration.
- With two socket configuration, then "Closed Loop Liquid Cooling" or "DLC Module" must be selected. Configurator to default "Closed Loop Liquid Cooling" upon Processor selection and allow the customer to remove and select "DLC Module" with “Performance Fan Kit”.
- In one socket configuration, the air cooling with Performance Heatsinks & Performance Fan Kits can be supported. Field upgrade to two socket is not supported with air cooling solution.

Intel Xeon-Platinum 8444H 2.9GHz 16-core 270W Processor for HPE

P49625-B21

Notes:

- XCC die
- Max 2
- "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But customer should be allowed to remove and select DLC Module and Performance Heatsink.



Core Options

4th Generation Intel Xeon-Gold 6

Notes: All SKUs below ship with processor only. Adequate fans and heatsinks must be selected.

Intel Xeon-Gold 6458Q 3.1GHz 32-core 350W Processor for HPE

P49608-B21

Notes:

- MCC die
- Max 2
- "Closed Loop Liquid Cooling" or "DLC Module" must be selected. Configurator to default "Closed Loop Liquid Cooling" upon Processor selection and allow the customer to remove and select "DLC Module" with "Performance Fan Kit".
- If Open-loop Liquid Cooling processor 6458Q is selected with Closed-loop Liquid Cooling, then backplane and drive cannot be selected in the 8SFF CTO server. Only NS204i-u can be selected.
- With Closed-loop Liquid Cooling, then 4LFF and 20EDSFF CTO Server cannot be selected as backplane is embedded as default, or DLC Module with Performance Fan Kit must be selected.
- If selected with InfiniBand HDR/EN 200Gb 1p/2p QSFP56 OCP 3 Adapter, then NVMe drive cannot be selected.

Intel Xeon-Gold 6454S 2.2GHz 32-core 270W Processor for HPE

P49654-B21

Notes:

- XCC die
- Max 2
- "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But customer should be allowed to remove and select DLC Module and Performance Heatsink.

Intel Xeon-Gold 6448Y 2.1GHz 32-core 225W Processor for HPE

P49600-B21

Notes:

- MCC die
- Max 2.
- "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But customer should be allowed to remove and select DLC Module and Performance Heatsink.

Intel Xeon-Gold 6448H 2.4GHz 32-core 250W Processor for HPE

P49622-B21

Notes:

- MCC die
- Max 2.
- "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But customer should be allowed to remove and select DLC Module and Performance Heatsink.

Intel Xeon-Gold 6444Y 3.6GHz 16-core 270W Processor for HPE

P49602-B21

Notes:

- MCC die
- Max 2
- "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But customer should be allowed to remove and select DLC Module and Performance Heatsink.



Core Options

Intel Xeon-Gold 6442Y 2.6GHz 24-core 225W Processor for HPE P49599-B21

Notes:

- MCC die
- Max 2
- "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But customer should be allowed to remove and select DLC Module and Performance Heatsink.

Intel Xeon-Gold 6438Y+ 2.0GHz 32-core 205W Processor for HPE P49615-B21

Notes:

- MCC die
- Max 2
- "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But customer should be allowed to remove and select DLC Module and Performance Heatsink.

Intel Xeon-Gold 6438N 2.0GHz 32-core 205W Processor for HPE P49638-B21

Notes:

- MCC die
- Max 2
- "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But customer should be allowed to remove and select DLC Module and Performance Heatsink.

Intel Xeon-Gold 6434 3.7GHz 8-core 195W Processor for HPE P49601-B21

Notes:

- MCC die
- Max 2
- "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But customer should be allowed to remove and select DLC Module and Performance Heatsink.

Intel Xeon-Gold 6430 2.1GHz 32-core 270W Processor for HPE P49614-B21

Notes:

- XCC die
- Max 2
- "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But customer should be allowed to remove and select DLC Module and Performance Heatsink.

Intel Xeon-Gold 6426Y 2.5GHz 16-core 185W Processor for HPE P49598-B21

Notes:

- MCC die
- Max 2
- "Standard Heatsink" and "Standard Fan" must be selected. Configurator to default "Standard Heatsink" and "Standard Fan ". But Customer is allowed to remove and select "Performance Heatsink or DLC Module" and "Performance Fan" upon Processor selection.

Intel Xeon-Gold 6421N 1.8GHz 32-core 185W Processor for HPE P49641-B21

Notes:

- MCC die
- Max 1
- "Standard Heatsink" and "Standard Fan" must be selected. Configurator to default "Standard Heatsink" and "Standard Fan ". But Customer is allowed to remove and select "Performance Heatsink or DLC Module" and "Performance Fan" upon Processor selection.



Core Options

Intel Xeon-Gold 6418H 2.1GHz 24-core 185W Processor for HPE

P49621-B21

Notes:

- MCC die
- Max 2
- "Standard Heatsink" and "Standard Fan" must be selected. Configurator to default "Standard Heatsink" and "Standard Fan ". But Customer is allowed to remove and select "Performance Heatsink or DLC Module" and "Performance Fan" upon Processor selection.

Intel Xeon-Gold 6416H 2.2GHz 18-core 165W Processor for HPE

P49620-B21

Notes:

- MCC die
- Max 2
- "Standard Heatsink" and "Standard Fan" must be selected. Configurator to default "Standard Heatsink" and "Standard Fan ". But Customer is allowed to remove and select "Performance Heatsink or DLC Module" and "Performance Fan" upon Processor selection.

Intel Xeon-Gold 6414U 2.0GHz 32-core 250W Processor for HPE

P49619-B21

Notes:

- XCC die
- Max 1
- "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But customer should be allowed to remove and select DLC Module and Performance Heatsink.

4th Generation Intel Xeon-Gold 5

Intel Xeon-Gold 5420+ 2.0GHz 28-core 205W Processor for HPE

P49613-B21

Notes:

- MCC die
- Max 2
- "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But customer should be allowed to remove and select DLC Module and Performance Heatsink.

Intel Xeon-Gold 5418Y 2.0GHz 24-core 185W Processor for HPE

P49612-B21

Notes:

- MCC die
- Max 2
- "Standard Heatsink" and "Standard Fan" must be selected. Configurator to default "Standard Heatsink" and "Standard Fan ". But Customer is allowed to remove and select "Performance Heatsink or DLC Module" and "Performance Fan" upon Processor selection.

Intel Xeon-Gold 5418N 1.8GHz 24-core 165W Processor for HPE

P49640-B21

Notes:

- MCC die
- Max 2
- "Standard Heatsink" and "Standard Fan" must be selected. Configurator to default "Standard Heatsink" and "Standard Fan ". But Customer is allowed to remove and select "Performance Heatsink or DLC Module" and "Performance Fan" upon Processor selection.



Core Options

Intel Xeon-Gold 5416S 2.0GHz 16-core 150W Processor for HPE

P49653-B21

Notes:

- MCC die
- Max 2
- "Standard Heatsink" and "Standard Fan" must be selected. Configurator to default "Standard Heatsink" and "Standard Fan ". But Customer is allowed to remove and select "Performance Heatsink or DLC Module" and "Performance Fan" upon Processor selection.

Intel Xeon-Gold 5415+ 2.9GHz 8-core 150W Processor for HPE

P49597-B21

Notes:

- MCC die
- Max 2
- "Standard Heatsink" and "Standard Fan" must be selected. Configurator to default "Standard Heatsink" and "Standard Fan ". But Customer is allowed to remove and select "Performance Heatsink or DLC Module" and "Performance Fan" upon Processor selection.

Intel Xeon-Gold 5411N 1.9GHz 24-core 165W Processor for HPE

P49639-B21

Notes:

- MCC die
- Max 1
- "Standard Heatsink" and "Standard Fan" must be selected. Configurator to default "Standard Heatsink" and "Standard Fan ". But Customer is allowed to remove and select "Performance Heatsink or DLC Module" and "Performance Fan" upon Processor selection.

4th Generation Intel Xeon-Silver

Intel Xeon-Silver 4416+ 2.0GHz 20-core 165W Processor for HPE

P49611-B21

Notes:

- MCC die
- Max 2
- "Standard Heatsink" and "Standard Fan" must be selected. Configurator to default "Standard Heatsink" and "Standard Fan ". But Customer is allowed to remove and select "Performance Heatsink or DLC Module" and "Performance Fan" upon Processor selection.

Intel Xeon-Silver 4410Y 2.0GHz 12-core 150W Processor for HPE

P49610-B21

Notes:

- MCC die
- Max 2
- "Standard Heatsink" and "Standard Fan" must be selected. Configurator to default "Standard Heatsink" and "Standard Fan ". But Customer is allowed to remove and select "Performance Heatsink or DLC Module" and "Performance Fan" upon Processor selection.

4th Generation Intel Xeon-Bronze

Intel Xeon-Bronze 3408U 1.8GHz 8-core 125W Processor for HPE

P49617-B21

Notes:

- MCC die
- Max 1
- "Standard Heatsink" and "Standard Fan" must be selected. Configurator to default "Standard Heatsink" and "Standard Fan ". But Customer is allowed to remove and select "Performance Heatsink or DLC Module" and "Performance Fan" upon Processor selection.
- If 500W Power supply is selected, then Processor Wattage that is equal to or less than 125W must be selected.
- Supports PCIe4.0 only



Core Options

Heatsinks (incl. Liquid Cooling module)

For more details, please refer to the support matrix in Power and Cooling solutions (Additional Option section)

HPE ProLiant DL360 Gen11 Cold Plate Module FIO Kit from External NS204i-u P62026-B21

HPE ProLiant DL3XX Gen11 Cold Plate Module FIO Kit from PCIe P62029-B21

Notes:

Configuration with thermal consideration

- If Performance Heatsink or DLC Module is selected, then Performance Fan must be selected and vice versa.
- If DLC Module is selected, then "HPE ProLiant Direct Liquid Cooling 450mm Female-male Connection Quick Disconnect Tube Set FIO Kit (P62046-B21)" must be selected. (See Power and Cooling solutions).
- If Processor Wattage is more than 185W and less than or equal to 270W, then "Performance Heatsink" and "Performance Fan" must be selected. Configurator to default "Performance Heatsink" and "Performance Fan" upon Processor selection. But customer should be allowed to remove and select DLC Module and Performance Heatsink.
- If Processor Wattage is more than 270W, then "Closed Loop Liquid Cooling" or "DLC Module" must be selected. Configurator to default "Closed Loop Liquid Cooling" upon Processor selection and allow the customer to remove and select "DLC Module".
- For one socket processor only configuration at 300W, Performance Heatsink & Performance Fan Kit can be supported together.
- only configuration at 300W, Performance Heatsink & Performance Fan Kit can be supported together.
- Max 1 of Liquid cooling can be selected from the below: "Closed Loop Liquid Cooling", or "DLC CPM from external NS204i-u cage" or "DLC CPM from PCIe Slot".
- If NVMe/ SAS4 is selected, then Performance Heatsink or Closed Loop Liquid cooling Heatsink or DLC Module must be selected.
- If Networking/ InfiniBand that is 100G or more, then Performance Heatsink or Closed Loop Liquid cooling Heatsink or DLC Module must be selected.
- If 256GB DIMM is selected, then Performance Heatsink or Closed Loop Liquid cooling or DLC Module must be selected.
- If external NS204i-u OS Boot Device is selected, then Performance Heatsink or Closed Loop Liquid cooling or DLC Module must be selected.
- "NS204i-u Cage DLC Module" contains 2 Cold Plate Module and 1 Quick Disconnect Module.
- If "NS204i-u Cage DLC Module" is selected,
 - "HPE DL360 Gen11 NS204i-u Rear Cbl Kit" cannot be selected.
 - "Secondary FH Riser" cannot be selected.
- "PCIe DLC Module" contains 2 Cold Plate Module and 1 Quick Disconnect Module.
- If "PCIe DLC Module" is selected, then
 - either "Secondary LP Riser" must be selected or "Secondary FH Riser" needs to be selected. PCIe Slot 2 is still available for external NS204i-u OS Boot device, or available for other HH PCIe adapters, when the "SecondaryLP Riser" is selected for the "PCIe DLC Module" installation. Yet PCIe slot# 3 cannot be used. This must be considered for all PCIe card selection.

HPE DLC Infrastructure

- HPE ProLiant DL3XX Gen11 Direct Liquid Cooling (DLC) solution requires at least one liquid cooling infrastructure items as follows: HPE Rack in 800mmx1200mm (options listed below), Rack Manifold, CDU, Primary Hose Kit and Secondary Hose Kit in order to function. Without above rack infrastructure to be selected, an unbuildable configuration will be triggered in this order.
 - DLC Rack options
 - Rack 42U 800mm x 1200mm Ent G2 (applicable for DL3XX Gen11 DLC)
 - Rack 48U 800mm x 1200mm Ent G2 (applicable for DL3XX Gen11 DLC)



Core Options

- The DLC Rack Infrastructure setting is relatively complex, and needs to be conducted by HPE Service with a complete enablement of DLC Rack solution. Major factors impact the DLC Rack Infrastructure setting are listed below.
 - o The connectivity of server to manifold
 - o The DLC rack capability (liquid supply temperature, flow rate in each loop and CDU capability)
 - o The CDU parameter setting (liquid type, server units in rack, and any mixing servers)
- If customer has ordered from HPE previously and already has this basic infrastructure on site, pls get unbuildable exception approval from ProLiant Product Management Team. We can ship a standalone unit as an upgrade as exception, without this infrastructure the server DLC solution will not function.
- If customer selects “PCIe DLC Module” or “NS204i-u Cage DLC Module” which is a Direct Liquid Cooled solution (DLC) then
 - o Either DLC Solution is supported with specific Racks only. (as mentioned above)
 - o Or server is ordered as Standalone (without any HPE Rack), then “DL360 Gen11 DLC support requires liquid cooling infrastructure items as follows: HPE Rack, Rack Manifold, CDU, Primary Hose Kit and Secondary Hose Kit in order to function. If customer already has the infrastructure to support DLC on site, then server can be shipped as a standalone unit as an upgrade. Server will not function without the infrastructure for DLC

HPE ProLiant DL360 Gen11 Closed-loop Liquid Cooling Heat Sink Fan FIO Bundle Kit

P48906-B21

- **[HPE ProLiant Gen11 Closed-Loop Liquid Cooling Heat Sink FAQs](#)**
- **[Document - HPE ProLiant and X86 Servers and Options | HPE Support](#)**

Notes: Usage

- Closed-Loop Liquid Cooling Heat Sink is subject to maximum usage limitation as 5 years of operation
- The HPE DL360 Gen11 Closed-loop Liquid Cooling Heat Sink Fan FIO Bundle kit contains paired (2) cold plates (1 per CPU) each with a pump, Tubes, (7) 4028 fans and a radiator. The LC Heat Sink option is designed to cool down the processor effectively using cooled inlet air. It would benefit to the Processor temperature yet the internal radiator would increase the flow resistance and reduce the airflow to downstream components inside the server
- If Processor Wattage is more than 270W, then LC Heat Sink Kit must be selected. This applies to all processor SKUs for DL360 Gen11 including High Bandwidth Memory (HBM) processors.
- One processor configuration can be supported without filed upgrade to the 2nd processor, and support up to two processors
- If Closed-loop Liquid Cooling HeatSink Fan FIO Bundle Kit is selected, then any Fans (Standard Fan Kit or High Performance Fan Kit) cannot be selected.
- If Liquid Cooling HeatSink Fan FIO Bundle Kit is selected, then “Standard heat Sink” or "High Perf Heat Sink" cannot be selected.
- Max 1 of Liquid cooling bundle kit can be selected from the below:
 - o Closed Loop Liquid Cooling
 - o DLC Module from NS204i-u Cage
 - o DLC Module from PCIe slot

Configuration with thermal consideration

- If Closed Loop Liquid cooling is selected with specific high speed Networking/ InfiniBand, then EDSFF or SFF NVMe drive cannot be selected.
- If Closed Loop Liquid Cooling is selected with 256GB DIMM and Rear NS204i-u, then Maximum NVMe drive limit will be reduced from 10 to 4.



Core Options

- EDSFF CTO Model: If 350W CPU is selected with Closed Loop Liquid cooling, then 256GB DIMM cannot be selected.
- EDSFF Model: If 256GB DIMM and Rear NS204i-u are selected, then DLC Module must be selected.
- For 8SFF CTO Model: If “HPE IB NDR 1p OSFP MCX75310AAS Adptr” is selected with Closed Loop Liquid cooling, then Maximum of 8 NVMe can be selected.
- For EDSFF CTO Model: If “HPE IB NDR200 1p OSFP MCX75310AAS Adptr” is selected with Closed Loop Liquid cooling, then EDSFF drives cannot be selected.
- For 8SFF CTO Model: If the Nvidia Graphics Option is selected with Closed Loop Liquid cooling, then Maximum 8 quantity of NVMe/ SAS/ SATA drives can be selected.
- EDSFF CTO Model: If the Nvidia Graphics Option is selected with Closed Loop Liquid cooling, then EDSFF drives cannot be selected.

Design details

- The HPE DL360 Gen11 Closed-loop Liquid Cooling Heat Sink Fan FIO Bundle kit is designed as Factory Installation only & is not designated as a Customer Self-Repair (CSR) part to prevent damage to CPUs when customer is conducting the field upgrade on the Liquid Cooling modular itself or CPUs.
- The cooling liquid used in the liquid cooling heatsink is a mixture of purified water and ethylene with additional additives for corrosion resistance. The cooling liquid is not corrosive for human body, but to avoid the risk of connection or damages in a longer term, it is recommended to use hand protection in the form of chemically resistant gloves and to wash hands with plenty of water after contact. Be sure to avoid any eye contact. If eye contact occurs accidentally, immediately flush eye with plenty of water or seek for medical attention of any discomfort persists.
- There is no leak detection capability, yet the pumps inside of the system are redundant. If a pump or any of the components inside the solution fail, the CPU temperature or internal server temperature may increase leading to a iLO alert message.

HPE Warranty

- The HPE DL360 Gen11 Closed-loop Liquid Cooling Heat Sink Fan FIO Bundle kit is offered with Standard (3/3/3) Warranty support along with the server. Customers are able to purchase extended support for years (4) and (5).
- This Closed-loop Liquid Cooling Solution is subject to a maximum usage (operational) limitation not to exceed (5) years and required to be replaced when this time limit has been reached. Parts and components that Hewlett Packard Enterprise determines have surpassed the standard (3) years warranty* will not be provided, repaired, or replaced under warranty coverage. Contact your local HPE sales representative for additional information.

In addition:

*Or to the extended (4) or (5) years if warranty contract purchased, and subject to the maximum usage (operation) limitation of (5) years. For more details, please refer to the warranty terms for other options available from Hewlett Packard Enterprise.

HPE Tech Care

- Tech Care contract supersedes the warranty terms
- The (6) and (7) year support is provided as a duration choice under Tech Care instead of Warranty. Customer buys Tech Care with equal or greater than 4 years, covers the (6) and (7) -year scenario.
 - o Customers with <= (3) year Tech care or Warranty-only
 - If the CL LC Heat Sink fails <= (3) year, HPE will have to provide service to customers.



Core Options

- If the CL LC Heat Sink fails > (3) yearr, the cost is on the customer and te service & material expense will be charged if the customer calls
- o Customers with >= (4) year Tech care, or current Tech Care support contract of any kind
 - If the CL LC Heat Sink fails inside the Tech care period, HPE will provide service & cover the expense for customers, except the stated limitation on Maximum Usage Limitation.
 - If the Heat Sink works properly and reaches (5) year of usage time, customer can call the HPE representative for the replacement starting from (6) months piror to the (5) year.
 - If customer decides to ignore the maximum usage limitation notification and without contact HPE, customer will ow the liability & expense associated.



HPE ProLiant DL3XX/560 Gen11 High Performance Heat Sink Kit

P48905-B21

Notes:

- Quantity of Processor and Quantity of Heatsink must match.
- If Processor Wattage is more than 185W and less than or equal to 270W, then "Performance Heatsink" and "Performance Fan" must be selected.
- In 300Watt processor one socket configuration, the air cooling with Performance Heatsinks & Performance Fan Kits can be supported. Field upgrade to two socket is not supported with air cooling solution. If Performance Heatsink is selected, then Standard fan cannot be selected, and Performance Fan Kit must be selected
- For processors below 185W TDP, customers are able to configure with High Performane Heatsinks & Performnace Fan Kit in HPE One-Configuration-Advanced. First, deselect the Standard Heatsink and Standard Fan, then reselect High Performance Heatsink and Performance Fan Kit.
- If Closed-loop Liquid Cooling HeatSink or DLC module is selected, then "High Perf Heat Sink" cannot be selected.
- If Performance Heatsink or DLC Module is selected, then Performance Fan must be selected and vice versa.
- If NVMe/ SAS4 is selected, then Performance Heatsink or Closed Loop Liquid cooling Heatsink or DLC Module must be selected.
- If Closed Loop Liquid Cooling is selected with 256GB DIMM or Internal NS204i-u or rear NS204i-u, then Maximum EDSFF drive limit will be reduced from 20 to 10.
- If Networking/ InfiniBand that is 100G or more, then Performance Heatsink or Closed Loop Liquid cooling Heatsink or DLC Module must be selected.
- If 256GB DIMM is selected, then Performance Heatsink or Closed Loop Liquid cooling or DLC Module must be selected.
- If NS204i-u is selected, then Performance Heatsink or Closed Loop Liquid cooling or DLC Module must be selected.



Core Options

HPE ProLiant DL3X0 Gen11 1U Standard Heat Sink Kit

P48904-B21

Notes:

- Quantity of Processor and Quantity of Heatsink must match.
- If Processor Wattage is less than or equal to 185W, then "Standard Heatsink" and "Standard Fan" must be selected. Configurator to default "Standard Heatsink" and "Standard Fan ". But Customer is allowed to remove and select "Performance Heatsink or DLC Module" and "Performance Fan" upon Processor selection.
- If Standard Heatsink is selected, then Performance fan cannot be selected.
- If Standard Heatsink is selected in 1 processor configuration, then "HPE DL3X0 Gen11 1U Stnd Fan Kit" must be selected.
- If Standard Heatsink is selected in 2 processor configuration, then both "HPE DL3X0 Gen11 1U Stnd Fan Kit" and "HPE DL3X0 Gen11 1U 2P Std Fan Kit" must be selected.

Memory

Please select one or more memory DIMMs from below.

For new Gen11 memory population rule whitepaper and optimal memory performance guidelines, please go to:

<http://www.hpe.com/docs/memory-population-rules>

Server memory population rules for HPE Gen11 servers with 4th Gen Intel Xeon Scalable processors

For more information, please see the [HPE DDR5 Smart Memory QuickSpecs](#)

Notes:

- The maximum memory speed and capacity is a function of the memory type, memory configuration, and processor model.
- Quantity of memory DIMMs selected per socket must be 1, 2, 4, 6, 8, 12 or 16.
- x8 and x4 cannot be mixed.
- 3DS and non-3DS Memory cannot be mixed.
- Mixing of different Rank Memory is not allowed if less than 16 quantity of Memory is selected for 1 Processor configuration.
- Mixing of different Rank Memory is not allowed if less than 32 quantity of Memory is selected for 2 Processor configuration.
- If different Rank Memory are mixed, then quantity of each Memory part number must be same.
- If Memory Fault Tolerance is selected then only x4 memory options can be selected.
- 4800 MT/s memory SKUs offer a transfer rate of 4800 MT/s at 1 DIMM per channel and 4400 MT/s at 2 DIMMs per channel.
- The maximum memory speed is a function of the memory type, memory configuration, and processor model.
- Long boot time may be introduced because of DDR5 initialization takes much longer than last generation DDR4, as an industry impact. HPE ProLiant server boot times will go through multiple reboots during POST for default restore.
- A longer lead-time would be expected in high capacity DIMMs depending on vender supply.

Registered DIMMs DDR5 (RDIMMs)

DDR5-5600 (applies to the 5th Generation Intel® Xeon® Scalable Processors)

HPE 16GB (1x16GB) Single Rank x8 DDR5-5600 CAS-46-45-45 EC8 Registered Smart Memory Kit

P64705-B21

HPE 32GB (1x32GB) Dual Rank x8 DDR5-5600 CAS-46-45-45 EC8 Registered Smart Memory Kit

P64706-B21

HPE 64GB (1x64GB) Dual Rank x4 DDR5-5600 CAS-46-45-45 EC8 Registered Smart Memory Kit

P64707-B21

Notes:

If Memory Fault Tolerance is selected then only x4 memory options can be selected.



Core Options

HPE 96GB (1x96GB) Dual Rank x4 DDR5-5600 CAS-46-45-45 EC8 Registered Smart Memory Kit P64708-B21

Notes:

- 96GB Memory cannot be mixed with any other Memory.
- 96GB 5600 Memory cannot be selected with EE LCC (Edge Enhanced Low Core Count) die of the New 5th Generation Intel® Xeon® Scalable Processors.
- For 1 Processor, the allowed qty of 96GB DDR5-5600 Memory is 1, 6, 8, 12,16 only.
- For 2 Processor, the allowed qty of 96GB DDR5-5600 Memory is 2, 12, 16, 24, 32 only.
- If Memory Fault Tolerance is selected then only x4 memory options can be selected.

HPE 128GB (1x128GB) Quad Rank x4 DDR5-5600 CAS-52-45-45 EC8 Registered 3DS Smart Memory Kit P64709-B21

Notes:

If Memory Fault Tolerance is selected then only x4 memory options can be selected.

HPE 256GB (1x256GB) Octal Rank x4 DDR5-5600 CAS-52-45-45 EC8 Registered 3DS Smart Memory Kit P64710-B21

Notes:

- If 256GB Memory is selected, will be limited to 1P1D, thus Maximum of 8 can be selected per Processor.
- If 256GB Memory is selected, will be limited to using 7x performance fan or CLC fan (not allow standard fan), and limit at 25C. Or DLC must be selected.
- If 256GB Memory is selected without DLC Module, then high speed Networking/ InfiniBand card (PCIe and OCP) that is 100G or more cannot be selected.
- If Closed Loop Liquid Cooling is selected with 256GB DIMM and Rear NS204i-u, then Maximum NVMe drive limit will be reduced from 10 to 4.
- If Closed Loop Liquid Cooling is selected with 256GB DIMM or Internal NS204i-u or rear NS204i-u, then Maximum EDSFF drive limit will be reduced from 20 to 10
- EDSFF CTO Model: If 350W CPU is selected with Closed Loop Liquid cooling, then 256GB DIMM cannot be selected.
- EDSFF Model: If 256GB DIMM and Rear NS204i-u are selected, then DLC Module must be selected.
- If Memory Fault Tolerance is selected then only x4 memory options can be selected.

More detailed information about Memory population rules can be found in Server Memory SharePoint

<https://www.hpe.com/docs/server-memory>

DDR5-4800 (applies to the 4th Generation Intel® Xeon® Scalable Processors)

HPE 16GB (1x16GB) Single Rank x8 DDR5-4800 CAS-40-39-39 EC8 Registered Smart Memory Kit P43322-B21

HPE 32GB (1x32GB) Dual Rank x8 DDR5-4800 CAS-40-39-39 EC8 Registered Smart Memory Kit P43328-B21

HPE 64GB (1x64GB) Dual Rank x4 DDR5-4800 CAS-40-39-39 EC8 Registered Smart Memory Kit P43331-B21

Notes:

If Memory Fault Tolerance is selected then only x4 memory options can be selected.

HPE 96GB (1x96GB) Dual Rank x4 DDR5-4800 CAS-46-45-45 EC8 Registered Smart Memory Kit P66675-B21

Notes:

- 96GB Memory cannot be mixed with any other Memory.
- 96GB 4800 Memory can be selected only with XCC (Extreme Core Counts) & MCC (Medium Core Counts) of the 4th Generation Intel® Xeon® Scalable Processors. Not for HBM processors.
- If 96GB memory is selected, either 8 or 16 memory quantity can be allowed “per “processor.
- If Memory Fault Tolerance is selected then only x4 memory options can be selected.

HPE 128GB (1x128GB) Quad Rank x4 DDR5-4800 CAS-46-39-39 EC8 Registered 3DS Smart Memory Kit P43334-B21

Notes:

If Memory Fault Tolerance is selected then only x4 memory options can be selected.



Core Options

HPE 256GB (1x256GB) Octal Rank x4 DDR5-4800 CAS-46-39-39 EC8 Registered 3DS Smart Memory Kit¹ P43377-B21

Notes:

- If 256GB Memory is selected, will be limited to 1P1D, thus Maximum of 8 can be selected per Processor.
- If 256GB Memory is selected, will be limited to using 7x performance fan or CLC fan (not allow standard fan), and limit at 25C. Or DLC must be selected.
- If 256GB Memory is selected without DLC Module, then high speed Networking/ InfiniBand card (PCIe and OCP) that is 100G or more cannot be selected.
- If Closed Loop Liquid Cooling is selected with 256GB DIMM and Rear NS204i-u, then Maximum NVMe drive limit will be reduced from 10 to 4.
- If Closed Loop Liquid Cooling is selected with 256GB DIMM or Internal NS204i-u or rear NS204i-u, then Maximum EDSFF drive limit will be reduced from 20 to 10
- EDSFF CTO Model: If 350W CPU is selected with Closed Loop Liquid cooling, then 256GB DIMM cannot be selected.
- EDSFF Model: If 256GB DIMM and Rear NS204i-u are selected, then DLC Module must be selected.
- If Memory Fault Tolerance is selected then only x4 memory options can be selected.

More detailed information about Memory population rules can be found in Server Memory SharePoint

<https://www.hpe.com/docs/server-memory>

HPE DIMM blanks

HPE DDR4 DIMM Blank Kit P07818-B21

Notes: Embedded and shipped as default in all DL360 Gen11 CTO Servers, to enhance thermal condition. Leverage the same DIMM blanks from DL360 Gen10 Plus.

Storage Devices

Hardware Storage Controller

| | |
|---|------------|
| HPE SR932i-p Gen11 x32 Lanes 8GB Wide Cache PCI SPDM Plug-in Storage Controller | P47184-B21 |
| HPE MR416i-p Gen11 x16 Lanes 8GB Cache PCI SPDM Plug-in Storage Controller | P47777-B21 |
| HPE MR416i-o Gen11 x16 Lanes 8GB Cache OCP SPDM Storage Controller | P47781-B21 |
| HPE MR216i-p Gen11 x16 Lanes without Cache PCI SPDM Plug-in Storage Controller | P47785-B21 |
| HPE MR216i-o Gen11 x16 Lanes without Cache OCP SPDM Storage Controller | P47789-B21 |
| HPE MR408i-o Gen11 x8 Lanes 4GB Cache OCP SPDM Storage Controller | P58335-B21 |



Core Options

HPE Smart Array E208e-p SR Gen10 (8 External Lanes/No Cache) 12G SAS PCIe Plug-in Controller

804398-B21

Notes:

- Max 1 of PCIe internal controller can be selected per server.
- Max 2 of PCIe and OROC internal controller can be selected per server.
- If any of this controller is selected, then "HPE 96W Smart Stg Li-ion Batt 145mm Kit" or "HPE Smart Hybrid Capacitor w/ 145mm Cbl" must be selected. Vice versa.
- Internal MR-series and Internal SR-series controller cannot be selected together. Below message to be displayed in configurator: "MegaRAID Tools cannot be used to script and configure SmartRAID (formerly known as SmartArray) controllers used on HPE Gen9/10/10 Plus/11 servers".
- If Microchip external controller (E208e) is selected with MR Internal (MR216i/MR416i/MR408i) controllers in the configuration, please be aware these two products use different RAID configuration tools. Therefore, there will be a RAID configuration tool for the SR external controller and another for the MR internal controller.
- For 8SFF CTO Model: If MR408i-o is the only controller selected, then 8SFF cable kit cannot be selected for 8SFF x4 drive cages.
- Except MR408i-o, all internal controllers are supported with 8SFF CTO Model only.
- If both 4P Networking (Base-T and Full-Height) and Half-Height Internal PCIe controller (MR416i-p and MR216i-p) are selected, then Secondary FH riser cannot be selected.
- For 8SFF x4 U.3 drive cage selection with 2SFF Drive cage: If MR416i-p/ MR216i-p and MR416i-o/ MR216i-o/ MR408i-o are selected, then both "HPE DL360 Gen11 8SFF PCIe Cbl Ki/ P48909-B21 or HPE DL360 Gen11 OROC TM Cbl Kit/ P52416-B21" and "HPE DL360 Gen11 2SFF TM Cbl Kit/ P48910-B21" must be selected.
- Prioritization list for Primary controller selection in HPE ProLiant DL360 Gen11 8SFF NC CTO Server (P52499-B21) is as follows:
 - o HPE SR932i-p Gen11 24G Controller Kit
 - o HPE MR416i-o Gen11 12G Controller Kit
 - o HPE MR416i-p Gen11 12G Controller Kit
 - o HPE MR408i-o Gen11 SPDM Storage Cntrl
 - o HPE MR216i-o Gen11 12G Controller Kit
 - o HPE MR216i-p Gen11 12G Controller Kit
 - o Intel® VROC
 - o Direct Attach
- For additional details, pls visit:
 - [**HPE Compute MR Gen11 Controllers Quick Spec**](#)
 - [**HPE Compute SR Gen11 Controllers Quick Spec**](#)

Storage Battery

HPE 96W Smart Storage Lithium-ion Battery with 145mm Cable Kit

P01366-B21

HPE Smart Storage Hybrid Capacitor with 145mm Cable Kit

P02377-B21

HPE ProLiant DL360 Gen11 Storage Controller Enablement Cable Kit

P48918-B21

Notes:

- If "HPE 96W Smart Stg Li-ion Batt 145mm Kit" or "HPE Smart Hybrid Capacitor w/ 145mm Cbl" is selected, then "HPE DL360 Gen11 Stg Cntrl Enable Cbl Kit" must be selected. Vice versa.
- Max 1 of Storage Battery can be selected per server.



Core Options

Internal Storage Controller Cables

| | |
|---|------------|
| HPE ProLiant DL360 Gen11 8SFF PCIe Controller Cable Kit | P48909-B21 |
| HPE ProLiant DL360 Gen11 2SFF Tri-Mode Controller Cable Kit | P48910-B21 |
| HPE ProLiant DL360 Gen11 LFF Internal Cable Kit | P48913-B21 |

Notes:

- When SAS or NVMe storage is selected.
- There are two independent cables that support PCIe RAID controller and OCP RAID controller in this LFF internal cable kit. If 4LFF internal cable kit is selected, then at least one MR408i-o/ MR216i-o/ MR416i-o/ MR216i-p/ MR416i-p must be selected.
- If there is no Hardware controller selected, the DL360 Gen11 4LFF SATA Signal Cable Kit (P51897-B21) must be selected in order to support embedded SATA (Direct attach) configuration.

| | |
|--|------------|
| HPE ProLiant DL360 Gen11 OROC Tri-Mode Cable Kit | P52416-B21 |
|--|------------|

Notes:

- Max 1 of 8SFF cable can be selected per server.
- Max 1 of 2SFF cable can be selected per server.
- Max 1 LFF cable can be selected for 4LFF CTO Model.
- If 8SFF PCIe cable is selected, then any one of 8SFF Drive cage and PCIe form factor internal controller must be selected.
- If 8SFF OROC cable is selected, then any one of 8SFF Drive cage and OCP form factor controller (OROC) must be selected.
- If 2SFF TM cable is selected, then any one of 2SFF Drive cage and any controller (PCIe or OCP form factor) must be selected.
- For 8SFF x4 U.3 drive cage selection with 2SFF Drive cage: If MR416i-p/ MR216i-p and MR416i-o/ MR216i-o/ MR408i-o are selected, then both "HPE DL360 Gen11 8SFF PCIe Cbl Ki/ P48909-B21 or HPE DL360 Gen11 OROC TM Cbl Kit/ P52416-B21" and "HPE DL360 Gen11 2SFF TM Cbl Kit/ P48910-B21" must be selected.

| | |
|---|------------|
| HPE ProLiant DL360 Gen11 4LFF SAS/SATA Signal Cable Kit | P51897-B21 |
|---|------------|

Notes:

- Max 1 cable can be selected for 4LFF CTO Model in between P48913-B21 & P51897-B21.
- Supported with 4LFF CTO Model only.
- If this 4LFF SATA signal cable (P48913-B21) is selected, then no RAID controllers can be selected, MR408i-o/ MR216i-o/ MR416i-o/ MR216i-p/ MR416i-p. As the cable works for embedded SATA configuration.
- If LFF SATA drive is selected without MR408i-o/ MR216i-o/ MR416i-o/ MR216i-p/ MR416i-p controller, then this cable must be selected.

| | |
|---|------------|
| HPE ProLiant DL360 Gen11 2SFF slimSAS to MLB Cable FIO Trigger System Setting | P61535-B21 |
|---|------------|

Notes:

- This is a virtual trigger part for instruction upon factory installation of SATA or SAS drive in the 2SFF drive cage, not a physical part or component.
- Max 1 of 2SFF cable can be selected per server.
- Supported with 8SFF CTO Model only.
- If 2SFF slimSAS to MLB FIO is selected, then 2SFF x4 U.3 drive cage must be selected.
- 8SFF x1 U.3 or 8SFF x4 U.3 drive cage is selected with 2SFF U.3 and both are connected to Motherboard (without any internal controller) and SATA drive is selected in 2SFF cage, then "HPE DL360 G11 2SFF slimSAS to MLB FIO" is required.
- If "HPE DL360 G11 2SFF slimSAS to MLB FIO" is selected, then NVMe drive cannot be installed in 2SFF U.3 drive cage.
- If "HPE DL360 G11 2SFF slimSAS to MLB FIO" is selected, then NS204i-u cannot be selected.



Core Options

RAID Settings

| | |
|--|------------|
| HPE RAID 0 Drive 1 FIO Setting | 339777-B21 |
| HPE RAID 1 Drive 1 FIO Setting | 339778-B21 |
| HPE RAID 5 Drive 1 FIO Setting | 339779-B21 |
| HPE Raid 5 w/SP Drive 1 FIO Setting | 339780-B21 |
| HPE RAID FIO Advanced Data Guarding Option | 339781-B21 |
| HPE Customer Defined RAID Setting Service | 389692-B21 |

Notes:

- General RAID rules:
- Only a single set of RAID will be offered and will only be applied to all applicable drives installed in a server.
- RAID requires selection of a Smart Array controller and a specific number of matching drives. (i.e same part number)
- If RAID is selected, and only SAS OR SATA OR NVMe drives are configured, then all drives must be the same part number. (i.e., matching drives)
- If RAID is selected and both SAS AND SATA drives are configured, then only the SAS drives will be used in the RAID set. (SAS drives must be the same part number; SATA drives can vary in part numbers)
- If RAID is selected and NVMe, SAS AND SATA drives are configured, then only the NVMe drives will be used in the RAID set. (NVMe drives must be the same part number; SAS & SATA drives can vary in part numbers)
- RAID must be selected if both Factory Installed OS and Smart Array controller (embedded or otherwise) are present.
- RAID 0 requires at least 1 drive.
- RAID 1 requires at least 2 or even a number of drives.
- RAID 1 with Spare requires at least 3 drives
- RAID 5 requires at least 3 drives.
- RAID 5 with Spare requires at least 4 drives.
- RAID 6 requires at least 4 drives.
- If SR932i-p/ MR416i-p/ MR416i-o/ MR408i-o is the Primary controller, then all RAID levels are allowed.
- If MR216i-o/MR216i-p/ Intel® VROC Standard is the primary controller, then only following RAID levels are allowed: 0, 1 (available from RAID FIO settings at HPE factory).
- The Intel® VROC Standard is available for RAID support 0, 1, 5 in the field.
- If Intel® VROC Premium is the primary controller, then the following RAID levels are allowed: 0, 1, 5 (available from RAID FIO settings at HPE factory).
- The Intel® VROC Premium is available for RAID support 0, 1, 5, 10 in the field.
- If Direct Attach is the Primary controller, then RAID is NOT allowed.
- If RAID is being selected in a configuration with Intel® VROC and internal controller, then Customer Defined RAID Setting (389692-B21) must be selected.
- For HPE Customer Defined RAID Setting (389692-B21) only:
 - o If this part number is selected then the following RAID rules do not apply:
 - Max of 1 RAID level per server.
 - All integrated hard drives must match
 - Minimum drive quantity requirement for each RAID level.
 - RAID level must be selected if Factory Installed OS is present and Smart Array SAS controller (embedded or otherwise) is the primary controller.
 - o If this part number is selected, then at least 1 hard drive must be in the order.
 - o If this part number is selected, then preinstalled OS must be on the order.



Core Options

- A Customer Intent Document (CID) must be supplied if this part number is ordered. This Customer Intent Document should include all details about the desired RAID custom configuration. (This includes drive part #s and quantities, RAID levels desired, which drives should be applied to each RAID level, and if a preinstalled OS has been ordered - which RAID set it should be installed on)
- If "HPE Customer Defined RAID Setti ALL" is selected with one Internal controller. HPE Recommends using below standard RAID Settings.
 - 339777-B21 - HPE RAID 0 Drive 1 FIO Setting
 - 339778-B21 - HPE RAID 1 Drive 1 FIO Setting
 - 339779-B21 - HPE RAID 5 Drive 1 FIO Setting
 - 339780-B21 - HPE RAID 5 w/SP Drive 1 FIO Setting
 - 339781-B21 - HPE Raid Adv Data Guarding FIO
- If RAID is being selected in a configuration with Intel® VROC and internal controller, then Customer Defined RAID Setting (389692-B21) must be selected.

Drive cage and backplane (8 SFF CTO server only)

User Selection: Min 0 // Max 2 . If front drives are needed in the 8 SFF server, please select one backplane from list below.

Notes: No optional backplanes available for LFF models, 4-bay 12G x1 SAS/SATA already included with server.

HPE DL360 Gen11 Basic Carrier (BC) drive cages and drive backplanes

Notes: For all backplanes below:

- Supports Basic Carrier Drives.
- Includes cabling.

HPE ProLiant DL360 Gen11 8SFF x1 U.3 Tri-Mode Backplane Kit

P48895-B21

Notes:

- Supports SATA, SAS and NVMe Basic Carrier (BC) drives.
- NVMe SSDs must be U.3. If 8SFF x1 drive cage is connected to Direct Attach (without internal controller and 8SFF cable), then only SATA drive can be selected in this drive cage.
- No NVMe Direct Attach support.
- Not supported with SR932i-p Tri-Mode controller.
- Supports HPE Gen11 SAS/SATA controller if only SAS/SATA drives are installed

Cable Kit selection with controller(s) for P48895-B21 & P48899-B21

- Alone selection without 2SFF Drive cage: If SR932i-p/ MR416i-p/ MR216i-p is selected, then "HPE DL360 Gen11 8SFF PCIe Cbl Kit" must be ordered.
- Selection with 2SFF Drive cage:
 - If SR932i-p/ MR416i-p/ MR216i-p is alone selected, then both "HPE DL360 Gen11 8SFF PCIe Cbl Kit" and "HPE DL360 Gen11 2SFF TM Cbl Kit" must be selected.
 - If MR416i-o/ MR216i-o is alone selected, then both "HPE DL360 Gen11 OROC TM Cbl Kit" and "HPE DL360 Gen11 2SFF TM Cbl Kit" must be selected.
 - If 1 quantity of MR408i-o is alone selected, then "HPE DL360 Gen11 OROC TM Cbl Kit" must be selected. And then "HPE DL360 Gen11 2SFF TM Cbl Kit" cannot be selected.
 - If 2 quantity of MR408i-o is selected, then both "HPE DL360 Gen11 OROC TM Cbl Kit" and "HPE DL360 Gen11 2SFF TM Cbl Kit" must be selected.
 - , If SR932i-p, MR416i-p, MR216i-p, MR416i-o, MR216i-o controller is selected, then max 1 of the internal controllers can be selected per server.



Core Options

HPE ProLiant DL360 Gen11 8SFF x4 U.3 Tri-Mode Backplane Kit

P48896-B21

HPE ProLiant DL360 Gen11 2SFF x4 U.3 BC Tri-Mode Enablement Kit

P48899-B21

Notes:

- Supports SATA, SAS and NVMe Basic Carrier (BC) drives.
- NVMe SSDs must be U.3.
- Supports NVMe Direct Access and slotted Tri-Mode controllers.
- Includes Direct Access cables and backplane power cables. Drive cages will be connected to Motherboard (Direct Attach) if no Internal controller is selected. Direct Attach is capable of supporting all the drives (SATA or NVMe).
- Mixing SR and MR internal controllers is not allowed .
- Requires 8 SFF cables (P48909-B21 HPE ProLiant DL360 Gen11 8SFF PCIe Controller Cable Kit) for Tri-Mode PCIe standup controllers.
- Requires 8 SFF cables (P52416-B21 HPE ProLiant DL360 Gen11 OROC Tri-Mode Cable Kit) for OCP3.0 controllers.
- Requires 2 SFF cables (P48910-B21 HPE ProLiant DL360 Gen11 2SFF Tri-Mode Controller Cable Kit) for Tri-Mode PCIe standup and OCP3.0 controllers.
- Max 1 of 8SFF Drive cage can be selected per server.
- If 8SFF drive cage is selected without 2SFF Drive cage, then Max 1 of internal controller can be selected.
- If 2SFF drive cage is selected, then 8SFF Drive cage must be selected.
- If 8SFF x4 drive cage is connected to Direct Attach (without internal controller and 8SFF cable), then only NVMe drive can be selected in this drive cage.
- If 2SFF U.3 drive cage is connected to Direct Attach (without internal controller and 2SFF cable), then either SATA or NVMe drive can be selected in this drive cage.
- For 2SFF U.3 drive cage selection in 1 Processor configuration: If 2SFF Drive cage is connected to Direct Attach (without Internal controller and 2SFF cable) and NVMe drive is selected, then "CPU1 to OCP2 x8" and "OCP1 x16" OCP upgrade kit cannot be selected.

Cable Kit selection with controller(s) for P48896-B21 & P48899-B21

- Alone selection without 2SFF Drive cage:
 - o If SR932i-p/ MR416i-p/ MR216i-p is selected, then "HPE DL360 Gen11 8SFF PCIe Cbl Kit" must be selected.
 - o If MR416i-o/ MR216i-o is selected, then "HPE DL360 Gen11 OROC TM Cbl Kit" must be selected.
 - o MR408i-o cannot be selected.
- Selection with 2SFF Drive cage:
 - o If SR932i-p is alone selected, then "HPE DL360 Gen11 8SFF PCIe Cbl Kit" or both "HPE DL360 Gen11 8SFF PCIe Cbl Kit" and "HPE DL360 Gen11 2SFF TM Cbl Kit" must be selected.
 - o If 1 quantity of MR416i-p/ MR216i-p is alone selected, then either "HPE DL360 Gen11 8SFF PCIe Cbl Kit" or "HPE DL360 Gen11 2SFF TM Cbl Kit" must be selected. Both the cables cannot be selected.
 - o If 1 quantity of MR416i-o/ MR216i-o is selected, then either "HPE DL360 Gen11 OROC TM Cbl Kit" or "HPE DL360 Gen11 2SFF TM Cbl Kit" must be selected. Both the cables cannot be selected at a time.
 - o If 2 quantities MR416i-o/ MR216i-o is selected, then both "HPE DL360 Gen11 OROC TM Cbl Kit" and "HPE DL360 Gen11 2SFF TM Cbl Kit" must be selected.
 - o If MR408i-o is alone selected, then "HPE DL360 Gen11 2SFF TM Cbl Kit" must be selected, and 8SFF cable kit cannot be selected.
 - o If MR416i-p/ MR216i-p and MR416i-o/ MR216i-o/ MR408i-o are selected, then both "HPE DL360 Gen11 8SFF PCIe Cbl Kit or HPE DL360 Gen11 OROC TM Cbl Kit" and "HPE DL360 Gen11 2SFF TM Cbl Kit" must be selected.



Core Options

- If 2SFF U.3 drive cage is connected to Direct Attach (without internal controller & 2SFF cable), then SATA drive cannot be selected in 2SFF drive cage when "NS204i-u Gen11 Ht Plg Boot Opt Dev" is selected.

HPE ProLiant DL3X0 Gen11 1U 8SFF Display Port/USB/Optical Drive Blank Kit P48926-B21

Notes:

- Universal Media Bay.
- For 8SFF CTO Svr only.
- Max 1 of 2SFF Drive cage or ODD cage can be selected per server.
- 8SFF CTO Model: If Optical drive is selected, then ODD Cage " HPE ProLiant DL3X0 Gen11 1U 8SFF Display Port/USB/Optical Drive Blank Kit " must be selected.

Display Port

HPE ProLiant DL3X0 Gen11 1U LFF Display Port/USB Kit P48928-B21

Notes: Supported with 4LFF CTO Model only.

Optical Cable

HPE ProLiant DL360 Gen11 LFF Optical Cable Kit P48914-B21

Optical Drive

HPE Mobile USB DVD-RW Optical Drive 701498-B21

Notes: This kit is supported on USB 3.0 ports only.

HPE 9.5mm SATA DVD-ROM Optical Drive 726536-B21

Notes:

- Requires Universal Media Bay Kit (P48926-B21) to install on 8 SFF models.
- Requires cable for optical drive (P48914-B21) to install on 4 LFF models.

HPE 9.5mm SATA DVD-RW Optical Drive 726537-B21

Notes:

- Requires Universal Media Bay Kit (P48926-B21) to install on 8 SFF models.
- Requires cable for optical drive (P48914-B21) to install on 4 LFF models.

HPE ProLiant DL360 Gen10 Plus LFF Optical Cable P26459-B21

Notes: Max 1

HDD Blank Kit

HPE Small Form Factor Hard Drive Blank Kit 666987-B21

HPE Gen9 LFF HDD Spade Blank Kit 807878-B21

Storage

- Maximum limit for SAS/ SATA/ NVMe will vary depending upon the selected drive cage, controller and cable combination.
- User may select any combination of SAS or SATA Hard Drives. However, if RAID is selected and both SAS and SATA Hard Drives have been selected, then only the SAS Drives will be used in the RAID set.
- User may select any combination of SAS or SATA or NVMe Drives on U.3 cage with Tri-Mode controller. However, if RAID is selected with SAS, SATA and NVMe Drives, then only the NVMe Drives will be used in the RAID set.
- Direct Attach supports only SATA or NVMe drives. If SAS drive is selected, then Internal controller must be selected.
- If SAS drive is selected, then 8SFF drive cage must be selected.
- If 8SFFx1 drive cage is connected to Direct Attach (without internal controller and 8SFF cable), then only SATA drive can be selected in this drive cage.
- For SSD selection guidance, please visit: <http://ssd.hpe.com/>



Core Options

NVMe Gen5 – Read Intensive (max 20)

Read Intensive – NVMe – EDSFF - Solid State Drives

| | |
|---|------------|
| HPE 15.36TB NVMe Gen5 High Performance Read Intensive E3S EC1 EDSFF SPDM CM7 SSD | P61187-B21 |
| HPE 7.68TB NVMe Gen5 High Performance Read Intensive E3S EC1 EDSFF SPDM CM7 SSD | P61183-B21 |
| HPE 6.4TB NVMe Gen5 High Performance Mixed Use E3S EC1 EDSFF SPDM CM7 SSD | P61195-B21 |
| HPE 3.84TB NVMe Gen5 High Performance Read Intensive E3S EC1 EDSFF SPDM CM7 SSD | P61179-B21 |
| HPE 3.2TB NVMe Gen5 High Performance Mixed Use E3S EC1 EDSFF SPDM CM7 SSD | P61191-B21 |
| HPE 15.36TB NVMe Gen5 High Performance Read Intensive E3S EC1 EDSFF SPDM PM1743 SSD | P57807-B21 |
| HPE 7.68TB NVMe Gen5 High Performance Read Intensive E3S EC1 EDSFF SPDM PM1743 SSD | P57803-B21 |
| HPE 3.84TB NVMe Gen5 High Performance Read Intensive E3S EC1 EDSFF SPDM PM1743 SSD | P57799-B21 |

Notes:

- In 20EDSFF CTO server only.
- These drives cannot be used as boot drives with VMware software. Therefore, when these drives are selected with VMware OS, then the internal or external NS204i-u OS Boot device must be selected to run VMware.
- For detail configuration limitation, please refer to the 20EDSFF CTO Server section, CPU selection, 256GB memory section and Networking card above 100GbE section.

| | |
|--|------------|
| HPE 7.68TB NVMe Gen5 Mainstream Performance Read Intensive E3S EC1 EDSFF CD7 SSD | P56587-B21 |
| HPE 3.84TB NVMe Gen5 Mainstream Performance Read Intensive E3S EC1 EDSFF CD7 SSD | P56586-B21 |
| HPE 1.92TB NVMe Gen5 Mainstream Performance Read Intensive E3S EC1 EDSFF CD7 SSD | P56585-B21 |

NVMe Gen4 – SSD and AIC – Read Intensive & Mixed Used (max 10)

Read Intensive – NVMe – SFF – Self-encrypting Solid-State Drives

| | |
|--|------------|
| HPE 3.84TB NVMe Gen4 High Performance Read Intensive SFF BC Self-encrypting FIPS U.3 CM6 SSD | P41403-B21 |
| HPE 1.92TB NVMe Gen4 High Performance Read Intensive SFF BC Self-encrypting FIPS U.3 CM6 SSD | P41402-B21 |

Read Intensive - NVMe - SFF - Solid State Drives

| | |
|--|------------|
| HPE 15.36TB NVMe Gen4 High Performance Read Intensive SFF BC U.3 PM1733a SSD | P50224-B21 |
| HPE 7.68TB NVMe Gen4 High Performance Read Intensive SFF BC U.3 PM1733a SSD | P50222-B21 |
| HPE 7.68TB NVMe Gen4 Mainstream Performance Read Intensive SFF BC U.3 Static V2 Multi Vendor SSD | P64848-B21 |
| HPE 3.84TB NVMe Gen4 High Performance Read Intensive SFF BC U.3 PM1733a SSD | P50219-B21 |
| HPE 3.84TB NVMe Gen4 Mainstream Performance Read Intensive SFF BC U.3 Static V2 Multi Vendor SSD | P64846-B21 |
| HPE 1.92TB NVMe Gen4 High Performance Read Intensive SFF BC U.3 PM1733a SSD | P50216-B21 |
| HPE 1.92TB NVMe Gen4 Mainstream Performance Read Intensive SFF BC U.3 Static V2 Multi Vendor SSD | P64844-B21 |
| HPE 960GB NVMe Gen4 Mainstream Performance Read Intensive SFF BC U.3 Static V2 Multi Vendor SSD | P64842-B21 |

Mixed Use – NVMe – SFF – Self-encrypting Solid-State Drives

| | |
|--|------------|
| HPE 3.2TB NVMe Gen4 High Performance Mixed Use SFF BC Self-encrypting FIPS U.3 CM6 SSD | P41405-B21 |
| HPE 1.6TB NVMe Gen4 High Performance Mixed Use SFF BC Self-encrypting FIPS U.3 CM6 SSD | P41404-B21 |

Mixed Use - NVMe - SFF - Solid State Drives

| | |
|--|------------|
| HPE 6.4TB NVMe Gen4 High Performance Mixed Use SFF BC U.3 PM1735a SSD | P50233-B21 |
| HPE 6.4TB NVMe Gen4 Mainstream Performance Mixed Use SFF BC U.3 Static V2 Multi Vendor SSD | P65023-B21 |
| HPE 3.2TB NVMe Gen4 High Performance Mixed Use SFF BC U.3 PM1735a SSD | P50230-B21 |
| HPE 3.2TB NVMe Gen4 Mainstream Performance Mixed Use SFF BC U.3 Static V2 Multi Vendor SSD | P65015-B21 |
| HPE 1.6TB NVMe Gen4 High Performance Mixed Use SFF BC U.3 PM1735a SSD | P50227-B21 |
| HPE 1.6TB NVMe Gen4 Mainstream Performance Mixed Use SFF BC U.3 Static V2 Multi Vendor SSD | P65007-B21 |
| HPE 800GB NVMe Gen4 Mainstream Performance Mixed Use SFF BC U.3 Static V2 Multi Vendor SSD | P64999-B21 |



Core Options

SSD - Read Intensive (max 10)

Read Intensive - 24G SAS - SFF – Self-encrypting Solid-State Drives

| | |
|---|------------|
| HPE 7.68TB SAS 24G Read Intensive SFF BC Self-encrypting FIPS PM6 SSD | P41399-B21 |
| HPE 3.84TB SAS Read Intensive SFF BC Self-encrypting FIPS 140-3 PM7 SSD | P63875-B21 |
| HPE 3.84TB SAS 24G Read Intensive SFF BC Self-encrypting FIPS PM6 SSD | P41398-B21 |

Read Intensive - 12G/24G SAS - SFF - Solid State Drives

| | |
|---|------------|
| HPE 15.36TB SAS 24G Read Intensive SFF BC Multi Vendor SSD | P49045-B21 |
| HPE 7.68TB SAS 12G Read Intensive SFF BC Value SAS Multi Vendor SSD | P40509-B21 |
| HPE 7.68TB SAS 24G Read Intensive SFF BC Multi Vendor SSD | P49041-B21 |
| HPE 3.84TB SAS 12G Read Intensive SFF BC Value SAS Multi Vendor SSD | P40508-B21 |
| HPE 3.84TB SAS 24G Read Intensive SFF BC Multi Vendor SSD | P49035-B21 |
| HPE 1.92TB SAS 12G Read Intensive SFF BC Value SAS Multi Vendor SSD | P40507-B21 |
| HPE 1.92TB SAS 24G Read Intensive SFF BC Multi Vendor SSD | P49031-B21 |
| HPE 960GB SAS 12G Read Intensive SFF BC Value SAS Multi Vendor SSD | P40506-B21 |
| HPE 960GB SAS 24G Read Intensive SFF BC Multi Vendor SSD | P49029-B21 |

Read Intensive – 6G SATA – SFF - Self-encrypting Solid-State Drives

| | |
|--|------------|
| HPE 1.92TB SATA 6G Read Intensive SFF BC Self-encrypting 5400P SSD | P58240-B21 |
| HPE 480GB SATA 6G Read Intensive SFF BC Self-encrypting 5400P SSD | P58236-B21 |

Read Intensive - 6G SATA - SFF - Solid State Drives

| | |
|---|------------|
| HPE 7.68TB SATA 6G Read Intensive SFF BC Multi Vendor SSD | P40501-B21 |
| HPE 3.84TB SATA 6G Read Intensive SFF BC PM893a SSD | P63910-B21 |
| HPE 3.84TB SATA 6G Read Intensive SFF BC Multi Vendor SSD | P40500-B21 |
| HPE 3.84TB SATA 6G Read Intensive SFF BC PM893 SSD | P44010-B21 |
| HPE 1.92TB SATA 6G Read Intensive SFF BC Multi Vendor SSD | P40499-B21 |
| HPE 1.92TB SATA 6G Read Intensive SFF BC PM893 SSD | P44009-B21 |
| HPE 480GB SATA 6G Read Intensive SFF BC PM893a SSD | P63886-B21 |
| HPE 480GB SATA 6G Read Intensive SFF BC Multi Vendor SSD | P40497-B21 |
| HPE 480GB SATA 6G Read Intensive SFF BC PM893 SSD | P44007-B21 |
| HPE 960GB SATA 6G Read Intensive SFF BC Multi Vendor SSD | P40498-B21 |
| HPE 960GB SATA 6G Read Intensive SFF BC PM893 SSD | P44008-B21 |
| HPE 240GB SATA 6G Read Intensive SFF BC Multi Vendor SSD | P40496-B21 |

Read Intensive - 6G SATA - LFF - Solid State Drives

| | |
|---|------------|
| HPE 960GB SATA 6G Read Intensive LFF LPC Multi Vendor SSD | P47808-B21 |
|---|------------|

SSD – Mixed Use (max 10)

Mixed Use - 24G SAS - SFF – Self-encrypting Solid-State Drives

| | |
|---|------------|
| HPE 1.6TB SAS Mixed Use SFF BC Self-encrypting FIPS 140-2 PM7 SSD | P63871-B21 |
| HPE 1.6TB SAS 24G Mixed Use SFF BC Self-encrypting FIPS PM6 SSD | P41401-B21 |
| HPE 800GB SAS 24G Mixed Use SFF BC Self-encrypting FIPS PM6 SSD | P41400-B21 |



Core Options

Mixed Use - 12G/24G SAS - SFF - Solid State Drives

| | |
|--|------------|
| HPE 6.4TB SAS 24G Mixed Use SFF BC Multi Vendor SSD | P49057-B21 |
| HPE 3.84TB SAS 12G Mixed Use SFF BC Value SAS Multi Vendor SSD | P40512-B21 |
| HPE 3.2TB SAS 24G Mixed Use SFF BC Multi Vendor SSD | P49053-B21 |
| HPE 1.92TB SAS 12G Mixed Use SFF BC Value SAS Multi Vendor SSD | P40511-B21 |
| HPE 1.6TB SAS 24G Mixed Use SFF BC Multi Vendor SSD | P49049-B21 |
| HPE 960GB SAS 12G Mixed Use SFF BC Value SAS Multi Vendor SSD | P40510-B21 |
| HPE 800GB SAS 24G Mixed Use SFF BC Multi Vendor SSD | P49047-B21 |

Mixed Use - 6G SATA - SFF - Self-encrypting Solid-State Drives

| | |
|---|------------|
| HPE 1.92TB SATA 6G Mixed Use SFF BC Self-encrypting 5400M SSD | P58248-B21 |
| HPE 960GB SATA 6G Mixed Use SFF BC Self-encrypting 5400M SSD | P58244-B21 |

Mixed Use - 6G SATA - SFF - Solid State Drives

| | |
|--|------------|
| HPE 3.84TB SATA 6G Mixed Use SFF BC Multi Vendor SSD | P40505-B21 |
| HPE 3.84TB SATA 6G Mixed Use SFF Spl BC Multi Vendor SSD | P47032-B21 |
| HPE 1.92TB SATA 6G Mixed Use SFF BC Multi Vendor SSD | P40504-B21 |
| HPE 1.92TB SATA 6G Mixed Use SFF BC PM897 SSD | P44013-B21 |
| HPE 1.92TB SATA 6G Mixed Use SFF Spl BC Multi Vendor SSD | P47028-B21 |
| HPE 960GB SATA 6G Mixed Use SFF BC Multi Vendor SSD | P40503-B21 |
| HPE 960GB SATA 6G Mixed Use SFF BC PM897 SSD | P44012-B21 |
| HPE 480GB SATA 6G Mixed Use SFF BC Multi Vendor SSD | P40502-B21 |
| HPE 480GB SATA 6G Mixed Use SFF BC PM897 SSD | P44011-B21 |

Mixed Use - 12G SAS - LFF - Solid State Drives

| | |
|--|------------|
| HPE 960GB SAS 12G Mixed Use LFF LPC Value SAS Multi Vendor SSD | P37009-B21 |
|--|------------|

HDD- Enterprise 15K/10K -SFF (max 10)

Mission Critical - 12G SAS - SFF SED Drives

| | |
|---|------------|
| HPE 2.4TB SAS 12G Mission Critical 10K SFF BC 3-year Warranty 512e Self-encrypting FIPS HDD | P28618-B21 |
| HPE 1.2TB SAS 12G Mission Critical 10K SFF BC 3-year Warranty Self-encrypting FIPS HDD | P28622-B21 |

Enterprise - 12G SAS - SFF Drives

| | |
|---|------------|
| HPE 2.4TB SAS 12G Mission Critical 10K SFF BC 3-year Warranty 512e Multi Vendor HDD | P28352-B21 |
| HPE 1.8TB SAS 12G Mission Critical 10K SFF BC 3-year Warranty 512e Multi Vendor HDD | P53562-B21 |
| HPE 1.2TB SAS 12G Mission Critical 10K SFF BC 3-year Warranty Multi Vendor HDD | P28586-B21 |
| HPE 900GB SAS 12G Mission Critical 15K SFF BC 3-year Warranty Multi Vendor HDD | P40432-B21 |
| HPE 600GB SAS 12G Mission Critical 15K SFF BC 3-year Warranty Multi Vendor HDD | P53560-B21 |
| HPE 600GB SAS 12G Mission Critical 10K SFF BC 3-year Warranty Multi Vendor HDD | P53561-B21 |
| HPE 300GB SAS 12G Mission Critical 15K SFF BC 3-year Warranty Multi Vendor HDD | P28028-B21 |
| HPE 300GB SAS 12G Mission Critical 10K SFF BC 3-year Warranty Multi Vendor HDD | P40430-B21 |

HDD - Midline - 7.2K - SFF (max 10)

Midline - 6G SATA - SFF Drives

| | |
|--|------------|
| HPE 2TB SATA 6G Business Critical 7.2K SFF BC 1-year Warranty 512e HDD | P28500-B21 |
| HPE 1TB SATA 6G Business Critical 7.2K SFF BC 1-year Warranty HDD | P28610-B21 |

HDD - Midline - 7.2K - LFF (max 4)

Midline - 12G SAS - LFF Drives

| | |
|---|------------|
| HPE 20TB SAS 12G Business Critical 7.2K LFF LP 1-year Warranty Helium 512e ISE Multi Vendor HDD | P53553-B21 |
| HPE 16TB SAS 12G Business Critical 7.2K LFF LP 1-year Warranty Helium 512e ISE Multi Vendor HDD | P23608-B21 |
| HPE 14TB SAS 12G Business Critical 7.2K LFF LP 1-year Warranty Helium 512e Multi Vendor HDD | P09155-B21 |



Core Options

| | |
|---|------------|
| HPE 12TB SAS 12G Business Critical 7.2K LFF LP 1-year Warranty Helium 512e Multi Vendor HDD | 881781-B21 |
| HPE 8TB SAS 12G Business Critical 7.2K LFF LP 1-year Warranty 512e Multi Vendor HDD | 834031-B21 |
| HPE 6TB SAS 12G Business Critical 7.2K LFF LP 1-year Warranty 512e Multi Vendor HDD | 861746-B21 |
| HPE 4TB SAS 12G Business Critical 7.2K LFF LP 1-year Warranty Multi Vendor HDD | 833928-B21 |
| HPE 2TB SAS 12G Business Critical 7.2K LFF LP 1-year Warranty Multi Vendor HDD | 833926-B21 |

Midline - 6G SATA - LFF Drives

| | |
|---|------------|
| HPE 20TB SATA 6G Business Critical 7.2K LFF LP 1-year Warranty Helium 512e ISE Multi Vendor HDD | P53554-B21 |
| HPE 18TB SATA 6G Business Critical 7.2K LFF LP 1-year Warranty Helium 512e ISE Multi Vendor HDD | P37678-B21 |
| HPE 16TB SATA 6G Business Critical 7.2K LFF LP 1-year Warranty Helium 512e ISE Multi Vendor HDD | P23449-B21 |
| HPE 12TB SATA 6G Business Critical 7.2K LFF LP 1-year Warranty Helium 512e Multi Vendor HDD | 881787-B21 |
| HPE 8TB SATA 6G Business Critical 7.2K LFF LP 1-year Warranty 512e Multi Vendor HDD | 834028-B21 |
| HPE 6TB SATA 6G Business Critical 7.2K LFF LP 1-year Warranty 512e Multi Vendor HDD | 861742-B21 |
| HPE 4TB SATA 6G Business Critical 7.2K LFF LP 1-year Warranty Multi Vendor HDD | 861683-B21 |
| HPE 2TB SATA 6G Business Critical 7.2K LFF LP 1-year Warranty Multi Vendor HDD | 861681-B21 |
| HPE 1TB SATA 6G Business Critical 7.2K LFF LP 1-year Warranty Multi Vendor HDD | 861686-B21 |

Factory Configuration Settings

Each of the following may be selected if desired at time of factory integration

Battery Upgrade Removal Setting

| | |
|----------------------------------|------------|
| HPE FIO No Smart Storage Battery | P06141-B21 |
|----------------------------------|------------|

Notes:

- If "HPE FIO No Smart Storage Battery" is selected, then SR932/ MR416/ MR408 controller does not require selection of Battery.
- If "HPE FIO No Smart Storage Battery" is selected, then SR932/ MR416/ MR408 controller must be selected.
- If "HPE FIO No Smart Storage Battery" is selected, then Battery cannot be selected.

BIOS Mode

| | |
|---|------------|
| HPE ProLiant DL300 Gen10 Plus Platform RAS OS Control FIO Setting | P27078-B21 |
|---|------------|

Notes: OS First – RAS Setting Trigger.

Cray Compute Node Identifier

| | |
|---|--------|
| HPE Cray Compute Node FIO Configuration | R9H92A |
|---|--------|

Notes: Can only be selected or configured for a Cray or Slingshot Solution. Not allowed for Non-Cray or Non-Slingshot Solutions.

Cray User-Defined Non-Compute Node Identifier

| | |
|---|--------|
| HPE Cray Supercomputing Service Node 1 FIO Configuration | R4L49A |
| HPE Cray Supercomputing Service Node 2 FIO Configuration | R4L50A |
| HPE Cray Supercomputing Service Node 3 FIO Configuration | R4L51A |
| HPE Cray Supercomputing Service Node 4 FIO Configuration | R4L52A |
| HPE Cray Supercomputing Service Node 5 FIO Configuration | R4L53A |
| HPE Cray Supercomputing Service Node 6 FIO Configuration | R4L54A |
| HPE Cray Supercomputing Service Node 7 FIO Configuration | R4L55A |
| HPE Cray Supercomputing Service Node 8 FIO Configuration | R4L56A |
| HPE Cray Supercomputing Service Node 9 FIO Configuration | R4L57A |
| HPE Cray Supercomputing Service Node 10 FIO Configuration | R4L58A |
| HPE Cray Supercomputing Service Node 11 FIO Configuration | R4L59A |



Core Options

| | |
|--|--------|
| HPE Cray Supercomputing Service Node 12 FIO Configuration | R4L60A |
| HPE Cray Supercomputing Service Node 13 FIO Configuration | R4L61A |
| HPE Cray Supercomputing Service Node 14 FIO Configuration | R4L62A |
| HPE Cray Supercomputing Service Node 15 FIO Configuration | R4L63A |
| HPE Cray Supercomputing Service Node 16 FIO Configuration | R4L64A |
| HPE Cray Supercomputing Service Node 17 FIO Configuration | R4L65A |
| HPE Cray Supercomputing Service Node 18 FIO Configuration | R4L66A |
| HPE Cray Supercomputing Service Node 19 FIO Configuration | R4L67A |
| HPE Cray Supercomputing User Access Node FIO Configuration | R4L68A |

Identifier/Tracking SKUs

| | |
|--|------------|
| HPE ProLiant for Microsoft Azure Stack HCI Configure-to-order Tracking | P64062-B21 |
|--|------------|

iLO Common Password

| | |
|-------------------------------------|------------|
| HPE iLO Common Password FIO Setting | P08040-B21 |
|-------------------------------------|------------|

Notes:

- It is advisable to match the order quantity of this SKU matching the quantity of servers being ordered.
- Below Warning message to be displayed in the configurators upon the selection of this SKU:
- "Use of iLO Common Password SKU sets the initial iLO password to be a well-known string rather than a random password. It is advisable to match the order quantity of this SKU matching the quantity of servers being ordered."
- HPE highly recommends changing this password immediately after the initial onboarding process.
- Customers who want to choose their own custom iLO default password should use the HPE Factory Express Integration Services

Logical Size Settings

| | |
|------------------------------------|------------|
| HPE 200GB Logical Size FIO Setting | 436007-B21 |
|------------------------------------|------------|

Notes: If "HPE 200GB Logical Size FIO Setting" is selected, then RAID level must be selected.

Memory Setting

| | |
|---|------------|
| HPE Smart Memory Fast Fault Tolerance FIO Setting | 875293-B21 |
|---|------------|

Notes:

- If Memory Fast Fault Tolerance kit is selected with 1 Processor and Single Rank memory, then Memory Min = 2 and Max= 16.
- If Memory Fast Fault Tolerance kit is selected with 1 Processor and Dual/Quad/ Octal Rank memory then, Memory Min = 1 and Max= 16.
- If Memory Fast Fault Tolerance kit is selected with 2 Processors and Single Rank memory, then Memory Min = 4 and Max= 32.
- If Memory Fast Fault Tolerance kit is selected with 2 Processors and Dual/Quad/ Octal Rank memory, then Memory Min = 2 and Max= 32

| | |
|--|------------|
| HPE ProLiant DL3XX Gen11 Cache Mode for High-Bandwidth Memory FIO Trigger System Setting | P65886-B21 |
|--|------------|

Notes:

- Memory Fast Fault Tolerance and HBM Cache Mode cannot be selected together.
- HBM Cache mode requires selection of HBM Processor (94xx).
- If HBM Cache mode is selected, then Memory Qty must be 4/ 8/ 16 per HBM Processor.
- If 16GB capacity Memory is selected with HBM Cache mode then minimum Qty 8 per HBM Processor must be selected.
- If 32GB or higher capacity Memory is selected with HBM Cache mode then minimum Qty 4 per HBM Processor must be selected.



Core Options

- If 256GB is selected with HBM Cache mode, then the system memory Qty need to be 16 per HBM processor.

CE Mark Setting

HPE CE Mark Removal FIO Enablement Kit

P35876-B21

Notes:

Correlated to the new EU Lot9 Regulation addressed in the Power Supplies section.

For EU Lot9 out-of-scope countries, incl. rest of EMEA, the Americas, Asia-Pacific & Japan and China.

- Users will be able to select non-compliant Power Supplies on this server.
- If a non-compliant PSU is selected as FIO/OD1, the Configurator will auto populate SKU P35876-B21 [HPE CE Mark Removal FIO Enable Kit] which directs to use the non-CE bearing variant of agency and COO labels. Then the unit is not-importable into the EU Lot9 in scope countries.
- If CE Mark Removal SKU is deleted from configuration, without removing non-compliant Power Supply, this will be identified as unbuildable configuration, until the 96% efficient (Titanium) FlexSlot power supply is mandated to meet the Lot9 requirements.

OEM Configuration Setting

HPE OEM FIO Server Unbranding Service

P44105-B21

Trusted Supply Chain

HPE Trusted Supply Chain for HPE ProLiant

P36394-B21

Notes:

- If "HPE Trusted Supply Chain FIO Config" is selected then "Gen11 Intrusion Cbl Kit" must be selected.
- If HPE Trusted Supply Chain FIO Config is selected, then Configurator should default to "Gen11 Intrusion Cbl Kit".
- If "HPE Trusted Supply Chain FIO Config" is selected, then "HPE iLO Adv 1-svr Lic 3yr Support" or "HPE OneView for DL 3y 24x7 FIO Phys 1 Svr Lic" or "HPE iLO Adv 1-svr Lic 1yr Support" must be selected.
- If HPE Trusted Supply Chain FIO Config is selected then Configurator should default 1Qty of "HPE iLO Adv 1-svr Lic 3yr Support" and customer will be allowed to deselect. If deselects then either "HPE OneView for DL 3y 24x7 FIO Phys 1 Svr Lic" or "HPE iLO Adv 1-svr Lic 1yr Support" must be selected.
- If HPE Trusted Supply Chain FIO Config is selected, configurator to display the following Warning Message: "Logistics delivery speeds/services are available, please select within NGQ"
- If "HPE Trusted Supply Chain FIO Config" is selected then HPE Trusted Supply Chain E-LTU Software is required per order (not per server).
- If HPE Trusted Supply Chain FIO Config is selected then Configurator should default Trusted Supply Chain E-LTU Software.
- Display the following note for the Trusted Supply Chain section in OCA Menu view: "If Trusted Supply Chain section is selected, only one instance of the following E-LTU software option is required per order (not per server): HPE Trusted Supply Chain E-LTU."



Core Options

Riser Cards

Standard Primary (Butterfly) Riser: (embedded in all CTO and BTO Server)

- Slot 1 - 1x PCIe 5.0 x16 Full-height, up to 9.5" length (or Half-length card)
- Slot 2 - 1x PCIe 5.0 x16 Low-profile, up to 9.5" length (or Half-length card)

After factory installation and shipment,, field upgrade riser card settings is currently not available,

Notes: If Hot-plug NS204i-u is installed, the Slot 2 cage need to be removed

HPE ProLiant DL360 Gen11 x16 Full Height Riser Kit

P48901-B21

Notes:

- Referred as Secondary FH riser.
- 2nd Processor is required.
- Slot 3: 1x PCIe5.0 x 16 Full-length, up to 9.5' length (or Half-length card)
- If both 4P Networking (Base-T and Full-Height) and Half-Height Internal PCIe controller are selected, then Secondary FH riser cannot be selected.

HPE ProLiant DL360 Gen11 x16 LP Riser Kit

P48903-B21

Notes:

- Referred as Secondary Low Profile (LP) riser.
- 2nd Processor is required.
- Slot 3: 1xPCIe5.0 x 16 Low-profile, up to 9.5" length (or Half-length crad)

| Riser Information*** | | | | | | | | | | |
|-----------------------------|---|----------------|------|-----------------------------|------------------|-----|----------------|---------------------|----------|-------------|
| Part number | Description | Riser position | | Slot Bus width (Gen5 lanes) | | | GPU Support | NVMe Direct Connect | | M.2 Connec. |
| | | Prim. | Sec. | #1 | #2 | #3 | | Connectors | Max SSDs | |
| (default in chassis) | HPE DL360 Gen11 x16/x16 Primary Riser | D | N/A | x16 | x16 | N/A | Y | N/A | N/A | N/A |
| P48901-B21 | HPE ProLiant DL360 Gen11 x16 Full Height Riser Kit ¹ | N/A | O | N/A | N/A ¹ | x16 | Y | N/A | N/A | N/A |
| P48903-B21 | HPE ProLiant DL360 Gen11 x16 LP Riser Kit | N/A | O | N/A | N/A | x16 | Y ² | N/A | N/A | N/A |

Notes:

- Prim. = Primary; Sec = Secondary; D = Default on server; O = Optional; N/A = not supported or slot/connector not present.
- Quantity of Processor and Quantity of Heatsink must match.
- All DL360 Gen11 Riser cards are designed in x16 PCIe slot form factor (physical length) as well as in full x16 lanes of PCIe5.0 as electrical bandwidth.
- If secondary riser is selected, then 2 Processors must be selected.
- If secondary riser and "NS204i-u Rear Cbl Kit" are not selected, then maximum 2 quantity of PCIe cards can selected.
- If secondary riser is not selected and "NS204i-u Rear Cbl Kit" is selected, then maximum 1 quantity of PCIe cards can be selected.
- ¹If secondary FH riser is selected, then maximum 2 quantity of PCIe FH cards can be selected, as primary PCIe Slot 2 cannot be used.
- If secondary FH riser is not selected, then maximum 1 quantity of FH PCIe cards can selected.
- If secondary LP riser and "NS204i-u Rear Cbl Kit" are selected, then maximum 2 quantity of PCIe cards can selected.
- If secondary LP riser is selected and "NS204i-u Rear Cbl Kit" is not selected, then maximum 3 quantity of PCIe cards can selected.
- 4 ports base-T Low Profile NIC adapters are not allowed to be installed at Slot 2 (P51178-B21 & P21106-B21)
- ²GPU max 75W



Core Options

PCIe Slotting

| Configuration 1: Primary Riser only (default in chassis) | | |
|--|----------------------|-----------|
| Riser | (Primary as default) | |
| Slot Number | Slot 1 | Slot 2 |
| Bus Width | x16 | x16 |
| Form Factor | FHHL | HHHL (LP) |
| PCIe adapter | Slot Priority | |
| -PCIe x16 | 1 | 2 |
| -PCIe x8 | 1 | 2 |
| -PCIe x4 | 1 | 2 |
| -PCIe x1 | 1 | 2 |

| Configuration 2: Primary Riser (default in chassis) & Secondary FH Riser, 2 CPUs | | | |
|--|----------------------|------------|------------------------|
| Riser | (Primary as default) | | Secondary (P48901-B21) |
| Slot Number | Slot 1 | No support | Slot 3 |
| Bus Width | x16 | | x16 |
| Form Factor | FHHL | | FHHL |
| PCIe adapter | Slot Priority | | |
| -PCIe x16 | 1 | No support | 2 |
| -PCIe x8 | 1 | | 2 |
| -PCIe x4 | 1 | | 2 |
| -PCIe x1 | 1 | | 2 |

| Configuration 3: Primary Riser (default in chassis) & Secondary HH/LP Riser, 2 CPUs | | | |
|---|----------------------------|---|------------------------|
| Riser | (Primary riser as default) | | Secondary (P48903-B21) |
| Slot Number | Slot 1 | Slot 2 (not available for EDSFF CTO Svr) | Slot 3 |
| Bus Width | x16 | x16 | x16 |
| Form Factor | FHHL | HHHL (LP) | HHHL (LP) |
| PCIe adapter | Slot Priority | | |
| -PCIe x16 | 1 | 3 | 2 |
| -PCIe x8 | 1 | 3 | 2 |
| -PCIe x4 | 1 | 3 | 2 |
| -PCIe x1 | 1 | 3 | 2 |
| -2xControllers | 1 | 2 | N No support |

PCIe Adapters Slotting Rules

| General | |
|----------|---|
| Priority | Description & Rules |
| 1 | SR932i-p (P47184-B21) as a FH adapter, can only be slotted in PCIe Slot 1 (fixed cable length) |
| 2 | HPE ProLiant DL360 Gen11 x16 LP Riser Kit (P48903-B21) can only be slotted in HHHL (LP) PCIe Slot |
| 3 | If PCIe Standup Tri-Mode Controller adapter is ordered, can only be slotted in PCIe Slot 1 or Slot2. HHHL (LP) GPGPU card should be slotted in PCIe Slot 3. |
| 4 | PCIe Slot 2 supports HHHL (LP) cards only. |
| 5 | 4-Port Base-T NIC card is not available in Slot2 (Mechanical constraint) |
| 6 | If NS204i-u Rear Cbl Kit (P54702-B21) is ordered, Slot 2 will be unavailable. |



Core Options

| Installation Rules | |
|--------------------|--|
| Priority | Description & Rules |
| 1 | x16 electrical bandwidth card to x16 electric slot |
| 2 | x8 electrical card to x8 electric slot |
| 3 | x8 electrical card to x16 electric slot |

| Priority from Card Types | |
|--------------------------|--|
| Priority | Description & Rules |
| 1 | HPE SR932i-p Gen11 x32 Lanes 8GB Wide Cache PCI SPDM Plug-in Storage Controller (P47182-001) |
| 2 | 4-Port Networking PCIe Adapter (restricted in Slot 2) |
| 3 | HHHI (LP) Internal PCIe Controllers |
| 4 | GPGPU Adapters |
| 5 | Others |

Notes:

- All PCIe slots are featured with Wake-on-Lane (WoL)
- Prioritization list for Primary controller selection in HPE ProLiant DL360 Gen11 8SFF NC CTO Server (P52499-B21) is as follows:
 - o HPE SR932i-p Gen11 24G Controller Kit
 - o HPE MR416i-o Gen11 12G Controller Kit
 - o HPE MR416i-p Gen11 12G Controller Kit
 - o HPE MR408i-o Gen11 SPDM Storage Cntlr
 - o HPE MR216i-o Gen11 12G Controller Kit
 - o HPE MR216i-p Gen11 12G Controller Kit
 - o Intel VROC
 - o Direct Attach

OS Boot Device

| | |
|--|------------|
| HPE NS204i-u Gen11 NVMe Hot Plug Boot Optimized Storage Device | P48183-B21 |
| HPE ProLiant DL360 Gen11 NS204i-u Internal Cable Kit | P48920-B21 |
| HPE ProLiant DL360 Gen11 NS204i-u Rear Cable Kit | P54702-B21 |

| DL360 Gen11 NS204i-u Enablement Kit Support Matrix | | | | |
|--|--|-------------|--------------------------|---------------------|
| Enablement Kit | Description | Field Inst. | NS204i-u Location | Hot-plug Capability |
| P54702-B21 | HPE ProLiant DL360 Gen11 NS204i-u Rear Cable Kit | Yes | PCIe Slot 2 ² | Yes |
| P48920-B21 | HPE ProLiant DL360 Gen11 NS204i-u Internal Cable Kit | Yes | Internal | No support |

Notes:

- ¹x4 PCIe Gen3.0 OS Boot device includes 2x 480GB M.2 NVMe SSDs, with preconfigured hardware RAID1.
- ²With removing the original PCIe Slot 2 cage and re-install the dedicated DL360 Gen11 NS204i-u cage, latch and cables in the P54702-B21. The NS204i-u will take up PCIe Slot 2 space only. The PCIe Slot 1 (FHHL) and PCIe Slot 3 (to be Low Profile) are available in the system with the selection of optional "HPE ProLiant DL360 Gen11 x16 LP Riser Kit (P48903-B21)".
- If NS204i-u is selected, then either NS204i-u Internal or Rear cable must be selected and vice versa.
- Both NS204i-u Internal and Rear cable cannot be selected together.
- If secondary FH riser is selected, then "NS204i-u Rear Cbl Kit" cannot be selected.



Core Options

- If 2SFF U.3 drive cage is connected to Direct Attach (without internal controller & 2SFF controller cable), then SATA drive cannot be selected in 2SFF drive cage when "NS204i-u Gen11 Ht Plg Boot Opt Dev" is selected.
- For additional information, please see the [HPE OS Boot Device QuickSpecs](#)

| NS204i-u thermal Information -4LFF & 8+2 SFF | | | | | | |
|--|-----|--|------------------------|-----------------------|---------------------------|--------------------|
| Location | Qty | Cooling | 4LFF (14W SAS/SATA) | 8+2 SFF (25W NVMe) | 8+2 SFF (10W SAS/SATA) | 8SFF (25W NVMe) |
| Internal NS204i-u | 1 | High Performance Fan Kit (P4-8908-B21) | 30C | 30C | 30C | 30C |
| | 1 | Closed-loop Liquid Cooling Heat Sink Fan FIO Bundle Kit, (P4-8906-B21) | 30C | 30C | 30C | 30C |
| External Hot-plug NS204i-u (at rear) | 1 | High Performance Fan Kit (P4-8908-B21) | 30C | 30C | 30C | 30C |
| | 1 | Closed-loop Liquid Cooling Heat Sink Fan FIO Bundle Kit, (P4-8906-B21) | 30C | 25C ² | 25C | 30C |

Notes:

- ¹If 256GB DIMM is selected, will require limit of ambient at 25C
- ²If 256GB DIMM is selected with up to 10SFF NVMe, will need to operated at 23C. Will not be a feasible configuration to support.
- If NS204i-u is selected, then either NS204i-u Internal or Rear cable must be selected and vice versa.
- Both NS204i-u Internal and Rear cable cannot be selected together.
- If secondary FH riser is selected, then "NS204i-u Rear Cbl Kit" cannot be selected.

Networking

The thermal conditions vary as a combination of types of Networking PCIe OR OCP adapter in different DL360 Gen11 CTO Servers. In general:

- Standard Fan Kit cannot be selected when above 100GbE
- 256GB DIMM is not allowed when above 100GbE
- Ambient limitation will vary in the combination of Networking Adapter OR OCP bandwidth, DIMM capacity and cable type, incl. Direct Attach Copper (DAC) cable and Active Optical Cable (AOC)

A detailed ambient temperature recommendation upon high-speed networking adapters is described in a later session.

Default settings in 8SFF CTO Server and 4LFF CTO Server

- In 1 Processor configuration, "CPU1 to OCP2 x8 Enablement Kit" will be selected as default as "BCM5719 Ethernet 1Gb 4-port BASE-T OCP3 Adapter" is pre-selected at OCP Slot 2, to be defaulted in the configurator if 1 Processor is selected. Customer is allowed to remove if OCP NIC is not selected but need to be replaced by a PCIe standup NIC. Meanwhile, the "CPU1 to OCP2 x8 Enablement Kit" will be removed.
- "CPU2 to OCP2 x8 Enablement Kit" or "CPU2 to OCP2 x16 Enablement Kit" must be selected if OCP NIC is selected in 2 Processors configuration. "CPU2 to OCP2 x8 Enablement Kit" to be defaulted in the configurator if 2 Processors are selected. User should be allowed to remove "CPU2 to OCP2 x8 Enablement Kit" and should be forced select "CPU2 to OCP2 x16 Enablement Kit" if OCP NIC is selected. Customer is allowed to remove if OCP NIC is not selected but need to be replaced by a PCIe standup NIC. Meanwhile, the "CPU2 to OCP2 x8 Enablement Kit" will be removed.

Notes: Exception: Only x8 PCIe5.0 lanes each in the 2 OCP Slots from 20EDSFF CTO Server.



Core Options

InfiniBand PCIe

HPE InfiniBand HDR/Ethernet 200Gb 1-port QSFP56 PCIe4 x16 MCX653105A-HDAT Adapter

P23664-B21

HPE InfiniBand HDR/Ethernet 200Gb 2-port QSFP56 PCIe4 x16 MCX653106A-HDAT Adapter

P31324-B21

Recommended Ambient Temperature & Cooling Solution

| System Config | P23664-B21 or P31324-B21 |
|-------------------------------|--|
| 4LFF or 8SFF NVMe/SAS/SATA | 2x CPU TDP 0-270W: 30C / Air Cooling 2x CPU TDP 271-350W: support 25C (or with DAC cable 30C) / Closed-loop Liquid Cooling 2x CPU TDP 0-350W: 30C / DLC solution |
| 10SFF NVMe/SAS/SATA | 2x CPU TDP 0-270W: 30C / Air Cooling 2x CPU TDP 0-350W: 30C / DLC solution Not Supported. If 2x CPU TDP 271-350W: Not supported. (or special approval is required with DAC cable, 30C) / Closed-loop Liquid Cooling |
| 20EDSFF | 2x CPU TDP 0-350W: 30C / DLC solution Not supported. If 2x CPU TDP 0-270W: it requires <20C (or special approval with DAC cable at 30C) / Air Cooling If 2x CPU TDP 271-350W: It requires <20C (or special approval with DAC cable at 30C) / Closed-loop Liquid Cooling |

Other Restrictions:

1. High Performance Fan Kit is required for above 100GB NIC
2. 256GB DIMMs are not supported if this adapter is selected (or with DLC, support 1DPC, up to 8 DIMMs/per socket)

HPE InfiniBand HDR100/Ethernet 100Gb 1-port QSFP56 PCIe4 x16 MCX653105A-ECAT Adapter

P23665-B21

HPE InfiniBand HDR100/Ethernet 100Gb 2-port QSFP56 PCIe4 x16 MCX653106A-ECAT Adapter

P23666-B21

Recommended Ambient Temperature & Cooling Solution

| System Config | P23665-B21 or P23666-B21 |
|-------------------------------|---|
| 4LFF or 8SFF NVMe/SAS/SATA | 2x CPU TDP 0-270W: 30C / Air Cooling 2x CPU TDP 271-350W: 25C (or with DAC cable 30C) / Closed-loop Liquid Cooling 2x CPU TDP 0-350W: 30C / DLC solution |
| 10SFF NVMe/SAS/SATA | 2x CPU TDP 0-270W: 30C / Air Cooling 2x CPU TDP 271-350W: 25C (or with DAC cable 30C) / Closed-loop Liquid Cooling 2x CPU TDP 0-350W: 30C / DLC solution |
| 20EDSFF | 2x CPU TDP 0-270W: 25C (or with DAC cable 30C) / Air Cooling 2x CPU TDP 0-350W: 30C / DLC solution Not supported. 2x CPU TDP 271-350W: N/A, requires <20C (or special approval with DAC cable at 30C) / Closed-loop Liquid Cooling |

Other Restrictions:

1. High Performance Fan Kit is required for above 100GB NIC
2. 256GB DIMMs are not supported if this adapter is selected. (or with DLC, support 1DPC, up to 8 DIMMs/per socket)

HPE InfiniBand NDR 1-port OSFP PCIe5 x16 MCX75310AAS-NEAT Adapter

P45641-B21

Recommended Ambient Temperature & Cooling Solution

| System Config | P45641-B21 |
|-------------------------------|---|
| 4LFF or 8SFF NVMe/SAS/SATA | 2x CPU TDP 0-270W: 27C (or with DAC cable 30C) / Air Cooling 2x CPU TDP 0-350W: 30C / DLC solution Not supported. |



Core Options

| | |
|---------------------|--|
| | 2x CPU TDP 271-350W: It requires 22C (or special approval with DAC cable at 30C) / Closed-loop Liquid Cooling |
| 10SFF NVMe/SAS/SATA | 2x CPU TDP 0-270W: 27C (or with DAC cable 30C) / Air Cooling 2x CPU TDP 0-350W: 30C / DLC solution |
| | Not supported. 2x CPU TDP 271-350W: Not supported (or special approval with DAC cable 30C) / Closed-loop Liquid Cooling |
| 20EDSFF | 2x CPU TDP 0-270W: 25C (or with DAC cable 30C) / Air Cooling 2x CPU TDP 0-350W: 30C / DLC solution |
| | Not supported. 2x CPU TDP 271-350W: It requires <20C (or special approval with DAC cable at 30C) / Closed-loop Liquid Cooling |

Other Restrictions

1. High Performance Fan Kit is required for above 100GB NIC
2. 256GB DIMMs not supported if this adapter is selected (or with DLC, support 1DPC, up to 8 DIMMs/per socket)

HPE InfiniBand NDR200 1-port OSFP PCIe5 x16 MCX75310AAS-HEAT Adapter

P45642-B21

Recommended Ambient Temperature & Cooling Solution

| System Config | P45642-B21 |
|-------------------------------|--|
| 4LFF or 8SFF NVMe/SAS/SATA | 2x CPU TDP 0-270W: 30C / Air Cooling 2x CPU TDP 0-350W: 30C / DLC solution |
| | Not supported. 2x CPU TDP 271-350W: It requires 23C (or special approval with DAC cable at 30C) / Closed-loop Liquid Cooling |
| 10SFF NVMe/SAS/SATA | 2x CPU TDP 0-270W: 30C / Air Cooling 2x CPU TDP 0-350W: 30C / DLC solution |
| | Not supported. 2x CPU TDP 271-350W: It requires 23C (or special approval with DAC cable at 30C) / Closed-loop Liquid Cooling |
| 20EDSFF | 2x CPU TDP 0-270W: 25C (or with DAC cable 30C) / Air Cooling 2x CPU TDP 0-350W: 30C / DLC solution |
| | Not supported. 2x CPU TDP 271-350W: It requires <20C (or special approval with DAC cable at 30C) / Closed-loop Liquid Cooling |

Other Restrictions

1. High Performance Fan Kit is required for above 100GB NIC
2. 256GB DIMMs not supported if this adapter is selected (or with DLC, support 1DPC, up to 8 DIMMs/per socket)

Notes:

- If 256GB Memory is selected, then high speed Networking/ InfiniBand card (PCIe and OCP) that is 100G or more cannot be selected.
- If 500W Power supply is selected, then x16 Networking/ InfiniBand cannot be selected.
- If configured for a Cray or Slingshot Solution, option to be used as the Slingshot 10 networking card.
- With 2xCPU in the range of 186-270 Watt and NVMe storages, Performance Fan Kit and DAC must be selected; if AOC is selected, can only work below 27C ambient temperature
- With 2xCPU go beyond 271 Watt and NVMe storages, Closed-loop Liquid Cooling Heatsink & Fan bundle kit and DAC must be selected; AOC cannot be supported.
- The InfiniBand HDR Adapters are in PCIe 4.0 x16// FH or LP
- InfiniBand NDR Adapter is in PCIe 5.0 x16// HL/ HH



Core Options

- If the above 100GbE Networking PCIe adapter or OCP adapter is selected, Standard Fan Kit cannot be configured.
- If Closed Loop Liquid cooling is selected with specific high-speed Networking/ InfiniBand HDR 200Gb / InfiniBand NDR 1-port/InfiniBand NDR200 1-port, then SFF NVMe/ EDSFF drive cannot be selected.
- For InfiniBand NDR 1-port OSFP Adapter, in 8SFF CTO Model: If this card is selected with Closed Loop Liquid cooling, then Maximum of 8 NVMe can be selected.
- For InfiniBand NDR200 1-port QSFP Adapter, in 20EDSFF CTO Model: If this card is selected with Closed Loop Liquid cooling, then EDSFF drives cannot be selected.”
- “HPE InfiniBand NDR 1x400Gb OSFP Multi-mode 50m HCA-side Transceiver” is available for “InfiniBand NDR 1-port” & “InfiniBand NDR200 1-port”.

Ethernet PCIe

Intel E810-XXVDA2 Ethernet 10/25Gb 2-port SFP28 Adapter for HPE P08443-B21

Notes: PCIe 4.0 x8// HH or LP

Intel E810-XXVDA4 Ethernet 10/25Gb 4-port SFP28 Adapter for HPE P08458-B21

Notes:

- PCIe 4.0 x16// FH/ HL
- If secondary FH riser is not selected, then maximum 1 quantity of FH PCIe cards can be selected.
- If both 4P Networking (Base-T and Full-Height) and Half-Height Internal PCIe controller are selected, then Secondary FH riser cannot be selected.

Mellanox MCX623105AS-VDAT Ethernet 200Gb 1-port QSFP56 Adapter for HPE P10180-B21

Mellanox MCX623106AS-CDAT Ethernet 100Gb 2-port QSFP56 Adapter for HPE P25960-B21

HPE Slingshot SA210S Ethernet 200Gb 1-port PCIe NIC R4K46A

Recommended Ambient Temperature & Cooling Solution

| System Config | P10180-B21 or P25960-B21 or R4K46A |
|-------------------------------|--|
| 4LFF or 8SFF NVMe/SAS/SATA | 2x CPU TDP 0-270W: 30C / Air Cooling 2x CPU TDP 271-350W: 25C (or with DAC cable 30C) / Closed-loop Liquid Cooling 2x CPU TDP 0-350W: 30C / DLC solution |
| 10SFF NVMe/SAS/SATA | 2x CPU TDP 0-270W: 30C / Air Cooling 2x CPU TDP 0-350W: 30C / DLC solution Not supported. 2x CPU TDP 271-350W: It requires <20C (or special approval with DAC cable at 30C) / Closed-loop Liquid Cooling |
| 20EDSFF | 2x CPU TDP 0-350W: 30C / DLC solution Not supported. 2x CPU TDP 0-270W: It requires <20C (or special approval with DAC cable at 30C) / Air Cooling 2x CPU TDP 271-350W: It requires <20C (or special approval with DAC cable at 30C) / Closed-loop Liquid Cooling |

Other Restrictions

1. High Performance Fan Kit is required for above 100GB NIC
2. 256GB DIMMs not supported if this adapter is selected (or with DLC, support 1DPC, up to 8 DIMMs/per socket)

Notes:

For P10180-B21 or P25960-B21:

- If 256GB Memory is selected, then high speed Networking/ InfiniBand card (PCIe and OCP) that is 100G or more cannot be selected.
- If configured for a Cray or Slingshot Solution, option to be used as the Slingshot 10 networking card.
- PCIe 4.0 x16// HL/ HH/LP
- For R4K46A:



Core Options

- If the above 100GbE Networking PCIe adapter or OCP adapter is selected, Standard Fan Kit cannot be configured.
- Can only be selected or configured for a Cray or Slingshot Solution. Not allowed for a Non-Cray or Non-Slingshot Solution
- Cannot have the following networking options configured within the same server: Slingshot 11 or Slingshot 22.
- PCIe 4.0 x16// LP
- If the above 100GbE Networking PCIe adapter or OCP adapter is selected, Standard Fan Kit cannot be configured.

Intel I350-T4 Ethernet 1Gb 4-port BASE-T Adapter for HPE

P21106-B21

Notes:

- Max 1 of 4 port cards can be selected if secondary riser is not selected. Cannot be installed in Slot# 2.
- Max 2 of 4 port cards can be selected if secondary riser is selected. Cannot be installed in Slot# 2.
- If both 4P Networking (Base-T and Full-Height) and Half-Height Internal PCIe controller are selected, then Secondary FH riser cannot be selected.
- PCIe 2.0 x4 // HH /HL/ LP

Intel E810-CQDA2 Ethernet 100Gb 2-port QSFP28 Adapter for HPE

P21112-B21

Recommended Ambient Temperature & Cooling Solution

| System Config | P21112-B21 |
|----------------------------|--|
| 4LFF or 8SFF NVMe/SAS/SATA | 2x CPU TDP 0-270W: 30C / Air Cooling 2x CPU TDP 271-350W: 25C (or with DAC cable 30C) / Closed-loop Liquid Cooling 2x CPU TDP 0-350W: 30C / DLC solution |
| 10SFF NVMe/SAS/SATA | 2x CPU TDP 0-270W: 30C / Air Cooling 2x CPU TDP 271-350W: 25C (or with DAC cable 30C) / Closed-loop Liquid Cooling 2x CPU TDP 0-350W: 30C / DLC solution |
| 20EDSFF | 2x CPU TDP 0-270W: 25C (or with DAC cable 30C) / Air Cooling 2x CPU TDP 0-350W: 30C / DLC solution |
| | Not supported. 2x CPU TDP 271-350W: It, requires <20C (or special approval with DAC cable at 30C) / Closed-loop Liquid Cooling |

Other Restrictions

1. High Performance Fan Kit is required for above 100GB NIC
2. 256GB DIMMs not supported if this adapter is selected (or with DLC, support 1DPC, up to 8 DIMMs/per socket)

Notes:

- If 256GB Memory is selected, then high speed Networking/ InfiniBand card (PCIe and OCP) that is 100G or more cannot be selected.
- PCIe 4.0 x16// HL/ HH
- If above 100GbE Networking PCIe adapter or OCP adapter is selected, Standard Fan Kit cannot be configured.

Broadcom BCM57416 Ethernet 10Gb 2-port BASE-T Adapter for HPE

P26253-B21

Notes: PCIe 3.0 x8// HH/ HL/ LP

Broadcom BCM57412 Ethernet 10Gb 2-port SFP+ Adapter for HPE

P26259-B21

Notes: PCIe 3.0 x8// HH/ HL/ LP

Broadcom BCM57414 Ethernet 10/25Gb 2-port SFP28 Adapter for HPE

P26262-B21

Notes: PCIe 3.0 x8// HH/ HL/ LP



Core Options

Broadcom BCM57504 Ethernet 10/25Gb 4-port SFP28 Adapter for HPE P26264-B21

Notes: PCIe 4.0 x16// HH/ HL/ LP

Mellanox MCX631102AS-ADAT Ethernet 10/25Gb 2-port SFP28 Adapter for HPE P42044-B21

Notes: PCIe 4.0 x8// HH/ HL/ LP

Broadcom BCM5719 Ethernet 1Gb 4-port BASE-T Adapter for HPE P51178-B21

Notes:

- Max 1 of 4 port cards can be selected if secondary riser is not selected. Cannot be installed in Slot# 2.
- Max 2 of 4 port cards can be selected if secondary riser is selected. Cannot be installed in Slot# 2.
- If both 4P Networking (Base-T and Full-Height) and Half-Height Internal PCIe controller are selected, then Secondary FH riser cannot be selected.
- PCIe 2.0 x4// HH/ HL/ LP

Ethernet OCP

2 OCP slots in Motherboard additionally. Does not consume PCIe slot.

Intel I350-T4 Ethernet 1Gb 4-port BASE-T OCP3 Adapter for HPE P08449-B21

Broadcom BCM57416 Ethernet 10Gb 2-port BASE-T OCP3 Adapter for HPE P10097-B21

Intel E810-XXVDA4 Ethernet 10/25Gb 4-port SFP28 OCP3 Adapter for HPE P41614-B21

Intel E810-XXVDA2 Ethernet 10/25Gb 2-port SFP28 OCP3 Adapter for HPE P10106-B21

Broadcom BCM57414 Ethernet 10/25Gb 2-port SFP28 OCP3 Adapter for HPE P10115-B21

Recommended Ambient Temperature & Cooling Solution

| System Config | P10115-B21 |
|-------------------------------|---|
| 4LFF or 8SFF NVMe/SAS/SATA | 2x CPU TDP 0-270W: 30C / Air Cooling 2x CPU TDP 271-350W: 25C (or with DAC cable 30C) / Closed-loop Liquid Cooling 2x CPU TDP 0-350W: 30C / DLC solution |
| 10SFF NVMe/SAS/SATA | 2x CPU TDP 0-270W: 30C / Air Cooling 2x CPU TDP 271-350W: 25C (or with DAC cable 30C) / Closed-loop Liquid Cooling 2x CPU TDP 0-350W: 30C / DLC solution: |
| 20EDSFF | 2x CPU TDP 0-270W: 30C / Air Cooling 2x CPU TDP 0-350W: 30C / DLC solution Not supported. 2x CPU TDP 271-350W: It requires <20C (or special approval with DAC cable at 30C) / Closed-loop Liquid Cooling |

Intel E810-CQDA2 Ethernet 100Gb 2-port QSFP28 OCP3 Adapter for HPE P22767-B21



Core Options

| Recommended Ambient Temperature & Cooling Solution | |
|--|--|
| System Config | P22767-B21 |
| 4LFF or 8SFF NVMe/SAS/SATA | 2x CPU TDP 0-270W: 30C / Air Cooling 2x CPU TDP 0-350W: 30C / DLC solution Not supported. 2x CPU TDP 271-350W: It requires 22C (or special approval with DAC cable at 30C) / Closed-loop Liquid Cooling |
| 10SFF NVMe/SAS/SATA | 2x CPU TDP 0-270W: 30C / Air Cooling 2x CPU TDP 0-350W: 30C / DLC solution Not supported. 2x CPU TDP 271-350W: It requires 22C (or special approval with DAC cable at 30C) / Closed-loop Liquid Cooling |
| 20EDSFF | 2x CPU TDP 0-270W: 25C (with DAC cable 30C) / Air Cooling 2x CPU TDP 0-350W: 30C / DLC solution Not supported. 2x CPU TDP 271-350W: It requires <20C (or special approval with DAC cable at 30C) / Closed-loop Liquid Cooling |

Other Restrictions

- High Performance Fan Kit is required for above 100GB NIC
- 256GB DIMMs not supported if this adapter is selected (or with DLC, support 1DPC, up to 8 DIMMs/per socket)

Notes:

- If 256GB Memory is selected, then high speed Networking/ InfiniBand card (PCIe and OCP) that is 100G or more cannot be selected.
- If no OCP enablement kit is selected, then x16 OCP cannot be selected.
- If any one of "CPU1 to OCP1 x16" or "CPU2 to OCP2 x16" is selected, then Max 1 of x16 (>=100G) card can be selected per server.
- If both "CPU1 to OCP1 x16" and "CPU2 to OCP2 x16" are selected, then Maximum 2 of x16 (>=100G) card can be selected per server.
- If selected with 350W Processor with low Tcase (6458Q/ 8470Q), Closed-loop Liquid Cooling Heat Sink Fan FIO Bundle Kit must be selected, only 8x SATA drive can be selected. And limit ambient temperature at 25C is required.
- If above 100GbE Networking PCIe adapter or OCP adapter is selected, Standard Fan Kit cannot be configured.

Broadcom BCM57412 Ethernet 10Gb 2-port SFP+ OCP3 Adapter for HPE

P26256-B21

Broadcom BCM57504 Ethernet 10/25Gb 4-port SFP28 OCP3 Adapter for HPE

P26269-B21

Notes:

- Warning Message has to be displayed in the configurator any time this OCP card is selected: "CPU1 to OCP1 x16" or "CPU2 to OCP2 x16" OCP Upgrade kit can be selected with this OCP card if customer wants to have OCP x16 connectivity. With below restriction:
 - OCP Slot 2 is the default OCP networking slot with the Share NIC & Wake-on-Lane features. The "CPU1 to OCP1 x16" will be available in only one OCP Networking card configuration, after April 2023.
 - Yet the "CPU2 to OCP2x16" OCP Upgrade kit will be only available in two processor configurations.

Mellanox MCX631432AS-ADAI Ethernet 10/25Gb 2-port SFP28 OCP3 Adapter for HPE

P42041-B21

Broadcom BCM5719 Ethernet 1Gb 4-port BASE-T OCP3 Adapter for HPE

P51181-B21

Notes: "BCM 5719 1Gb 4p BASE-T OCP Adptr" to be defaulted in the configurator. Customer is allowed to remove and select other cards (PCIe or OCP) from Networking OR InfiniBand OR Smart IO (HW) OR Storage Offload category.



Core Options

Fibre Channel HBA

| | |
|--|--------|
| HPE SN1610Q 32Gb 1-port Fibre Channel Host Bus Adapter | R2E08A |
| HPE SN1610Q 32Gb 2-port Fibre Channel Host Bus Adapter | R2E09A |
| HPE SN1610E 32Gb 1-port Fibre Channel Host Bus Adapter | R2J62A |
| HPE SN1610E 32Gb 2-port Fibre Channel Host Bus Adapter | R2J63A |

Notes: PCIe 3.0 x8// FH or LP for SN1610Q/1610E

| | |
|--|--------|
| HPE SN1700E 64Gb 1-port Fibre Channel Host Bus Adapter | R7N77A |
| HPE SN1700E 64Gb 2-port Fibre Channel Host Bus Adapter | R7N78A |
| HPE SN1700Q 64Gb 1-port Fibre Channel Host Bus Adapter | R7N86A |
| HPE SN1700Q 64Gb 2-port Fibre Channel Host Bus Adapter | R7N87A |

Notes: PCIe 4.0 x8// FH or LP for SN1700QE 1-port and 2-port

Transceiver

| | |
|--|------------|
| HPE BladeSystem c-Class Virtual Connect 1G SFP SX Transceiver | 453151-B21 |
| HPE BladeSystem CClass Virtual Connect 1G SFP RJ45 Transceiver | 453154-B21 |
| HPE BladeSystem c-Class 10Gb SFP+ SR Transceiver | 455883-B21 |
| HPE BladeSystem c-Class 10Gb SFP+ LR Transceiver | 455886-B21 |
| HPE 25Gb SFP28 SR 100m Transceiver | 845398-B21 |
| HPE 100Gb QSFP28 MPO SR4 100m Transceiver | 845966-B21 |
| HPE QSFP28 to SFP28 Adapter | 845970-B21 |
| HPE InfiniBand NDR/Ethernet 1x400Gb OSFP Multi-mode 50m HCA-side Transceiver | P49764-B21 |

Notes: Requires selection of NDR InfiniBand card, "HPE IB NDR 1p OSFP MCX75310AAS Adptr" or "HPE IB NDR200 1p OSFP MCX75310AAS Adptr".

| | |
|--|--------|
| HPE 100GbE QSFP28 SR4 100m Transceiver | Q2F19A |
|--|--------|

Notes:

- Each storage offload card requires selection of 2 QTY (Min/Max=2 per card) of either "100GbE QSFP28 PSM4 500m XCVR" OR "100GbE QSFP28 SR4 100m XCVR" transceivers or Q9S71A "HPE 100GbE QSFP28 to QSFP28 5m AOC".
- Configurator has to default 2 QTY of "100GbE QSFP28 SR4 100m XCVR" per storage offload card selection. However, customer is allowed to deselect "100GbE QSFP28 SR4 100m XCVR" and must select "100GbE QSFP28 PSM4 500m XCVR" OR Q9S71A "HPE 100GbE QSFP28 to QSFP28 5m AOC".
- If these transceivers are selected, then Storage offload card must be selected.
- Selection of this transceiver must be in multiples of 2.

| | |
|--|--------|
| HPE 100GbE QSFP28 500m 1310mm PSM4 Transceiver | Q8J73A |
|--|--------|

Notes:

- Each storage offload card requires selection of 2 QTY (Min/Max=2 per card) of either "100GbE QSFP28 PSM4 500m XCVR" OR "100GbE QSFP28 SR4 100m XCVR" transceivers OR Q9S71A "HPE 100GbE QSFP28 to QSFP28 5m AOC".
- Configurator has to default 2 QTY of "100GbE QSFP28 SR4 100m XCVR" per storage offload card selection. However, customer is allowed to deselect "100GbE QSFP28 SR4 100m XCVR" and must select "100GbE QSFP28 PSM4 500m XCVR" OR Q9S71A "HPE 100GbE QSFP28 to QSFP28 5m AOC".
- If these transceivers are selected, then Storage offload card must be selected.
- Selection of this transceiver must be in multiples of 2.



Core Options

HPE 100GbE QSFP28 to QSFP28 5m Active Optical Cable

Q9S71A

Notes:

- Each storage offload card requires selection of 2 QTY (Min/Max=2 per card) of either "100GbE QSFP28 PSM4 500m XCVR" OR "100GbE QSFP28 SR4 100m XCVR" transceivers" OR Q9S71A "HPE 100GbE QSFP28 to QSFP28 5m AOC".
- Configurator has to default 2 QTY of "100GbE QSFP28 SR4 100m XCVR" per storage offload card selection. However, customer is allowed to deselect "100GbE QSFP28 SR4 100m XCVR" and must select "100GbE QSFP28 PSM4 500m XCVR" OR Q9S71A "HPE 100GbE QSFP28 to QSFP28 5m AOC".
- If these transceivers are selected, then Storage offload card must be selected.
- Category max is not applicable. However, 2 QTY (Min/ Max=2) per storage offload card to be selected.
- The selection of this AOC cable must be in multiples of 2.

OCP3.0 Slot Priority Support Matrix – 4LFF, 8+2 SFF & 20EDSFF CTO Server

| DL360 Gen11 Rear wall | | Selected OCP cards (Qty & type) | | | | |
|-----------------------|--------------------------------|---|---------------|---------------|-------------------------|-----------------------------|
| | | 2 | 1 | 1 | 1 | 2 |
| OCP Slots # | Share NIC Feature | 1xOROC ¹ + 1x NIC ² | 1xNIC | 2xNICs | 1xOROC | 2x OROCs |
| 1 | N/A | OROC | (Secondary) | NIC | OROC (Primary) | OROC ⁴ (Primary) |
| 2 | Available (Incl. Wake-on-Lane) | NIC | NIC (Primary) | NIC (Primary) | No support ³ | OROC ⁴ |

Notes:

- ¹OCP form factor internal controller
- ²OCP Networking card
- ³If only 1 OROC card is selected, by default connected from 8SFF backplane to OCP Slot1. And there is no controller cable that can connect from 8SFF Backplane to OCP Slot 2.
- ⁴If 2 OROC cards are selected, by default the 8SFF controller cable is connected to OCP Slot1 (the comparably higher-end OROC card to be selected by default) and the 2SFF backplane is connected to OCP Slot2 with another OROC card selected (comparably less high-end one) with 2FF controller cable.

OCP3.0 Enablement Kits – 4LFF & 8+2 SFF CTO Server

| PCIe signal | Upgrade Cable Kits | | PCIe5.0 lanes availability | |
|-------------|-------------------------|---|----------------------------|-------------|
| | Orderable SKU | Description | OCP Slot #1 | OCP Slot #2 |
| CPU1 | | (x8 PCIe5.0 embedded from MLB) | (default x8) | No support |
| | P51911-B21 ¹ | HPE ProLiant DL360 Gen11 CPU1 to OCP2 x8 Enablement Kit | (default x8) | X8 |
| | P48827-B21 ² | HPE ProLiant DL3XX Gen11 OCP1 x16 Enablement Kit | x16 | No support |
| CPU1 & CPU2 | P48828-B21 | HPE ProLiant DL3XX Gen11 OCP2 x16 Enablement Kit | (default x8) | x16 |
| | P48827-B21 & P48828-B21 | HPE ProLiant DL3XX Gen11 OCP1 x16 Enablement Kit HPE ProLiant DL3XX Gen11 OCP2 x16 Enablement Kit | x16 | x16 |
| | P48830-B21 | HPE ProLiant DL3XX Gen11 CPU2 to OCP2 x8 Enablement Kit | (default x8) | x8 |
| | P51911-B21 ³ | HPE ProLiant DL360 Gen11 CPU1 to OCP2 x8 Enablement Kit | (default x8) | x8 |
| | P48827-B21 & P48830-B21 | HPE ProLiant DL3XX Gen11 OCP1 x16 Enablement Kit HPE ProLiant DL3XX Gen11 CPU2 to OCP2 x8 Enablement Kit | x16 | x8 |

Notes:

- ¹OCP Slot 2 is the primary slot for OCP NIC card for its Share NIC (incl. WoL) feature. When only 1 OCP NIC is selected, the P51911-B21 will be populated.



Core Options

- ²in 1 CPU configuration, to offer flexibility for customers to assign OCP NIC to Slot 1 (if Share NIC & WoL are not required), the P48827-B21 can be manually selected, and P51911-B21 will be removed when P48827-B21 is selected. (The 2 cables cannot co-exist in 1 CPU configuration)
- ³in 2 CPUs Configuration, to connect all OCP Slots from CPU1, the P51911-B21 can be selected.

OCP Slotting - 4LFF & 8+2 SFF CTO Server

Configuration 1: No OCP enablement kit or only P48827-B21 is selected

| Slot Number | Slot 1 | Slot 2 (Share NIC, incl. Wake-on-Lane) |
|----------------|---------------------|--|
| OCP Enablement | N/A or P48827-B21 | No support |
| Bus Width | x8 (default) or x16 | No support |
| OCP adapter | | Slot Priority |
| -Controller | 1 | No support |
| -Networking | 1 | No support |

Configuration 2: Only P51911-B21 is selected

| Slot Number | Slot 1 | Slot 2 (Share NIC, incl. Wake-on-Lane) |
|----------------|--------------|--|
| OCP Enablement | N/A | P51911-B21 |
| Bus Width | x8 (default) | x8 |
| OCP adapter | | Slot Priority |
| -Controller | 1 | 2 |
| -Networking | 2 | 1 |

Configuration 3: Only P48830-B21 is selected, or both P48827-B21 & P48830-B21 are selected

| Slot Number | Slot 1 | Slot 2 (Share NIC, incl. Wake-on-Lane) |
|----------------|---------------------|--|
| OCP Enablement | N/A or P48827-B21 | P48830-B21 |
| Bus Width | x8 (default) or x16 | x8 |
| OCP adapter | | Slot Priority |
| -Controller | 1 | 2 |
| -Networking | 2 | 1 |

Configuration 4: Only P48828-B21 is selected, or both P48827-B21 & P48828-B21 are selected

| Slot Number | Slot 1 | Slot 2 (Share NIC, incl. Wake-on-Lane) |
|----------------|---------------------|--|
| OCP Enablement | N/A or P48827-B21 | P48828-B21 |
| Bus Width | x8 (default) or x16 | x16 |
| OCP adapter | | Slot Priority |
| -Controller | 1 | 2 |
| -Networking | 2 | 1 |

OCP3.0 Enablement Kits – 20EDSFF CTO Server

| PCIe signal | Upgrade Cable Kit | | PCIe5.0 lanes availability | |
|-------------|-------------------|---|----------------------------|-------------|
| | Orderable SKU | Description | OCP Slot #1 | OCP Slot #2 |
| CPU1 & CPU2 | | (x8 PCIe5.0 embedded from MLB) | (default x8) | No support |
| | P48830-B21 | HPE ProLiant DL3XX Gen11 CPU2 to OCP2 x8 Enablement Kit | (default x8) | x8 |

Notes: "CPU1 to OCP1 x16" (P48827-B21)/ "CPU2 to OCP2 x16" (P48828-B21)/ "CPU1 to OCP2 x8" (P51911-B21) cannot be selected, as Port 9, 10, 11 are by default connected to front storages.



Core Options

| OCP Slotting - 20EDSFF CTO Server | | |
|--|---------------|--|
| Configuration: No OCP enablement kit or P48830-B21 is selected | | |
| Slot Number | Slot 1 | Slot 2 (Share NIC, incl. Wake-on-Lane) |
| OCP Enablement | N/A | NA or P48830-B21 |
| Bus Width | x8 (default) | x8 |
| OCP adapter | Slot Priority | |
| -Controller | 1 | 2 |
| -Networking | 2 | 1 |

| OCP Cards Slotting Rules – 4LFF, 8+2 SFF & 20EDSFF CTO Server | |
|---|---|
| General | |
| Priority | Description & Rules |
| 1 | OCP Networking card to be installed in Slot 2 as priority, as the Slot 2 supports ShareNIC (incl. Wake-on-Lane). |
| 2 | 2x OCP Controllers (OROC): Tri-Mode Controllers are in higher priority than SAS Controllers. |
| 3 | 2x OCP Networking cards: High Speed NIC is in higher priority to be installed in Slot 2. |
| 4 | If no OCP Slot 2 Enablement Kit is selected, the OCP Slot 2 is occupied. |
| 5 | If no OCP Slot 1 Enablement Kit is selected, the OCP Slot 1 is default in x8 electrical lanes (embedded from MLB) |

OCP3.0 Enablement Kit details

- In 1 Processor configuration, “CPU1 to OCP2 x8 Enablement Kit” will be selected as default as “BCM5719 Ethernet 1Gb 4-port BASE-T OCP3 Adapter” is pre-selected at OCP Slot 2, to be defaulted in the configurator if 1 Processor is selected. Customer is allowed to remove if OCP NIC is not selected but need to be replaced by a PCIe standup NIC. Meanwhile, the “CPU1 to OCP2 x8 Enablement Kit” will be removed.
- “CPU2 to OCP2 x8 Enablement Kit” or “CPU2 to OCP2 x16 Enablement Kit” must be selected if OCP NIC is selected in 2 Processors configuration. “CPU2 to OCP2 x8 Enablement Kit” to be defaulted in the configurator if 2 Processors are selected. User should be allowed to remove “CPU2 to OCP2 x8 Enablement Kit” and should be forced select “CPU2 to OCP2 x16 Enablement Kit” if OCP NIC is selected. Customer is allowed to remove if OCP NIC is not selected but need to be replaced by a PCIe standup NIC. Meanwhile, the “CPU2 to OCP2 x8 Enablement Kit” will be removed.
- Exception: Only x8 PCIe5.0 lanes each in the 2 OCP Slots from 20EDSFF CTO Server.

HPE ProLiant DL3XX Gen11 OCP1 x16 Enablement Kit

P48827-B21

Notes:

- For 2SFF U.3 drive cage selection in 1 Processor configuration:
If 2SFF Drive cage is connected to Direct Attach (without Internal controller and 2SFF cable) and NVMe drive is selected, then "CPU1 to OCP2 x8" and "OCP1 x16" OCP upgrade kit cannot be selected.
- If no OCP enablement kit is selected, then x16 OCP cannot be selected. And max 1 of OCP/ OROC can be selected.
- "CPU1 to OCP2 x8" and "CPU1 to OCP1 x16" cannot be selected together.
- If any one of "CPU1 to OCP1 x16" or "CPU2 to OCP2 x16" is selected, then Max 1 of x16 (>=100G) card can be selected per server.
- If both "CPU1 to OCP1 x16" and "CPU2 to OCP2 x16" are selected, then Maximum 2 of x16 (>=100G) card can be selected per server.
- If 8SFF x4 and 2SFF Drive cages are selected without controller, then "CPU1 to OCP1 x16" and "CPU1 to OCP2 x8" cannot be selected.
- "CPU1 to OCP1 x16" or "CPU2 to OCP2 x16" OCP Upgrade kit can be selected with OCP card if customer wants to have OCP x16 connectivity.
- Not available for 20EDSFF CTO Server.



Core Options

HPE ProLiant DL3XX Gen11 OCP2 x16 Enablement Kit

P48828-B21

Notes:

- If no OCP enablement kit is selected, then Max 1 of OCP/ OROC can be selected, and x16 OCP cannot be selected.
- "CPU2 to OCP2 x16" and "CPU2 to OCP2 x8" cannot be selected together.
- If "CPU2 to OCP2 x16" or "CPU2 to OCP2 x8" is selected, then 2 Processors must be selected.
- If any one of "CPU1 to OCP1 x16" or "CPU2 to OCP2 x16" is selected, then Max 1 of x16 (>=100G) card can be selected per server.
- If both "CPU1 to OCP1 x16" and "CPU2 to OCP2 x16" are selected, then Maximum 2 of x16 (>=100G) card can be selected per server.
- "CPU1 to OCP1 x16" or "CPU2 to OCP2 x16" OCP Upgrade kit can be selected with this OCP card if customer wants to have OCP x16 connectivity.
- Not available for 20EDSFF CTO Server.

HPE ProLiant DL3XX Gen11 CPU2 to OCP2 x8 Enablement Kit

P48830-B21

Notes:

- To be defaulted in the configurator if 2 Processor is selected. Customer is allowed to remove if OCP card is not selected.
- If no OCP enablement kit is selected, then x16 OCP cannot be selected. And Max 1 of OCP/ OROC can be selected.
- "CPU2 to OCP2 x16" and "CPU2 to OCP2 x8" cannot be selected together.
- If "CPU2 to OCP2 x16" or "CPU2 to OCP2 x8" is selected, then 2 Processor must be selected.
- Available for 20EDSFF CTO Server.

HPE ProLiant DL360 Gen11 CPU1 to OCP2 x8 Enablement Kit

P51911-B21

Notes:

- For 2SFF U.3 drive cage selection in 1 Processor configuration:
If 2SFF Drive cage is connected to Direct Attach (without Internal controller and 2SFF cable) and NVMe drive is selected, then "CPU1 to OCP2 x8" and "OCP1 x16" OCP upgrade kit cannot be selected.
- To be defaulted in the configurator if 1 Processor is selected. Customer is allowed to remove if OCP card is not selected.
- If no OCP enablement kit is selected, then x16 OCP cannot be selected.
- "CPU1 to OCP2 x8" and "CPU1 to OCP1 x16" cannot be selected together.
- "CPU1 to OCP2 x8" cannot be selected if 2 Processor is selected.
- If 8SFF x4 and 2SFF Drive cages are selected without controller, then "CPU1 to OCP1 x16" and "CPU1 to OCP2 x8" cannot be selected.
- Not available for 20EDSFF CTO Server.

OCP Infiniband

HPE InfiniBand HDR/Ethernet 200Gb 1-port QSFP56 PCIe4 x16 OCP3 MCX653435A-HDAI Adapter

P31323-B21

| Recommended Ambient Temperature & Cooling Solution | |
|--|---|
| System Config | P31323-B21 |
| 4LFF or 8SFF NVMe/SAS/SATA | 2x CPU TDP 0-270W: 25C (or with DAC cable 30C) / Air Cooling 2x CPU TDP 0-350W: 25C / DLC solution Not supported. 2x CPU TDP 271-350W: It requires <20C (or special approval with DAC cable at 25C) / Closed-loop Liquid Cooling |
| 10SFF NVMe/SAS/SATA | 2x CPU TDP 0-350W: 25C / DLC solution Not supported. 2x CPU TDP 0-270W: It requires <20C (or special approval with DAC cable at 30C) / Air Cooling |



Core Options

| | |
|---------|--|
| | 2x CPU TDP 271-350W: It requires <20C (or special approval with DAC cable at 25C) / Closed-loop Liquid Cooling |
| 20EDSFF | 2x CPU TDP 0-270W: 25C (or with DAC cable 30C) / Air Cooling 2x CPU TDP 0-350W: 25C / DLC solution |
| | Not supported. 2x CPU TDP 271-350W: It requires <20C / Closed-loop Liquid Cooling |

Other Restrictions

1. High Performance Fan Kit is required for above 100GB NIC
2. 256GB DIMMs not supported if this adapter is selected (or with DLC, support 1DPC, up to 8 DIMMs/per socket)

HPE InfiniBand HDR/Ethernet 200Gb 2-port QSFP56 PCIe4 x16 OCP3 MCX653436A-HDAI Adapter

P31348-B21

Recommended Ambient Temperature & Cooling Solution

| System Config | P31348-B21 |
|-------------------------------|--|
| 4LFF or 8SFF NVMe/SAS/SATA | 2x CPU TDP 0-270W: 25C (with DAC cable 30C) / Air Cooling 2x CPU TDP 0-350W: 25C / DLC solution Not supported. 2x CPU TDP 271-350W: It requires <20C (or special approval with DAC cable at 25C) / Closed-loop Liquid Cooling |
| 10SFF NVMe/SAS/SATA | 2x CPU TDP 0-350W: 25C / DLC solution Not supported. 2x CPU TDP 0-270W: It requires <20C (or special approval with DAC cable at 30C) / Air Cooling 2x CPU TDP 271-350W: It requires <20C (or special approval with DAC cable 30C) / Closed-loop Liquid Cooling |
| 20EDSFF | 2x CPU TDP 0-165W: 25C (or with DAC cable 30C) / Air Cooling 2x CPU TDP 0-350W: 25C / DLC solution Not supported. 2x CPU TDP 166W-270W: It requires 24C/Air cooling 2x CPU TDP 166W-270W: It requires <20 C/ with Closed-loop LC 2x CPU TDP 271-350W: It requires <20C / Closed-loop Liquid Cooling |

Other Restrictions

1. High Performance Fan Kit is required for above 100GB NIC
2. 256GB DIMMs not supported if this adapter is selected (or with DLC, support 1DPC, up to 8 DIMMs/per socket)

Notes:

- If 256GB Memory is selected, then high speed Networking/ InfiniBand card (PCIe and OCP) that is 100G or more cannot be selected.
- If configured for a Cray or Slingshot Solution, option to be used as the Slingshot 10 networking card.
- If selected with 350W Processor with low Tcase (6458Q/ 8470Q), Closed-loop Liquid Cooling Heatsink Fan FIO Bundle Kit must be chosen, and NVMe and SAS drive cannot be selected. Only max 8SFF SATA drive can be supported.
- If no OCP enablement kit is selected, then x16 OCP cannot be selected.
- If any one of “CPU1 to OCP1 x16” or “CPU2 to OCP2 x16” is selected, then Max 1 of x16 (>=100G) card can be selected per server.
- If both “CPU1 to OCP1 x16” and “CPU2 to OCP2 x16” are selected, then Maximum 2 of x16 (>=100G) card can be selected per server.
- If the above 100GbE Networking PCIe adapter or OCP adapter is selected, Standard Fan Kit cannot be configured.
- If the selected processor(s) is/are in the range of 271W to 350W TDP, and AOC cable is also selected, the ambient temperature would be limit at 25C



Core Options

Storage Offload

HPE NV60100M 100Gb 2-port Storage Offload Adapter

R8M41A

| Recommended Ambient Temperature & Cooling Solution | |
|--|--|
| System Config | R8M41A |
| 4LFF or 8SFF NVMe/SAS/SATA | 2x CPU TDP 0-270W: 30C / Air Cooling |
| | 2x CPU TDP 271-350W: 25C (or with DAC cable 30C) / Closed-loop Liquid Cooling |
| | 2x CPU TDP 0-350W: 30C / DLC solution |
| 10SFF NVMe/SAS/SATA | 2x CPU TDP 0-270W: 30C / Air Cooling |
| | 2x CPU TDP 0-350W: 30C / DLC solution |
| | Not supported. 2x CPU TDP 271-350W: Not supported (or with DAC cable 30C) / Closed-loop Liquid Cooling |
| 20EDSFF | 2x CPU TDP 0-350W: 30C / DLC solution |
| | Not supported. |
| | 2x CPU TDP 0-270W: It requires <20C (or special approval with DAC cable 30C) / Air Cooling 2x CPU TDP 271-350W: It requires <20C (or special approval with DAC cable at 30C) / Closed-loop Liquid Cooling |

Notes:

- PCIe 3.0 x16// HL/ HH
- If 256GB Memory is selected, then high speed Networking/ InfiniBand card (PCIe and OCP) that is 100G or more cannot be selected.
- Each storage offload card requires selection of 2 QTY (Min/Max=2 per card) of either Q8J73A "100GbE QSFP28 PSM4 500m XCVR" OR Q2F19A "100GbE QSFP28 SR4 100m XCVR" transceivers OR "HPE 100GbE QSFP28 to QSFP28 5m AOC"
- Configurator defaults with 2 QTY of "100GbE QSFP28 SR4 100m XCVR" per storage offload card selection. However, customer is allowed to deselect "100GbE QSFP28 SR4 100m XCVR" and must select "100GbE QSFP28 PSM4 500m XCVR" OR Q9S71A "HPE 100GbE QSFP28 to QSFP28 5m AOC".
- If 500W Power supply is selected, then x16 Networking/ InfiniBand cannot be selected.
- If above 100GbE Networking PCIe adapter or OCP adapter is selected, then Performance Heatsink or Closed Loop Liquid Cooling Heatsink or DLC Module must be selected.
- For EDSFF CTO Model:
If Closed Loop Liquid cooling is selected with specific high-speed Networking/ InfiniBand, then EDSFF drive cannot be selected.
- If 256GB DIMM is selected without DLC Module, then high speed Networking/ InfiniBand card (PCIe and OCP) that is 100G or more cannot be selected.

HPE Ethernet 10/25Gb 2-port Secure Network Adapter

S2A69A



Core Options

Thermal condition for High Speed Networking Adapter

| Networking PCIe adapter beyond 100GbE vs Maximum drive Qty | | | | | | |
|---|-----|---|---|--|--|--|
| Part number | Qty | Cooling | 4LFF (14W SAS/SATA) | 8+2 SFF (25W NVMe) | 8+2 SFF (10W SAS/SATA) | 8SFF (25W NVMe) |
| P25960-B21 ¹ , P10180-B21 ² , R8M41A ³ , P31324-B21 ⁴ , P21112-B21 ⁵ , P23665-B21 ⁶ , P23666-B21 ⁷ , P23664-B21 ¹⁰ | 3 | High Perf. Fan Kit, (P48908-B21) | Up to 2x270W CPU, 32x 128GB DIMMs | | | |
| | | | 30C | 30C | 30C | 30C |
| | 3 | Closed-loop LC Heat Sink Fan FIO Bundle Kit, (P48906-B21) | Up to 2x350W CPU, 32x 128GB DIMMs | | | |
| | | | 30C with DAC ⁸ ; 25C with AOC ⁹ | No support 30C with DAC ⁸ ; 20C with AOC ⁹ | 30C with DAC ⁸ ; 25C with AOC ⁹ | 30C, **30C with DAC, 25C with AOC ^{3,4} |
| | 3 | Direct LC + Perf. Fan Kit (P48908-B21) | Up to 2x350W CPU, 32x 128 GB or 16x 256GB DIMMs (1DPC, 16DIMMs per socket) | | | |
| | | | 30C | 30C | 30C | 30C |

Notes:

- ¹ Mellanox MCX623106AS-CDAT Ethernet 100Gb 2-port QSFP56 Adapter for HPE
- ² Mellanox MCX623105AS-VDAT Ethernet 200Gb 1-port QSFP56 Adapter for HPE
- ³ HPE NV60100M 100Gb 2-port Storage Offload Adapter
- ⁴ HPE InfiniBand HDR/Ethernet 200Gb 2-port QSFP56 PCIe4 x16 MCX653106A-HDAT Adapter
- ⁵ Intel E810-CQDA2 Ethernet 100Gb 2-port QSFP28 Adapter for HPE
- ⁶ HPE InfiniBand HDR100/Ethernet 100Gb 1-port QSFP56 PCIe4 x16 MCX653105A-ECAT Adapter
- ⁷ HPE InfiniBand HDR100/Ethernet 100Gb 2-port QSFP56 PCIe4 x16 MCX653106A-ECAT Adapter
- ⁸ Direct Attach Copper cable
- ⁹ Active Optical Cable
- 256GB DIMM cannot be selected if above 100GbE Networking Adapter or OCP Adapter is selected.
- ¹⁰ HPE InfiniBand HDR/Ethernet 200Gb 1-port QSFP56 PCIe4 x16 MCX653105A-HDAT Adapter
- For 20EDSFF CTO Server thermal condition, please refer to the “Recommended Ambient Temperature” section under each part number.

| Networking PCIe adapter beyond 100GbE | | | | | | |
|--|-----|---|------------------------------------|-----------------------------------|-------------------------------------|-----------------------------------|
| Part number | Qty | Cooling | 4LFF (14W SAS/SATA) | 8+2 SFF (25W NVMe) | 8+2 SFF (10W SAS/SATA) | 8SFF (25W NVMe) |
| P45641-B21 ¹ P45642-B21 ² | 3 | High Performance Fan Kit, (P48908-B21) | Up to 2x270W CPU, 32x 128GB DIMMs | | | |
| | | | 30C | 30C with DAC; 27C with AOC | 30C | 30C |
| | 3 | Closed-loop Liquid Cooling Heat Sink Fan FIO Bundle Kit, (P48906-B21) | Up to 2x350W CPU, 32x 128GB DIMMs | | | |
| | | | No support, 22C; (30C with DAC) | No support <20C (30C with DAC) | Not support, <20C (30C with DAC) | No support, 22C (30C with DAC) |

Notes:

- ¹ HPE InfiniBand NDR 1-port OSFP PCIe5 x16 MCX75310AAS-NEAT Adapter
- ² HPE InfiniBand NDR200 1-port OSFP PCIe5 x16 MCX75310AAS-HEAT Adapter
- For 20EDSFF CTO Server thermal condition, please refer to the “Recommended Ambient Temperature” section under each part number.



Core Options

| Networking OCP adapter beyond 100GbE | | | | | | |
|--|-----|---|------------------------------------|------------------------------------|-------------------------------------|------------------------------------|
| Part number | Qty | Cooling | 4LFF (14W SAS/SATA) | 8+2 SFF (25W NVMe) | 8+2 SFF (10W SAS/SATA) | 8SFF (25W NVMe) |
| P31323-B21 ¹ P31348-B21 ² | 2 | High Performance Fan Kit, (P48908-B21) | Up to 2x270W CPU, 32x 128GB DIMMs | | | |
| | | | 30C with DAC; 25C with AOC | No support, <20C (30C with DAC) | No support, <20C (30C with DAC) | 30C with DAC; 25C with AOC |
| | 2 | Closed-loop Liquid Cooling Heat Sink Fan FIO Bundle Kit, (P48906-B21) | Up to 2x350W CPU, 32x 128GB DIMMs | | | |
| | | | No support, <20C (30C with DAC) | No support, <20C (25C with DAC) | No support, <20C; (30C with DAC) | No support, <20C (30C with DAC) |

Notes:

- ¹ HPE InfiniBand HDR/Ethernet 200Gb 1-port QSFP56 PCIe4 x16 OCP3 MCX653435A-HDAI Adapter
- ² HPE InfiniBand HDR/Ethernet 200Gb 2-port QSFP56 PCIe4 x16 OCP3 MCX653436A-HDAI Adapter
- For 20EDSFF CTO Server thermal condition, please refer to the “Recommended Ambient Temperature” section under each part number.

| Networking OCP adapter 10/25GbE | | | | | | |
|---------------------------------|-----|---|-----------------------------------|-------------------------------|-------------------------------|-------------------------------|
| Part number | Qty | Cooling | 4LFF (14W SAS/SATA) | 8+2 SFF (25W NVMe) | 8+2 SFF (10W SAS/SATA) | 8SFF (25W NVMe) |
| P10115-B21 ¹ | 2 | High Performance Fan Kit, (P48908-B21) | Up to 2x270W CPU, 32x 128GB DIMMs | | | |
| | | | 30C | 30C | 30C | 30C |
| | 2 | Closed-loop Liquid Cooling Heat Sink Fan FIO Bundle Kit, (P48906-B21) | Up to 350W CPU, 32x 128GB DIMMs | | | |
| | | | 30C with DAC; 25C with AOC | 30C with DAC; 25C with AOC | 30C with DAC; 25C with AOC | 30C with DAC; 25C with AOC |

Notes:

- ¹ Broadcom BCM57414 Ethernet 10/25Gb 2-port SFP28 OCP3 Adapter for HPE
- For 20EDSFF CTO Server thermal condition, please refer to the “Recommended Ambient Temperature” section under each part number.

Power and Cooling

Power Supplies

European Union Erp Lot 9 Regulation

Beginning on January 1st, 2024, units sold into the European Union (EU), European Economic Area (EEA), the United Kingdom, or Switzerland must include more efficient AC power supplies: 94% for multi-output and 96% for single-output. HPE Flexible Slot power supplies are single-output, and part numbers 865438-B21, P03178-B21, and P44712-B21 are 96% efficient, thus meeting requirements.

HPE is on target to fulfil compliant systems ahead of time and will begin enforcing these requirements in advance to satisfy requests with the current power supplies by the set deadline.

Please select one or two power supplies from below in the system configuration.

Notes:

- Mixing 2 different power supplies is NOT supported.
- Please refer to “Factory Configuration Setting” section regarding “HPE CE Mark Removal FIO Enablement Kit (P35876-B21)” for non- EU Erp Lot 9 configuration.



Core Options

- In order to select the right size power supply for your ProLiant Server it is highly recommended to use "HPE Power Advisor" located at <https://poweradvisorex.it.hpe.com/?Page=Index>

HPE 500W Flex Slot Platinum Hot Plug Low Halogen Power Supply Kit

865408-B21

Notes:

- Supported with 4LFF CTO Model only.
- If 500W Power supply is selected, then Processor Wattage that is equal to or less than 125W must be selected.
- If 500W Power supply is selected, then 2 Processors cannot be selected.
- If 500W Power supply is selected, then "HPE DL3X0 Gen11 1U 2P Std Fan Kit" cannot be selected.
- If 500W Power supply is selected, then Maximum of 2 Networking/ InfiniBand can be selected.
- If 500W Power supply is selected, then x16 Networking/ InfiniBand cannot be selected.
- If 500W Power supply is selected, then Maximum 8 Memory can be selected.

HPE 800W Flex Slot Platinum Hot Plug Low Halogen Power Supply Kit

P38995-B21

HPE 800W Flex Slot Titanium Hot Plug Low Halogen Power Supply Kit

865438-B21

Notes:

- Power efficiency at 96% single output.
- Only supports high line voltage (200 VAC to 240 VAC).
- Before April 17, 2023, OCA Error /CLIC Unbuildable when the non-certified PSU is selected along with the model if selected Country in OCA is India: Trigger OCA Error /CLIC Unbuildable with below message while selecting this Power Supply as Factory Integrated Option(OD1/FIO)for the Model-X and if the ship to Country is India: "This Power Supply is not compliant with India BIS Certification for selected Model -X and SHOULD NOT BE SELECTED. This is a regulatory compliance and hence the user cannot select this combination(Power Supply+ Model-X) if order is shipping to India. Please Select alternate PSU." Or contact Product Management Team for approval after March 01, 2023.

HPE 1000W Flex Slot Titanium Hot Plug Power Supply Kit

P03178-B21

Notes: Power efficiency at 96% single output.

HPE 1600W Flex Slot -48VDC Hot Plug Power Supply Kit

P17023-B21

Notes: If 1600W DC Power supply is selected, then either "HPE 1600W DC PSU Power Cable Kit" or "HPE 1600W DC PSU Power Lug Option Kit" must be selected and quantity must match. vice versa

HPE 1600W Flex Slot Platinum Hot Plug Low Halogen Power Supply Kit

P38997-B21

Notes: Only supports high line voltage (200 VAC to 240 VAC).

HPE 1800W-2200W Flex Slot Titanium Hot Plug Power Supply Kit

P44712-B21

Notes:

- Power efficiency at 96% single output.
- Supports high line voltage (200VAC to 240VAC)
- The highest rating would variate from 1800-2200W depending on input voltage of datacenter

Notes:

According to The Bureau of Indian Standards Act, 2016, BIS certification is required by every manufacturer (Indian or foreign) of those who are manufacturing products under Compulsory Certification.

DL360 Gen11 CTO Servers manufactured in Singapore with below Power Supplies are certified with BIS: 865408-B21, P38995-B21, P03178-B21, P17023-B21, P38997-B21 and P44712-B21.

For information on BIS Certification requirement visit [BIS Certification - BIS Certificate for Import \(indianchemicalregulation.com\)](https://indianchemicalregulation.com)



Core Options

Accessory

HPE 1600W -48VDC Power Cable Lug Kit

P36877-B21

Notes: Both "HPE 1600W DC PSU Power Lug Option Kit" and "HPE 1600W DC PSU Power Cable Kit" cannot be selected together.

Power Cords

For more Power Cords options, please refer to "HPE One Config Advance".

If any of these "Optional" Power Cords are ordered, then quantity must be equal to total number of Power Supplies on the order.

- All Regions (Except Japan) - OCA/CLIC UNB
- For Japan - OCA/CLIC Warning"

HPE 1600W -48VDC 600V 3.5m Power Cable Kit

P22173-B21

Notes: Both "HPE 1600W DC PSU Power Lug Option Kit" and "HPE 1600W DC PSU Power Cable Kit" cannot be selected together.

HPE Flexible Slot (Flex Slot) Power Supplies share a common electrical and physical design that allows for hot plug, tool-less installation into HPE ProLiant Gen11 Performance Servers. Flex Slot power supplies are certified for high-efficiency operation and offer multiple power output options, allowing users to "right-size" a power supply for specific server configurations. This flexibility helps to reduce power waste, lower overall energy costs, and avoid "trapped" power capacity in the data center.

Prior to making a power supply selection it is highly recommended that the HPE Power Advisor is run to determine the right size power supply for your server configuration. The HPE Power Advisor is located at: [HPE Power Advisor](#)

HPE ProLiant servers ship with an IEC-IEC power cord used for rack mounting with Power Distribution Units (PDUs). Visit [HPE power cords and cables](#) for a full list of optional power cords. The standard 6-foot IEC C-13/C-14 jumper cord (A0K02A) is included with each standard AC power supply option kit.

For information on power specifications and technical content visit [HPE Flexible Slot power supplies](#)

Power Cooling Options

Heatsinks

HPE ProLiant DL3XX/560 Gen11 High Performance Heat Sink Kit

P48905-B21

HPE ProLiant DL3X0 Gen11 1U Standard Heat Sink Kit

P48904-B21

HPE ProLiant DL360 Gen11 Cold Plate Module FIO Kit from External NS204i-u

P62026-B21

HPE ProLiant DL3XX Gen11 Cold Plate Module FIO Kit from PCIe

P62029-B21

Notes: For more detail information, refer to Heastink section above

DLC Enablement

HPE ProLiant Direct Liquid Cooling 450mm Female-Male Connection Quick Disconnect Tube Set FIO Kit

P62046-B21

Notes:

- Min/ Max is not applicable. However Maximum One quantity of Tube set can be selected per server.
- If DLC Module is selected, then "HPE DLC Hose 450mm FtM FIO KIT" must be selected, as extension tube from rear wall of the server.

HPE ProLiant DL360 Gen11 Closed-loop Liquid Cooling Heat Sink Fan FIO Bundle Kit

P48906-B21

Notes:

- The HPE DL360 Gen11 Closed-loop Liquid Cooling Heat Sink Fan FIO Bundle kit contains (2) cold plates (1 per CPU) each with a pump, Tubes, (7) 4028 fans and a radiator. The LC Heat Sink option is designed to cool down the processor effectively using cooled inlet air.
- Maximum quantity for Closed-loop Liquid Cooling (CL LC) Heat Sink Fan FIO Bundle Kit is one kit per system.
- The DL360 CL LC can be configured in a single socket DL360 Gen11 server as Factory Installation only. CPU Filed upgrade is not allowed. Please contact HPE Service if any request of upgrading CPU at field.



Core Options

Fan Kits

HPE ProLiant DL3X0 Gen11 1U High Performance Fan Kit

P48908-B21

Notes:

- Dual rotor 4056 performance fans (Qty 7)
- Two processors with a TDP equal or greater than 186W and below 270Watt
- For processors below 185Watt TDP, customers are able to configure with High Performane Heatsinks & Performnace Fan Kit in HPE One-Configuration-Advanced. With firstly deselect the Standard Heatsink and Standard Fan, then reselect High Performance Heatsink and Performance Fan Kit.

HPE ProLiant DL3X0 Gen11 1U Standard Fan Kit

P48907-B21

Notes: Dual rotor 4056 standard fans (Qty 5)

HPE ProLiant DL3X0 Gen11 1U 2P Standard Fan Kit

P54697-B21

Notes: Dual rotor 4056 standard fans (Qty 2)

| Cooling Option selection in 8+2 SFF and 4LFF CTO Servers | | | | | | |
|--|---|--|--|--|--|---|
| CPU TDP (Watts) | 125W – 185W | | 186W – 270W ¹ | 271W – 350W ¹ | 350W (LC CPU) ⁴ | |
| CPU Q'ty | 1 | 2 | 2 | 2 | 2 | 2 |
| Heatsink | Standard (P48904-B21) | | High Performance ² (P48905-B21) | Closed-loop LC Heatsink and Fan FIO Bundle Kit ³ (P48906-B21) | | Direct Liquid Cooling (DLC) Heatsink and High-Performance Fan (P48908-B21) FIO solution |
| Fans | Standard Fan (P48907-B21) | Standard Fan (P48907-B21) & 2 ^P Standard Fan (P54697-B21) | High Performance ² (P48908-B21) | | | |
| Max DIMM | 32x128GB | | | 32x128 GB or 16x256GB ⁵ | | 16x256GB ⁵ |
| Networking | 10/25GbE PCIe adapter or OCP ⁶ | | | | | |
| Max Drive | 4LFF SAS or 8+2 NVMe | | | | 8SFF CTO Svr with 0 backplane & 0 drive, 25C No support for 4LFF CTO Server | 4LFF SAS or 10NVMe |
| Internal OS Boot | Available for internal NS204i-u | | | | | |
| External OS Boot ⁶ | Available | | | 30C (4LFF SAS); 30C (8NVMe); No support, 23C (10 NVMe) | 25C | Available |
| Alternatives | Direct Liquid Cooling (DLC) Heatsink and High-Performance Fan FIO solution, for all processors in 2P Configuration. Support up to 32x256GB DIMM, Internal / external NS204i-u, 10x NVMe | | | | | |
| DIMM blanks | Required, embedded, and shipped as default in all CTO Servers | | | | | |

Notes:

- ¹Both minimum and maximum limits included (e.g greater or equal to, and up to including).
- ²Option driven (incl. CPU TDP, DIMM and NIC bandwidth). Options listed below would require Performance Fan kit or Direct Liquid Cooling bundle kit to be implemented.
 - o CPU TDP (as above matrix)
 - o 256GB DIMM
 - o NIC and InfiniBand adapters and OCP cards that go beyond 100GbE/200GbE
 - o NVMe storage (even Qty 1)
 - o With GPU
 - o With hot-plug (external) OS Boot Device NS204i-u

Core Options

- ³Recommended with
A bundle kit supports at two processors configuration only. The kit incl. two processors heatsink, coldplates, closed-loop liquid cooling tubes, radiator and dedicated 4028 fan sets (7ea) as Factory Installation only kits.
- Below configuration are required to apply.
- ⁴Intel Open-loop Liquid Cooling CPU (6458Q/ 8470Q) can be operated at or below 23C with Closed-loop Liquid cooling solution, yet only 8xSAS storage can be supported. Or operated at 25C with Closed-loop Liquid cooling solution with NS204i-u, without backplane and storage drives in 8SFF CTO Server.
- DLC solution is required if Intel CPU (6458Q/ 8470Q) are operated at or below 25C without drive support constraint.
- ⁵256GB DIMM supports only 1DPC with up to 8 DIMMs per socket due to thermal condition from DIMMs. And 2DPC for 16 GB, 32GB, 64GB and 128GB DIMM with up to 16 DIMMs per socket
- ⁶For NIC and InfiniBand PCIe adapters and OCP cards that go beyond 100GbE/200GbE, there will be additional configuration limit or ambient temperature requirements. Please refer to the Networking section.

| Cooling Option selection in 20EDSFF CTO Servers | | | | | | |
|---|--|--|--|---|---|---|
| CPU TDP (Watts) | 125W – 185W | 186W – 270W | 271W – 350W | 271W – 350W | 350W (LC CPU) ¹ | |
| CPU Qty (2P only) | 2 | 2 | 2 | 2 | 2 | 2 |
| Heatsink | Standard (P48904-B21) | High Performance (P48905-B21) | Closed-loop LC Heatsink and Fan FIO Bundle Kit ³ (P48906-B21) | Direct Liquid Cooling Heatsink FIO Kit | No support, if Closed-loop LC Heatsink and Fan FIO Bundle Kit (P48906-B21) ³ | Direct Liquid Cooling Heatsink FIO Kit |
| Fans | High Performance ² (P48908-B21) | High Performance (P48908-B21) | **Incl. dual rotor 4028 fans (Qty 7) | High Performance (P48908-B21) | | High Performance (P48908-B21) |
| Max DIMM | 32x128GB or 16x256GB ⁴ /1DPC | | 32x 128 GB | 32x 256GB | | 32x256GB |
| Networking | Up to 10/25GbE PCIe Adapter or OCP ⁵ | | | | | Up to 10/25 GbE |
| External NS204i-u | Available | | 25C (10 EDSFF+10 blanks); 28C (4 EDSFF + 16 blanks) Not support, 20C (20 EDSFF); | Available | | No support, 20C (20 EDSFF); |
| Maximum Qty of E3.s 1T drive | 20 | 20 | 10EDSFF +10blanks | 20 | No support, 0 drive | 20 |
| Support ambient | 30C (no GPU); 25C (Nvidia A2 or L4) | 30C (no GPU); 25C (Nvidia A2 or L4) | 30C (up to 128GB DIMM, no GPU); No support, require 18C (if any Nvidia A2 or L4 GPU), | 30C (256GB DIMM); 30C (Nvidia A2 or L4); | No support, < 20C | 30C (256GB DIMM); 30C (Nvidia A2 or L4); |
| Limitation of EDSFF drive | Only P57807-B21 (HPE 15.36TB NVMe RI E3S EC1 PM1743 SSD) is limited at 25C | | | | | |
| Alternatives | Choice of Direct Liquid Cooling (DLC) Heatsink and Fan FIO solution for all processors in 2P Configuration | | | | | |
| DIMM Blanks | Required, embedded, and shipped as default in all CTO Servers | | | | | |

Notes:

- ¹Intel Open-loop Liquid Cooling CPU (6458Q/ 8470Q)

Core Options

- ²Incl. dual rotor 4056 fans (Qty 7)
- ³Incl. 4028 fans (Qty 7)
- ⁴256GB DIMM supports only 1DPC with up to 8 DIMMs per socket due to thermal condition
- ⁵For NIC and InfiniBand PCIe adapters and OCP cards that go beyond 100GbE/200GbE, there will be additional configuration limit or ambient temperature requirements. Please refer to the Networking section

Security Options

Security Hardware

HPE Bezel Lock Kit 875519-B21

Notes:

- Maximum 1 of each can be selected.
- If Bezel lock is selected, then "HPE DL3XX Gen11 1U Bezel Kit" or "HPE OEM Gen11 1U Bezel KIT" must be selected.

HPE ProLiant DL3XX Gen11 Intrusion Cable Kit P48922-B21

Notes:

- Maximum 1 of each can be selected.
- If "HPE Trusted Supply Chain FIO Config" is selected then "Gen11 Intrusion Cbl Kit" must be selected.
- If HPE Trusted Supply Chain FIO Config is selected, then Configurator should default "Gen11 Intrusion Cbl Kit".

HPE ProLiant Gen11 1U Common Bezel Kit P50450-B21

Notes:

- Maximum 1 of each can be selected.
- If Bezel lock is selected, then "HPE DL3XX Gen11 1U Bezel Kit" or "HPE OEM Gen11 1U Bezel KIT" must be selected.
- Both "HPE DL3XX Gen11 1U Bezel Kit" and "HPE OEM Gen11 1U Bezel KIT" cannot be selected together.

Software as a Service Management

HPE GreenLake for Compute Ops Management

Base SKU

HPE GreenLake for Compute Ops Management Enhanced 3-year Upfront ProLiant SaaS R7A11AAE

Upgrade SKUS

HPE GreenLake for Compute Ops Management Enhanced 1-year Upfront ProLiant SaaS R7A10AAE

HPE GreenLake for Compute Ops Management Enhanced 5-year Upfront ProLiant SaaS R7A12AAE

HPE OneView

HPE OneView including 3yr 24x7 Support Flexible Quantity E-LTU E5Y35AAE

HPE OneView w/o iLO including 3yr 24x7 Support Flexible Quantity E-LTU P8B26AAE

Notes: For customers purchasing HPE GreenLake for Compute Ops Management, without a hardware purchase or a BTO purchase, use this base SKU within ASQ order:

HPE GreenLake for Compute Ops Management Base SaaS R6Z73AAE

For more information, visit the HPE GreenLake for Compute Ops Management QuickSpecs:

<https://www.hpe.com/psnow/doc/a50004263enw>

Supported Servers – CTO only. No OEM. – Complete list can be found here: Latest Supported Server List:

<https://www.hpe.com/info/com-supported-servers>



Additional Options

Some options may not be integrated at the factory. To ensure only valid configurations are ordered, Hewlett Packard Enterprise recommends the use of a Hewlett Packard Enterprise approved configurator. Contact your local sales representative for additional information.

Choose Additional Options

Accessories

Management Hardware

Maximum 1 of each can be selected.

HPE ProLiant DL36X Gen11 Rear Serial Port Cable Kit P48921-B21

HPE ProLiant DL360 Gen11 SFF System Insight Display Power Module Kit P48927-B21

Notes: Supported with 8SFF CTO Model only.

HPE ProLiant DL3X0 Gen11 1U LFF Display Port/USB Kit P48928-B21

Notes: Supported with 4LFF CTO Model only.

Manufacturing Services

HPE Remove Standard Power Cords 469774-409

Notes: If "Remove Standard IEC-IEC Power Cords" is selected, then the following Warning message should be displayed: By selecting this option, you will not receive standard power cords with this server. Please verify that no power cords are needed for this server prior to proceeding with your order. If "Remove Standard Power Cords" is selected by mistake, then please make sure to de-select it.

Rack Options

HPE ProLiant DL3XX Gen11 Easy Install Rail 3 Kit P52341-B21

HPE Easy Install Rail 5 Kit P52343-B21

HPE ProLiant DL300 Gen10 Plus 1U Cable Management Arm for Rail Kit P26489-B21

Notes:

- HPE rail kits contain telescoping rails which allow for in-rack serviceability.
- Rail Kit does not include Cable Management Arm.
- Hewlett Packard Enterprise recommends that a minimum of two people is required for all Rack Server installations.
- Please refer to your installation instructions for proper tools and number of people to use for any installation.
- Maximum 1 of each can be selected.
- If CMA is selected, then Rail kit must be selected.
- ¹Supported with 8SFF CTO Model only.
- ²Supported with 4LFF CTO & 20EDSFF CTO Models.
- HPE rail kits are designed to work with HPE racks in compliance with industry standard EIA-310-E. In the event a customer elects to purchase a third-party rack for use with an HPE rail kit, any such use is at customer's own risk. HPE makes no express or implied warranties with respect to such third-party racks and specifically disclaims any implied warranties of merchantability and fitness for a particular purpose. Furthermore, HPE has no obligation and assumes no liability for the materials, design, specifications, installation, safety, and compatibility of any such third-party racks with any rail kits, including HPE rail kits

vSAN Tracking SKUs

HPE ProLiant vSAN Original Storage Architecture FIO Tracking P63223-B21

HPE ProLiant vSAN ReadyNode Express Storage Architecture FIO Tracking P63226-B21

Software RAID

Notes:

- Requires selection of NVMe Drives (SFF/ EDSFF) through Direct Attach in 8SFF or EDSFF CTO server
- If RAID is being selected in a configuration with VROC and internal controller, then Customer Defined RAID Setting (389692-B21) must be selected.
- RAID is allowed on EDSFF drives only if Premium VROC or Standard VROC or VROC RAID1 is selected as Primary controller



Additional Options

- If any of the Processors below is selected, then VROC S3Q19A cannot be selected: Xeon 4510T, 409Y, 4510 and 3508U

Intel Virtual RAID on CPU Premium FIO Software for HPE

R7J57A

Notes:

- Intel® VROC Premium
- The Intel® VROC Premium is available for RAID support 0, 1, 5, 10 in the field.
- If Intel® VROC Premium is the primary controller, then the following RAID levels are allowed: 0, 1, 5 (available from RAID FIO settings at HPE factory). Requires selection of NVMe Drives through Direct Attach

Intel Virtual RAID on CPU Premium E-RTU for HPE

R7J59AAE

Notes: Same as Intel Virtual RAID on CPU Premium FIO Software for HPE (R7J57A), but intended for field deployments.

Intel Virtual RAID on CPU Standard FIO Software for HPE

S0E37A

Notes:

- Intel® VROC Standard
- The Intel® VROC Standard is available for RAID support 0, 1, 5 in the field.
- If Intel® VROC Standard is the primary controller, then only following RAID levels are allowed: 0, 1 (available from RAID FIO settings at HPE factory). Requires selection of NVMe Drives through Direct Attach

Intel Virtual RAID on CPU Standard E-RTU for HPE

S0E38AAE

Notes: Same as Intel Virtual RAID on CPU Standard FIO Software for HPE (S0E37A), but intended for field deployments.

Intel Virtual RAID on CPU RAID 1 FIO Software for HPE

S3Q19A

Notes: If Intel VROC RAID1 is the primary controller, then the following RAID levels are allowed: 1

Intel Virtual RAID on CPU RAID 1 E-RTU for HPE

S3Q39AAE

Notes: Same as Intel Virtual RAID on CPU RAID 1 FIO Software for HPE (S3Q19A), but intended for field deployments.

GPGPU

Notes:

- Mixing of different Graphics Option is not allowed.
- Requires “Increased Cooling” to be selected in BIOS settings (default setting is “Optimal Cooling”).
- There is no Energy Star 4.0 certification with Graphic cards.
- If GPU is selected, standard heatsink & stanrd fan kits are not supported. Requires high performance fans.
- If GPU is selected for best performance across common workloads, HPE recommends system main memory at least twice the memory of all GPU.

NVIDIA A2 16GB PCIe Non-CEC Accelerator for HPE

R9H23C

Notes: PCIe 4.0

| GPGPU Configuration | | | | | | | | |
|---------------------------------|-----|---------------------------------------|-----------------------------------|--------------------|------------------------|-----------------|---------|------------------------------------|
| Part number | Qty | Cooling | 4LFF (14W SAS/SATA) | 8+2 SFF (25W NVMe) | 8+2 SFF (10W SAS/SATA) | 8SFF (25W NVMe) | 20EDSFF | |
| Nvidia A2 (R9H23C) ¹ | 2 | High Performance Fan Kit (P48908-B21) | Up to 2x270W CPU, 32x 128GB DIMMs | | | | | Up to 2x205W CPU, 32x 128GB DIMMs |
| | | | 30C | 30C | 30C | 30C | 25C | |
| | 2 | | Up to 2x350W CPU, 32x 128GB DIMMs | | | | | Up to 2x350W CPU, 32x 128GB DIMMs, |



Additional Options

| | | | | | | | |
|--|--|--|-----|-------------------------|-------------------------|------------------|-------------------------|
| | | Closed-loop Liquid Cooling Heat Sink Fan FIO Bundle Kit (P48906-B21) | 25C | No support ³ | No support ³ | 25C ⁴ | No support ⁵ |
|--|--|--|-----|-------------------------|-------------------------|------------------|-------------------------|

Notes:

- Can support the GPU apapter with Max. length up to 9.5" (full length adapters are not supported) at PCIe Slot 1 and Slot 3. There is mechinal interference from the GPU bracket when installing A2 at Slot2.
- Nvidia GPU A2 will be available in all 3 slots (incl. Slot 2) expected in Q4 2023 with new low-profile bracket in the A2 kit.
- ¹ Requires high performance fans
- ² Can be installed at Slot 1 and Slot 3 (if 2nd processor is selected).
- ³Max 2x350W CPU, 32x128GB DIMM, and max 10SFF, will need to operated at 20C. Will not be a festible configuration to support.
- ⁴ In 8SFF CTO Model, if the Graphics Option is selected with the Processor that is more than 270W, then Maximum of 8 NVMe/ SAS/ SATA drives can be selected.
- ⁵In EDSFF CTO Model, if the Graphics Option is selected with Processor Wattage is more than 270W, then DLC Module must be selected.

NVIDIA L4 24GB PCIe Accelerator for HPE

SOK89C

| GPGPU Configuration | | | | | | | | |
|----------------------------------|-----|--|-----------------------------------|-------------------------|-------------------------|------------------|------------------------------------|--|
| Part number | Qty | Cooling | 4LFF (14W SAS/SATA) | 8+2 SFF (25W NVMe) | 8+2 SFF (10W SAS/SATA) | 8SFF (25W NVMe) | 20EDSFF | |
| Nvidia L4 (SOK9C) ^{1,2} | 3 | High Performance Fan Kit (P48908-B21) | Up to 2x270W CPU, 32x 128GB DIMMs | | | | Up to 2x225W CPU, 32x 128GB DIMMs | |
| | | | 30C | 30C | 30C | 30C | 28C | |
| | 3 | Closed-loop Liquid Cooling Heat Sink Fan FIO Bundle Kit (P48906-B21) | Up to 2x350W CPU, 32x 128GB DIMMs | | | | Up to 2x350W CPU, 32x 128GB DIMMs, | |
| | | | 25C | No support ³ | No support ³ | 25C ⁴ | No support ⁵ | |

Notes:

- Can support the GPU apapter with Max. length up to 9.5" (full length adapters are not supported) at PCIe Slot 1, 2 and 3. Nvidia GPU L4 will be available in all 3 slots.
- ¹ Requires high performance fans
- ² Can be installed at Slot 1, Slot2 and Slot 3 (if 2nd processor is selected).
- ³Max 2x350W CPU, 32x128GB DIMM, and max 10SFF, will need to operated at 20C. Will not be a festible configuration to support.
- ⁴ In 8SFF CTO Model, if the Graphics Option is selected with the Processor that is more than 270W, then Maximum of 8 NVMe/ SAS/SATA drives can be selected.
- ⁵In EDSFF CTO Model, if the Graphics Option is selected with Processor Wattage is more than 270W, then DLC Module must be selected.



Additional Options

Embedded Management

HPE iLO Advanced

| | |
|--|------------|
| HPE iLO Advanced 1-server License with 1yr Support on iLO Licensed Features | 512485-B21 |
| HPE iLO Advanced Flexible Quantity License with 1yr Support on iLO Licensed Features | 512486-B21 |
| HPE iLO Advanced AKA Tracking License with 1yr Support on iLO Licensed Features | 512487-B21 |
| HPE iLO Advanced 1-server License with 3yr Support on iLO Licensed Features | BD505A |
| HPE iLO Advanced Flexible Quantity License with 3yr Support on iLO Licensed Features | BD506A |
| HPE iLO Advanced AKA Tracking License with 3yr Support on iLO Licensed Features | BD507A |
| HPE iLO Advanced Electronic License with 1yr Support on iLO Licensed Features | E6U59ABE |
| HPE iLO Advanced Electronic License with 3yr Support on iLO Licensed Features | E6U64ABE |

HPE Converged Infrastructure Management Software

HPE OneView Advanced (with HPE iLO Advanced)

| | |
|--|----------|
| HPE OneView including 3yr 24x7 Support Physical 1-server LTU | E5Y34A |
| HPE OneView including 3yr 24x7 Support Flexible Quantity E-LTU | E5Y35AAE |

HPE OneView Advanced (without HPE iLO Advanced)

| | |
|--|----------|
| HPE OneView w/o iLO including 3yr 24x7 Support 1-server LTU | P8B24A |
| HPE OneView w/o iLO including 3yr 24x7 Support Track 1-server LTU | P8B25A |
| HPE OneView w/o iLO including 3yr 24x7 Support Flexible Quantity E-LTU | P8B26AAE |

Notes:

- Licenses ship without media. The HPE OneView Media Kit can be ordered separately, or can be downloaded at: <https://www.hpe.com/us/en/integrated-systems/software.html>
- Electronic and Flexible-Quantity licenses can be used to purchase multiple licenses with a single activation key.
- Licenses ship without media. The HPE OneView Media Kit can be ordered separately, or can be downloaded at: <https://www.hpe.com/us/en/integrated-systems/software.html>

HPE Racks

- Please see the HPE Advanced Series Racks QuickSpecs for information on additional racks options and rack specifications. [HPE G2 Advanced Series Racks](#)
- Please see the HPE Enterprise Series Racks QuickSpecs for information on additional racks options and rack specifications. [HPE G2 Enterprise Series Racks](#)

HPE Power Distribution Units (PDUs)

- Please see the [HPE Basic Power Distribution Units \(PDU\) QuickSpecs](#) for information on these products and their specifications.
- Please see the [HPE Metered Power Distribution Units \(PDU\) QuickSpecs](#) for information on these products and their specifications. Please see the [HPE Intelligent Power Distribution Unit \(PDU\) QuickSpecs](#) for information on these products and their specifications.
- Please see the [HPE Metered and Switched Power Distribution Units \(PDU\) QuickSpecs](#) for information on these products and their specifications.



Additional Options

HPE Uninterruptible Power Systems (UPS)

- To learn more, please visit the [HPE Uninterruptible Power Systems \(UPS\)](#) web page.
- Please see the [HPE DirectFlow Three Phase Uninterruptible Power System QuickSpecs](#) for information on these products and their specifications.
- Please see the [HPE Line Interactive Single Phase UPS QuickSpecs](#) for information on these products and their specifications.

HPE Tape Backup

HPE StoreEver LTO-9 Ultrium 45000 External Tape Drive

BC042A

HPE Support Services

Installation & Start-up Services

Tech Care

HPE 3 Year Tech Care Essential DL360 Gen11 HW Service

H93B6E

HPE 3 Year Tech Care Essential wDMR DL360 Gen11 HW Service

H93B7E

HPE 5 Year Tech Care Essential DL360 Gen11 HW Service

H93E0E

HPE 5 Year Tech Care Essential wDMR DL360 Gen11 HW Service

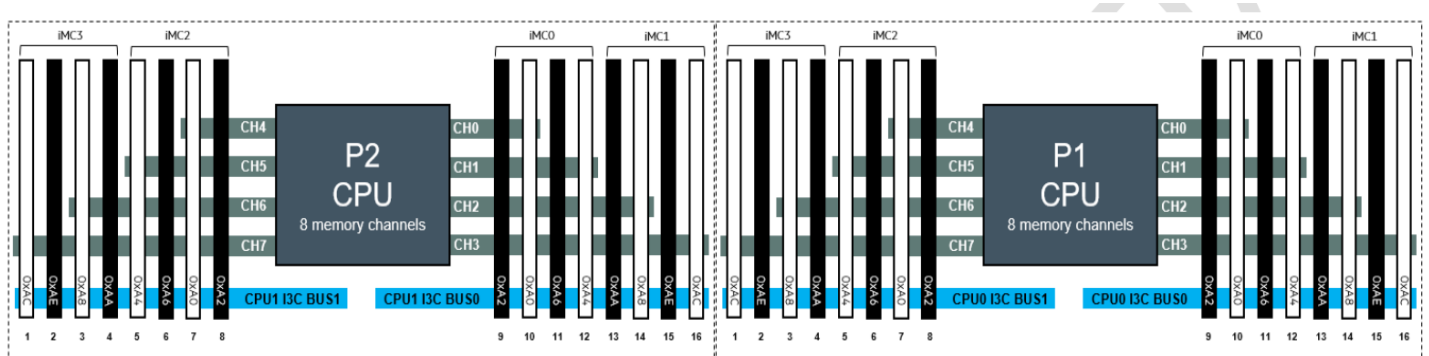
H93E1E

Notes: For a full listing of support services available for this server, please visit <http://www.hpe.com/services>.



Memory

Memory Population guidelines



Front End / HPE ProLiant DL360 Gen11

Notes:

- Listed below are general Memory Module Population Rules supported by the processor for reference.
- There is no longer a need to install DIMMs in pairs in non-RAS modes.
- The same information is displayed alternatively by rank, by speed, or by qty. That is, when viewing by rank, selecting a particular rank will then show the DIMM qty vs DIMM speed tradeoff/combinations. All DIMMs must be either all DDR5 DIMMs or DDR5 and Crow Pass DIMMs.
- There should be at least one DDR5 DIMM per socket.
- When one DIMM is used in a channel, it must be populated in DIMM slot farthest away from the CPU (DIMM slot 0) of a given channel.
- For 16 + 0 configuration with 1R + 2R mixed rank population, on each channel always populated the higher electrical load (2R) in DIMM0 followed by single rank DIMM in DIMM1.
- A maximum of 8 logical ranks (ranks seen by the host) per channel is allowed.
- For a DDR5 DIMM and Crow Pass DIMM in a channel, the DDR5 DIMM must be populated in the farthest DIMM slot (0), while CPS has to be in the nearest slot (1).
- All DIMMs in a Processor socket must have the same number of ranks (unless explicitly specified otherwise).
- x8 DIMMs and x4 DIMMs cannot be mixed in the same channel or same Processor socket.
- Mixing of non-3DS and 3DS RDIMMs is not allowed in the same channel, across different channels, and across different sockets.
- 9x4 RDIMMs cannot be mixed with another DIMM types (Crow Pass 10x4RDIMMs or Non 9x4 RDIMMs).
- All DDR5 DIMMs must operate at the same speed per Processor socket.
- Rank mixing is not allowed on a channel except for Standard RDIMM 1 Rank + 2 Rank combination, when all 16 DIMMs for a Processor socket is populated.
- Mixing vendor is allowed for RDIMMs, but it is not allowed for 3DS RDIMMS



Memory

| HPE ProLiant Gen11 16 slot per CPU DIMM population order | | | | | | | | | | | | | | | | |
|--|---|---|---|---|---|---|---|---|---|----|----|----|----|----|----|----|
| DIMM population order | | | | | | | | | | | | | | | | |
| DIMM slot | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 | 11 | 12 | 13 | 14 | 15 | 16 |
| 1 DIMM | | | | | | | | | | 10 | | | | | | |
| 2 DIMMs ² | | | 3 | | | | | | | 10 | | | | | | |
| 4 DIMMs ² | | | 3 | | | | 7 | | | 10 | | | | 14 | | |
| 6 DIMMs | | | 3 | | 5 | | 7 | | | 10 | | | | 14 | | 16 |
| 8 DIMMs ^{1,2} | 1 | | 3 | | 5 | | 7 | | | 10 | | 12 | | 14 | | 16 |
| 12 DIMMs | 1 | 2 | 3 | | 5 | 6 | 7 | | | 10 | 11 | 12 | | 14 | 15 | 16 |
| 16 DIMMs ^{1,2} | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 10 | 11 | 12 | 13 | 14 | 15 | 16 |

Notes :

- Omitted DIMM counts/socket not qualified by Intel.
- ¹ Supports SGX (Software Guard Extensions)
- ² Support Hemi (hemisphere mode).

General Memory Population Rules and Guidelines

- DIMMs should be installed in quantities of even numbers.
- Install DIMMs only if the corresponding processor is installed.
- If only one processor is installed in a two-processor system, only half of the DIMM slots are available.
- To maximize performance, it is recommended to balance the total memory capacity between all installed processors.
- When two processors are installed, balance the DIMMs across the two processors.
- White DIMM slots denote the first slot to be populated in a channel.
- Mixing of DIMM types (UDIMM, RDIMM, and LRDIMM) is not supported.
- The maximum memory speed is a function of the memory type, memory configuration, and processor model.
- The maximum memory capacity is a function of the number of DIMM slots on the platform, the largest DIMM capacity qualified on the platform, and the number and model of installed processors qualified on the platform.
- For details on the HPE Server Memory Options Population Rules, visit:

[Server memory populations rules for HPE Gen11 servers with 4th Gen Intel Xeon Scalable processors](#)

For additional information, please visit the [HPE Memory QuickSpecs and Technical White Papers](#) or [HPE DDR5 Smart Memory QuickSpecs](#).

| HPE SKU P/N | P43322-B21 | P43328-B21 | P43331-B21 |
|-------------------|---|---|---|
| SKU Description | HPE 16GB (1x16GB) Single Rank x8 DDR5-4800 CAS-40-39-39 EC8 Registered Smart Memory Kit | HPE 32GB (1x32GB) Dual Rank x8 DDR5-4800 CAS-40-39-39 EC8 Registered Smart Memory Kit | HPE 64GB (1x64GB) Dual Rank x4 DDR5-4800 CAS-40-39-39 EC8 Registered Smart Memory Kit |
| DIMM Capacity | 16GB | 32GB | 64GB |
| DIMM Rank | Single Rank (1R) | Dual Rank (2R) | Dual Rank (2R) |
| Voltage | 1.1 V | 1.1 V | 1.1 V |
| DRAM Depth [bit] | 2G | 2G | 4G |
| DRAM Width [bit] | x8 | x8 | x4 |
| DRAM Density | 16Gb | 16Gb | 16Gb |
| CAS Latency | 40-39-39 | 40-39-39 | 40-39-39 |
| DIMM Native Speed | 4800 MT/s | 4800 MT/s | 4800 MT/s |

Memory

| HPE SKU P/N | P43334-B21 | P43337-B21 |
|--------------------------|---|--|
| SKU Description | HPE 128GB (1x128GB) Quad Rank x4 DDR5-4800 CAS-46-39-39 EC8 Registered 3DS Smart Memory Kit | HPE 256GB (1x256GB) Octal Rank x4 DDR5-4800 CAS-46-39-39 EC8 Registered 3DS Smart Memory Kit |
| DIMM Capacity | 128GB | 256GB |
| DIMM Rank | Quad Rank (4R) | Octal Rank (8R) |
| Voltage | 1.1 V | 1.1 V |
| DRAM Depth [bit] | 4G | 4G |
| DRAM Width [bit] | x4 | x4 |
| DRAM Density | 16Gb | 16Gb |
| CAS Latency | 40-39-39 | 40-39-39 |
| DIMM Native Speed | 4800 MT/s | 4800 MT/s |

Notes: The maximum memory speed is a function of the memory type, memory configuration, and processor model.

For details on the HPE Server Memory speed, visit: <https://www.hpe.com/docs/memory-speed-table>

DDR5 memory options part number decoder

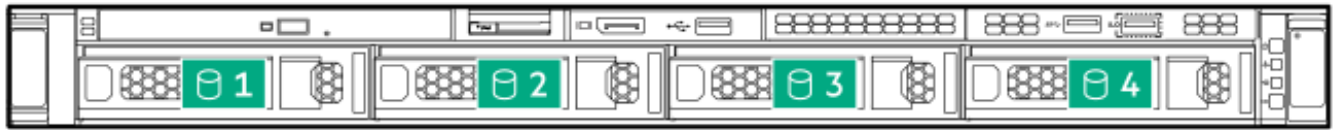
Notes:

- Capacity references are rounded to the common gigabyte (GB) values.
 - o 8GB = 8,192 MB
 - o 16GB = 16,384 MB
 - o 32GB = 32,768 MB
 - o 64GB = 65,536 MB
 - o 128GB = 131,072 MB
 - o 256GB = 262,144 MB
 - o 512GB = 524,288 MB

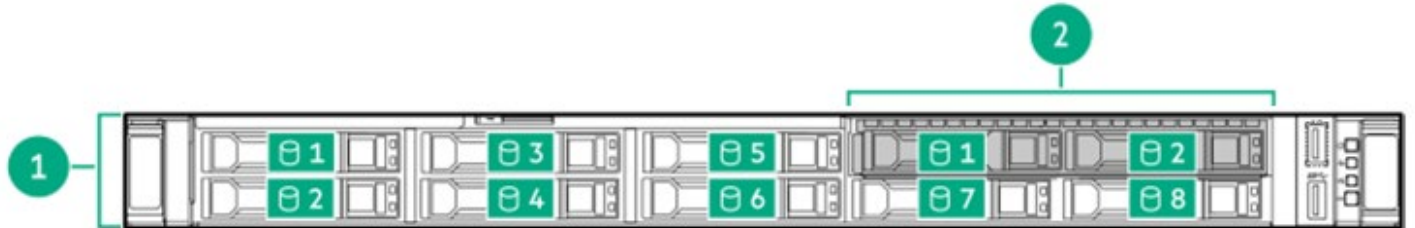
For more information on memory, please see the Memory QuickSpecs: [HPE DDR5 Smart Memory](#)



Storage



4 LFF device bay numbering



8 SFF + 2 SFF (optional) device bay numbering



8 SFF+ ODD device bay (optional through Media Bay)

| Box | Description |
|-----|--------------|
| 1 | Bays 1-8 |
| 2 | Bays 1 and 2 |



20 EDSFF device bay numbering



Technical Specifications

System Unit

Dimensions (Height x Width x Depth)

SFF Drives

- 4.29 x 43.46 x 75.31 cm
- 1.69 x 17.11 x 29.65 in

LFF Drives

- 4.29 x 43.46 x 77.31 cm
- 1.69 x 17.11 x 30.43 in

EDSFF Drives

- 4.29 x 43.46 x 77.31 cm
- 1.69 x 17.11 x 30.43 in

Weight (approximate)

- **14.56 kg (32.1 lb)**
 - **SFF minimum:** One drive, one processor, one power supply, two heatsinks, one Smart Array controller, and five fans.
- **20.44 kg (45.07 lb)**
 - **SFF maximum:** Ten drives, two processors, two power supplies, two heatsinks, one Smart Array controller and seven fans.
- **14.95 kg (32.96 lb)**
 - **LFF minimum:** One drive, one processor, one power supply, two heatsinks, one Smart Array controller and five fans.
- **21.58 kg (47.58 lb)**
 - **LFF maximum:** Four drives, two processors, two power supplies, two heatsinks, one Smart Array controller and seven fans.
- **14.75kg (32.51lb)**
 - **EDSFF minimum:** One drive, two processors, one power supply, two heatsinks, one Smart Array controller, and seven fans.
- **21.19kg (46.71lb)**
 - **EDSFF maximum:** Twenty drives, two processors, two power supplies, two heatsinks, one Smart Array controller and seven fans.

Input Requirements (per power supply)

Rated Line Voltage

- For 1800-2200W (Titanium): 200 to 240 VAC
- For 1600W (Platinum): 200 to 240 VAC
- For 1000W (Titanium): 100 to 240 VAC
- For 800W (Platinum): 100 to 240 VAC
- For 800W (Titanium): 100 to 240 VAC
- For 500W (Platinum): 100 to 240 VAC
- For 1600W (-48 VDC): -40 to -72 Vdc

British Thermal Unit (BTU) Rating

Maximum

- For 1800-2400W (Titanium) Power Supply: 6497BTU/hr (at 200 VAC), 7230 BTU/hr (at 220 VAC), 7962 BTU/hr (at 240 VAC)
- For 1600W (Platinum) Power Supply: 5918 BTU/hr (at 200 VAC), 5888 BTU/hr (at 220 VAC), 5884 BTU/hr (at 240 VAC)



Technical Specifications

- For 1000W (Titanium) Power Supply: 3741 BTU/hr (at 100 VAC), 3596 BTU/hr (at 200 VAC), 3582 BTU/hr (at 240 VAC)
- For 800W (Platinum) Power Supply: 3067 BTU/hr (at 100 VAC), 2958 BTU/hr (at 200 VAC), 2949 BTU/hr (at 240 VAC)
- For 1600W (48VDC) Power Supply: 6026 BTU/hr (at -40 VDC), 6000 BTU/hr (at -48 VDC), 5989 BTU/hr (at -72 VDC)
- For 500W (Platinum) Power Supply: 1999 BTU/hr (at 100 VAC), 1912 BTU/hr (at 200 VAC), 1904 BTU/hr (at 240 VAC)

Power Supply Output (per power supply)

Rated Steady-State Power

- For 1800W-2200W (Titanium) Power Supply: 1799W (at 200 VAC), 2000W (at 220 VAC), 2200W (at 240 VAC), 2200W (at 240 VDC) input for China only
- For 1600W (Platinum) Power Supply: 1600W (at 240 VAC), 1600W (at 240 VDC) input for China only
- For 1000W (Titanium) Power Supply: 1000W (at 100 VAC), 1000W (at 240 VAC), 1000W (at 240 VDC) input for China only
- For 800W (Platinum) Power Supply: 800W (at 100 VAC), 800W (at 240 VAC), 800W (at 240 VDC) input for China only
- For 800W (Titanium) Power Supply: 800W (at 200 VAC), 800W (at 240 VAC), 800W (at 240 VDC) input for China only
- For 1600W (-48VDC) Power Supply: 1600W (at -40 Vdc), 1600W (at -72Vdc)
- For 500W (Platinum) Power Supply: 500W (at 100 VAC), 500W (at 240 VAC), 500W (at 240 VDC) input for China only

Maximum Peak Power

- For 1800W-2200W (Titanium) Power Supply: 2200W (at 240 VAC), 2200W (at 240 VDC) input for China only
- For 1600W (Platinum) Power Supply: 1600W (at 240 VAC), 1600W (at 240 VDC) input for China only
- For 1000W (Titanium) Power Supply: 1000W (at 100 VAC), 1000W (at 240 VAC), 1000W (at 240 VDC) input for China only
- For 800W (Platinum) Power Supply: 800W (at 100 VAC), 800W (at 240 VAC), 800W (at 240 VDC) input for China only
- For 800W (Titanium) Power Supply: 800W (at 200 VAC), 800W (at 240 VAC), 800W (at 240 VDC) input for China only
- For 1600W (-48VDC) Power Supply: 1600W (at -40 Vdc), 1600W (at -72Vdc)
- For 500W (Platinum) Power Supply: 500W (at 100 VAC), 500W (at 240 VAC), 500W (at 240 VDC) input for China only

Notes: For more information, pls visit [HPE Flexible Slot Power Supplies](#)

System Inlet Temperature

• Standard Operating Support (Level 2 support)

10° to 35°C (50° to 95°F) at sea level with an altitude derating of 1.0°C per every 305 m (1.8°F per every 1000 ft) above sea level to a maximum of 3050 m (10,000 ft), no direct sustained sunlight. Maximum rate of change is 20°C/hr (36°F/hr). The upper limit and rate of change may be limited by the type and number of options installed.

System performance during standard operating support may be reduced if operating with a fan fault or above 30°C (86°F) or above 27°C (81°F) at 900M.

10° to 35°C (50° to 95°F) at 900M with an altitude derating of 1.0°C per every 305 m (1.8°F per every 1000 ft) above sea level to a maximum of 3050 m (10,000 ft), no direct sustained sunlight. Maximum rate of change is 20°C/hr (36°F/hr). The upper limit and rate of change may be limited by the type and number of options installed.

System performance during standard operating support may be reduced if operating with a fan fault or above 27°C (81°F) at 900M and 30°C (86°F) at sea level.

With Standard Operating Support, there shall be no processor performance drop. The approved hardware configurations for this system are listed at the URL [Extended Ambient Temperature Guidelines for HPE Gen11 servers](#)

• Extended Ambient Operating Support (Level 3 & Level 4 support)

For approved hardware configurations, the supported system inlet range is extended to be: 5° to 10°C (41° to 50°F) and 35° to 40°C (95° to 104°F) at sea level with an altitude derating of 1.0°C per every 175 m (1.8°F per every 574 ft) above 900 m (2953 ft) to a maximum of 3050 m (10,000 ft).



Technical Specifications

For approved hardware configurations, the supported system inlet range is extended to be: 40° to 45°C (104° to 113°F) at sea level with an altitude derating of 1.0°C per every 125 m (1.8°F per every 410 ft) above 900 m (2953 ft) to a maximum of 3050 m (10,000 ft).

With Extended Ambient Operating Support, Processor performance drop would be expected. The approved hardware configurations for this system require the High Performance Fan Kit (P26477-B21) and are listed at the URL:

<http://www.hpe.com/servers/ashrae>

System performance may be reduced if operating in the extended ambient operating range or with a fan fault.

- **Non-operating**
-30° to 60°C (-22° to 140°F). Maximum rate of change is 20°C/hr (36°F/hr).

Relative Humidity (non-condensing)

- **Operating**
8% to 90% - Relative humidity (Rh), 28°C maximum wet bulb temperature, non-condensing.
- **Non-operating**
5 to 95% relative humidity (Rh), 38.7°C (101.7°F) maximum wet bulb temperature, non-condensing.
- **Operating**
-12°C DP and 8% Rh to 21°C DP 80% - Relative humidity (Rh), 21°C maximum wet bulb temperature, non-condensing.
- **Non-Operating**
-12°C DP and 8% Rh to 21°C DP 80% - Relative humidity (Rh), 21°C maximum wet bulb temperature, non-condensing.

Altitude

- **Operating**
3050 m (10,000 ft). This value may be limited by the type and number of options installed. Maximum allowable altitude change rate is 457 m/min (1500 ft/min).
- **Non-operating**
9144 m (30,000 ft). Maximum allowable altitude change rate is 457 m/min (1500 ft/min).

Emissions Classification (EMC)

To view the regulatory information for your product, view the Safety and Compliance Information for Server, Storage, Power, Networking, and Rack Products, available at the Hewlett Packard Enterprise Support Center:

https://support.hpe.com/hpesc/public/docDisplay?docLocale=en_US&docId=c03471072

HPE Smart Array

For latest information please refer to the QuickSpecs.

- [HPE Compute MR Gen11 Controllers Quick Spec](#)
- [HPE Compute SR Gen11 Controllers Quick Spec](#)



Technical Specifications

Acoustic Noise

Listed are the declared mean A-Weighted sound power levels (LWA,m), declared average bystander position A-Weighted sound pressure levels (LpAm), and the statistical adder for verification (Kv) is a quantity to be added to the declared mean A-weighted sound power level. LWA,m when the product is operating in a 23°C ambient environment. Noise emissions were measured in accordance with ISO 7779 (ECMA 74) and declared in accordance with ISO 9296 (ECMA 109). The listed sound levels apply to standard shipping configurations. Additional options may result in increased sound levels. Please have your HPE representative provide information from the HPE EMESC website for further technical details regarding the configurations listed below.

| Test case | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 |
|------------------|--------|--------|--------|--------|--------|--------|--------|--------|
| Idle | | | | | | | | |
| LWA,m | 5.1 B | 4.7 B | 4.7 B | 5.0 B | 4.7 B | 4.7 B | 4.7 B | 5.2 B |
| LpAm | 37 dBA | 35 dBA | 36 dBA | 37 dBA | 36 dBA | 36 dBA | 36 dBA | 38 dBA |
| Kv | 0.4 B | 0.4 B | 0.4 B | 0.4 B | 0.4 B | 0.4 B | 0.4 B | 0.4 B |
| Operating | | | | | | | | |
| LW,m | 5.3 B | 5.0 B | 5.2 B | 5.3 B | 5.1 B | 5.4 B | 5.5 B | 6.0 B |
| LpAm | 40 dBA | 37 dBA | 39 dBA | 41 dBA | 37 dBA | 41 dBA | 41 dBA | 49 dBA |
| Kv | 0.4 B | 0.4 B | 0.4 B | 0.4 B | 0.4 B | 0.4 B | 0.4 B | 0.4 B |

Notes:

- Acoustics levels presented here are generated by the test configuration only. Acoustics levels will vary depending on system configuration. Values are subject to change without notification and are for reference only.
- The declared mean A-weighted sound power level, LWA,m, is computed as the arithmetic average of the measured.
- A-weighted sound power levels for a randomly selected sample, rounded to the nearest 0,1 B.
- The declared mean A-weighted emission sound pressure level, LpA,m, is computed as the arithmetic average of the measured A-weighted emission sound pressure levels at the bystander positions for a randomly selected sample, rounded to the nearest 1 dB.
- The statistical adder for verification, Kv, is a quantity to be added to the declared mean A-weighted sound power level, LWA,m, such that there will be a 95 % probability of acceptance, when using the verification procedures of ISO 9296, if no more than 6,5 % of the batch of new equipment, has A-weighted sound power levels greater than (LWA,m + Kv).
- The quantity, LWA,c (formerly called LWAd), can be computed from the sum of LWA,m and Kv.
- All measurements made to conform to ISO 7779 / ECMA-74 and declared to conform to ISO 9296 / ECMA-109.
- B, dB, abbreviations for bels and decibels, respectively, where 1 B = 10 dB.
- The results in this declaration apply only to the model numbers listed above when operating and tested according to the indicated modes and standards. A system with additional configuration components or increased operating functionality may increase the noise emission values.
- System under abnormal conditions may increase the noise level, persons in the vicinity of the product [cabinet] for extended periods of time should consider wearing hearing protection or using other means to reduce noise exposure.

Environment-friendly Products and Approach - End-of-life Management and Recycling

Hewlett Packard Enterprise offers **end-of-life product return, trade-in, and recycling programs**, in many geographic areas, for our products. Products returned to Hewlett Packard Enterprise will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the **Hewlett Packard Enterprise web site**. These instructions may be used by recyclers and other WEEE treatment facilities as well as Hewlett Packard Enterprise OEM customers who integrate and re-sell Hewlett Packard Enterprise equipment.



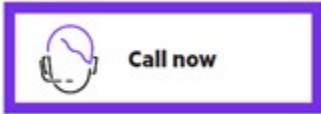
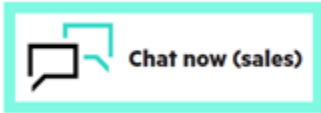
Summary of Changes

| Date | Version History | Action | Description of Change |
|-------------|-----------------|---------|--|
| 01-Apr-2024 | Version 16 | Changed | Overview, Pre-configured Models, Core Option and Additional Options sections were updated. |
| 18-Mar-2024 | Version 15 | Changed | Pre-configured Models section was updated. |
| 04-Mar-2024 | Version 14 | Changed | Optional Features, Core option and Additional Options sections were updated. |
| 05-Feb-2024 | Version 13 | Changed | Core Option section was updated. |
| 14-Dec-2023 | Version 12 | Changed | Overview, Standard Features,, Optional Features, Core Options and Additional Options were updated. |
| 06-Nov-2023 | Version 11 | Changed | Optional Features, Core Options and Additional Options sections were updated. |
| 05-Sep-2023 | Version 10 | Changed | Overview, Standard Features, Optional Features, Core Options, Aditonal Options and Technical Specification sections were updated. |
| 07-Aug-2023 | Version 9 | Changed | Overview, Standard Features and Core Options sections were updated. |
| 24-Jul-2023 | Version 8 | Changed | Overview, configuration Information and Core Options sections were updated. |
| 05-Jun-2023 | Version 7 | Changed | Overview, Pre-configured Models, Additional Options, Storage and Technical Specification sections were updated. |
| 01-May-2023 | Version 6 | Changed | Overview, Standard Features and Core Options sections were updated. |
| 17-Apr-2023 | Version 5 | Changed | Overview, Standard features, Pre-configured Models, Core Options |
| 03-Apr-2023 | Version 4 | Changed | Overview, Standard features, Pre-configured Models, Optional Features, Core Options, Storage, Technical Specifications |
| 06-Mar-2023 | Version 3 | Changed | Standard features, Configuration Information and Core Options were updated. |
| 06-Feb-2023 | Version 2 | Changed | Overview, Standard Features, Optional Features, Service Supports, Configuration Information, Core Options, Additional Options and Technical Specifications were updated. |
| 10-Jan-2023 | Version 1 | New | New QuickSpecs. |



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